UNITED STATES INTERNATIONAL TRADE COMMISSION
WASHINGTON, D.C. 20436

Before The Honorable Theodore R. Essex
Administrative Law Judge

In the Matter of CERTAIN SEMICONDUCTOR CHIPS WITH MINIMIZED CHIP PACKAGE SIZE AND PRODUCTS CONTAINING SAME	Investigation No. 337-TA-605

COMPLAINANT AND JOINT EXHIBITS – ALL EXHIBITS

Dated: August 4, 2008

Respectfully submitted,

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COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS

August 4, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	1					Withdrawn
CDX	2					Withdrawn
CDX	3					Withdrawn
CDX	4					Withdrawn
CDX	5					Withdrawn
CDX	6					Withdrawn
CDX	7					Withdrawn
CDX	8					Withdrawn
CDX	9					Withdrawn
CDX	10					Withdrawn
CDX	11					Withdrawn
CDX	12					Withdrawn
CDX	13					Withdrawn
CDX	14					Withdrawn
CDX	15					Withdrawn
CDX	16					Withdrawn
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CDX	28					Withdrawn
CDX	29					Withdrawn
CDX	30					Withdrawn
CDX	31					Withdrawn
CDX	32					Withdrawn
CDX	33					Withdrawn
CDX	34					Withdrawn
CDX	35					Withdrawn
CDX	36					Withdrawn
CDX	37					Withdrawn
CDX	38					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	39					Withdrawn
CDX	40					Withdrawn
CDX	41					Withdrawn
CDX	42					Withdrawn
CDX	43					Withdrawn
CDX	44					Withdrawn
CDX	45					Withdrawn
CDX	46					Withdrawn
CDX	47					Withdrawn
CDX	48					Withdrawn
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CDX	67					Withdrawn
CDX	68					Withdrawn
CDX	69					Withdrawn
CDX	70					Withdrawn
CDX	71					Withdrawn
CDX	72					Withdrawn
CDX	73					Withdrawn
CDX	74					Withdrawn
CDX	75	C	Dr. Qu Report Figure IV.1 – Example of Chip Package	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	76	C	Dr. Qu Report Figure III.5 – Solder Joints In a Package Assembly Are Subjected to Both Normal and Shear Strains Due To Differential Thermal Expansion And Warpage Caused By Differential Thermal Expansion	Qu	INFRNG/NON-INFRNG	Admitted
CDX	77	C	Dr. Qu Report Figure IV.2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	78	C	Qu Deposition Exhibit #269, Updated Figures and Tables from January 11, 2008 Expert Report	Qu	INFRNG/NON-INFRNG	Admitted
CDX	79	C	Dr. Qu Report Figure IXB.1 – An Example of Finite Element Mesh	Qu	INFRNG/NON-INFRNG	Admitted
CDX	80	C	Expert Report of Dr. Qu, Exhibit 4 - Values of Constants Used in Finite Element Analysis	Qu	INFRNG/NON-INFRNG	Admitted
CDX	81	C	Dr. Qu Report Figure XII.61 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	83	C	Expert Report of Dr. Qu, Exhibit 3 - Individual Results for Five Samples	Qu	INFRNG/NON-INFRNG	Admitted
CDX	84	C	Dr. Qu Report Figure XA.5 – Points of interest on the moiré cut for ST-TFBGA-84 (a) is an overall view of the package cross section, (b) is a close-up of the cross-section, and (c) indicates where the package was cut	Qu	INFRNG/NON-INFRNG	Admitted
CDX	084					Withdrawn
CDX	85	C	Dr. Qu Report Figure IXA.3 – Schematic View of Diffraction Grating Replication Process	Qu	INFRNG/NON-INFRNG	Admitted
CDX	86	C	Dr. Qu Report Figure IXA.4 – Sample Module in Grating Replication Fixture	Qu	INFRNG/NON-INFRNG	Admitted
CDX	87	C	Dr. Qu Report Figure IXA.9 – Time History of the Temperature Profile Applied at the Aluminum Base Plate	Qu	INFRNG/NON-INFRNG	Admitted
CDX	88	C	Dr. Qu Report Figure IXA.7 – Cross-Section of the Specimen and the Peltier Device Setup on the Optical Table	Qu	INFRNG/NON-INFRNG	Admitted
CDX	89					Withdrawn
CDX	90	C	Dr. Qu Report Figure XB.7 – Geometric Dimensions and Material Properties for STM-TFBGA-84	Qu	INFRNG/NON-INFRNG	Admitted
CDX	91					Withdrawn
CDX	92	C	Dr. Qu Report Figure XII.48 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	93					Withdrawn
CDX	94	C	Dr. Qu Report Figure XII.50 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	95					Withdrawn
CDX	96	C	Dr. Qu Report Figure XII.52 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	97					Withdrawn
CDX	98	C	Dr. Qu Report Figure XII.54 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	99					Withdrawn
CDX	100	C	Dr. Qu Report Figure XII.56 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	101					Withdrawn
CDX	102	C	Dr. Qu Report Figure XII.58 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	103					Withdrawn
CDX	104	C	Dr. Qu Report Figure XII.60 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	105	C	Dr. Qu Report Figure XII.4 – Relative movement between points A and C in ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	106					Withdrawn
CDX	107					Withdrawn
CDX	108	C	Dr. Qu Report Figure XII.42 – Relative movement between points A and C in STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	109					Withdrawn
CDX	110	C	Dr. Qu Report Figure XII.44 – Relative movement between points A and C in STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	111					Withdrawn
CDX	112	C	Dr. Qu Report Figure XII.46 – Relative movement between points A and C in STM-S-Moiré	Qu	INFRNG/NON-INFRNG	Admitted

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CDX	113	C	Dr. Qu Report Figure XII.47 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-M-S-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	114					Withdrawn
CDX	115	C	Dr. Qu Report Figure XII.49 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	116	C	Dr. Qu Report Figure XII.5 – Relative movement between points A and C in ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	117					Withdrawn
CDX	118	C	Dr. Qu Report Figure XII.51 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	119					Withdrawn
CDX	120	C	Dr. Qu Report Figure XII.53 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-M-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CDX	121					Withdrawn
CDX	122	C	Dr. Qu Report Figure XII.55 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	123					Withdrawn
CDX	124	C	Dr. Qu Report Figure XII.57 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-SCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	125					Withdrawn
CDX	126	C	Dr. Qu Report Figure XII.59 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-SFB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	127	C	Dr. Qu Report Figure XII.6 – Relative movement between points A and C in ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	128	C	Dr. Qu Report Figure XII.7 – Relative movement between points A and C in ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	129	C	Dr. Qu Report Figure XII.8 – Relative movement between points A and C in ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	130	C	Dr. Qu Report Figure XII.9 – Relative movement between points A and C in ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted

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CDX	131	C	Dr. Qu Report Figure XII.10 – Relative movement between points A and C in FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	132	C	Dr. Qu Report Figure XII.11 – Relative movement between points A and C in FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	133	C	Dr. Qu Report Figure XII.12 – Relative movement between points A and C in FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	134	C	Dr. Qu Report Figure XII.13 – Relative movement between points A and C in FRE-S-SCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	135					Withdrawn
CDX	136	C	Dr. Qu Report Figure XII.16 – Relative movement between points A and C in FRE-S-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	137	C	Dr. Qu Report Figure XII.17 – Relative movement between points A and C in FRE-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	138	C	Dr. Qu Report Figure XII.18 – Relative movement between points A and C in QUA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	139	C	Dr. Qu Report Figure XII.19 – Relative movement between points A and C in QUA-M-H-2-A	Qu	INFRNG/NON-INFRNG	Admitted
CDX	140	C	Dr. Qu Report Figure XII.20 – Relative movement between points A and C in QUA-M-H-2-B	Qu	INFRNG/NON-INFRNG	Admitted
CDX	141	C	Dr. Qu Report Figure XII.21 – Relative movement between points A and C in QUA-M-SCB-A	Qu	INFRNG/NON-INFRNG	Admitted
CDX	142	C	Dr. Qu Report Figure XII.22 – Relative movement between points A and C in QUA-M-SCB-B	Qu	INFRNG/NON-INFRNG	Admitted
CDX	143	C	Dr. Qu Report Figure XII.23 – Relative movement between points A and C in QUA-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	144	C	Dr. Qu Report Figure XII.24 – Relative movement between points A and C in QUA-S-HFT-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	145	C	Dr. Qu Report Figure XII.25 – Relative movement between points A and C in QUA-S-HFT-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	146	C	Dr. Qu Report Figure XII.26 – Relative movement between points A and C in QUA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	147	C	Dr. Qu Report Figure XII.27 – Relative movement between points A and C in SPA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	148	C	Dr. Qu Report Figure XII.28 – Relative movement between points A and C in SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	149	C	Dr. Qu Report Figure XII.29 – Relative movement between points A and C in SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	150	C	Dr. Qu Report Figure XII.30 – Relative movement between points A and C in SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	151	C	Dr. Qu Report Figure XII.31 – Relative movement between points A and C in SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	152	C	Dr. Qu Report Figure XII.32 – Relative movement between points A and C in SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CDX	153	C	Dr. Qu Report Figure XII.33 – Relative movement between points A and C in SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	154	C	Dr. Qu Report Figure XII.34 – Relative movement between points A and C in SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	155	C	Dr. Qu Report Figure XII.35 – Relative movement between points A and C in SPA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	156	C	Dr. Qu Report Figure XII.36 – Relative movement between points A and C in STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	157	C	Dr. Qu Report Figure XII.37 – Relative movement between points A and C in STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CDX	158	C	Dr. Qu Report Figure XII.38 – Relative movement between points A and C in STM-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	159	C	Dr. Qu Report Figure XII.39 – Relative movement between points A and C in STM-S-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	160	C	Dr. Qu Report Figure XII.4 – Relative movement between points A and C in ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	161	C	Dr. Qu Report Figure XII.40 – Relative movement between points A and C in STM-HCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	162	C	Dr. Qu Report Figure XII.41 – Relative movement between points A and C in STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CDX	163					Withdrawn
CDX	164	C	Dr. Qu Report Figure XII.43 – Relative movement between points A and C in STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	165					Withdrawn
CDX	166	C	Dr. Qu Report Figure XII.45 – Relative movement between points A and C in STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	167					Withdrawn
CDX	168	C	Dr. Qu Report Figure XII.2 – Illustration of Local Coordinate System in 2 Dimensions	Qu	INFRNG/NON-INFRNG	Admitted
CDX	169	C	Dr. Qu Report Figure XII.86 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-M-S-1	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	170	C	Dr. Qu Report Figure XII.87 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	171	C	Dr. Qu Report Figure XII.88 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	172	C	Dr. Qu Report Figure XII.89 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	173	C	Dr. Qu Report Figure XII.90 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	174	C	Dr. Qu Report Figure XII.91 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	175	C	Dr. Qu Report Figure XII.92 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CDX	176	C	Dr. Qu Report Figure XII.93 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	177	C	Dr. Qu Report Figure XII.94 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	178	C	Dr. Qu Report Figure XII.95 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	179	C	Dr. Qu Report Figure XII.96 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	180	C	Dr. Qu Report Figure XII.97 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	181	C	Dr. Qu Report Figure XII.98 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SFB-1	Qu	INFRNG/NON-INFRNG	Admitted

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CDX	182	C	Dr. Qu Report Figure XII.99 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	183	C	Dr. Qu Report Figure XII.100 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	184	C	Dr. Qu Report Figure XII.101 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	185	C	Dr. Qu Report Figure XII.102 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-2-A	Qu	INFRNG/NON-INFRNG	Admitted
CDX	186	C	Dr. Qu Report Figure XII.103 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-2-B	Qu	INFRNG/NON-INFRNG	Admitted
CDX	187	C	Dr. Qu Report Figure XII.104 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-SCB-A	Qu	INFRNG/NON-INFRNG	Admitted
CDX	188	C	Dr. Qu Report Figure XII.105 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-SCB-B	Qu	INFRNG/NON-INFRNG	Admitted
CDX	189	C	Dr. Qu Report Figure XII.106 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	190	C	Dr. Qu Report Figure XII.107 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-S-HFT-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	191	C	Dr. Qu Report Figure XII.108 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-S-HFT-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	192	C	Dr. Qu Report Figure XII.109 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	193	C	Dr. Qu Report Figure XII.110 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	194	C	Dr. Qu Report Figure XII.111 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	195	C	Dr. Qu Report Figure XII.111 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	196	C	Dr. Qu Report Figure XII.112 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	197	C	Dr. Qu Report Figure XII.113 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	198	C	Dr. Qu Report Figure XII.114 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	199	C	Dr. Qu Report Figure XII.115 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CDX	200	C	Dr. Qu Report Figure XII.116 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	201	C	Dr. Qu Report Figure XII.117 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	202	C	Dr. Qu Report Figure XII.118 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-S-SFS	Qu	INFRNG/NON-INFRNG	Admitted
CDX	203	C	Dr. Qu Report Figure XII.119 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	204	C	Dr. Qu Report Figure XII.120 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CDX	205	C	Dr. Qu Report Figure XII.121 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-M-SF	Qu	INFRNG/NON-INFRNG	Admitted

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CDX	206	C	Dr. Qu Report Figure XII.122 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	207	C	Dr. Qu Report Figure XII.123 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	208	C	Dr. Qu Report Figure XII.124 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CDX	209	C	Dr. Qu Report Figure XII.125 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	210	C	Dr. Qu Report Figure XII.126 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	211	C	Dr. Qu Report Figure XII.127 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	212	C	Dr. Qu Report Figure XII.128 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	213	C	Dr. Qu Report Figure XII.129 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-Moire	Qu	INFRNG/NON-INFRNG	Admitted
CDX	214	C	Dr. Qu Report Figure XII.130 – Accumulated Plastic Work for ATI-M-S-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	215	C	Dr. Qu Report Figure XII.131 – Accumulated Plastic Work for ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	216	C	Dr. Qu Report Figure XII.132 – Accumulated Plastic Work for ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	217	C	Dr. Qu Report Figure XII.133 – Accumulated Plastic Work for ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	218	C	Dr. Qu Report Figure XII.134 – Accumulated Plastic Work for ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	219	C	Dr. Qu Report Figure XII.135 – Accumulated Plastic Work for ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	220	C	Dr. Qu Report Figure XII.136 – Accumulated Plastic Work for ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	221	C	Dr. Qu Report Figure XII.137 – Accumulated Plastic Work for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	222	C	Dr. Qu Report Figure XII.138 – Accumulated Plastic Work for FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	223	C	Dr. Qu Report Figure XII.139 – Accumulated Plastic Work for FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	224	C	Dr. Qu Report Figure XII.14 – Relative movement between points A and C in FRE-S-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	225	C	Dr. Qu Report Figure XII.140 – Accumulated Plastic Work for FRE-S-SCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	226	C	Dr. Qu Report Figure XII.141 – Accumulated Plastic Work for FRE-S-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	227	C	Dr. Qu Report Figure XII.142 – Accumulated Plastic Work for FRE-S-SFB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	228	C	Dr. Qu Report Figure XII.143 – Accumulated Plastic Work for FRE-S-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	229	C	Dr. Qu Report Figure XII.144 – Accumulated Plastic Work for FRE-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	230	C	Dr. Qu Report Figure XII.145 – Accumulated Plastic Work for QUA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	231	C	Dr. Qu Report Figure XII.146 – Accumulated Plastic Work for QUA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	232	C	Dr. Qu Report Figure XII.147 – Accumulated Plastic Work for QUA-M-H-2-B	Qu	INFRNG/NON-INFRNG	Admitted
CDX	233	C	Dr. Qu Report Figure XII.148 – Accumulated Plastic Work for QUA-M-SCB-A	Qu	INFRNG/NON-INFRNG	Admitted
CDX	234	C	Dr. Qu Report Figure XII.149 – Accumulated Plastic Work for QUA-M-SCB-B	Qu	INFRNG/NON-INFRNG	Admitted
CDX	235	C	Dr. Qu Report Figure XII.15 – Relative movement between points A and C in FRE-S-SFB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	236	C	Dr. Qu Report Figure XII.150 – Accumulated Plastic Work for QUA-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	237	C	Dr. Qu Report Figure XII.151 – Accumulated Plastic Work for QUA-S-HFT-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	238	C	Dr. Qu Report Figure XII.152 – Accumulated Plastic Work for QUA-S-HFT-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	239	C	Dr. Qu Report Figure XII.153 – Accumulated Plastic Work for QUA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	240	C	Dr. Qu Report Figure XII.154 – Accumulated Plastic Work for SPA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	241	C	Dr. Qu Report Figure XII.155 – Accumulated Plastic Work for SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	242	C	Dr. Qu Report Figure XII.156 – Accumulated Plastic Work for SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	243	C	Dr. Qu Report Figure XII.157 – Accumulated Plastic Work for SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	244	C	Dr. Qu Report Figure XII.158 – Accumulated Plastic Work for SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	245	C	Dr. Qu Report Figure XII.159 – Accumulated Plastic Work for SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CDX	246					Withdrawn
CDX	247	C	Dr. Qu Report Figure XII.160 – Accumulated Plastic Work for SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	248	C	Dr. Qu Report Figure XII.161 – Accumulated Plastic Work for SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	249	C	Dr. Qu Report Figure XII.162 – Accumulated Plastic Work for SPA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	250	C	Dr. Qu Report Figure XII.163 – Accumulated Plastic Work for STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	251	C	Dr. Qu Report Figure XII.164 – Accumulated Plastic Work for STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CDX	252	C	Dr. Qu Report Figure XII.165 – Accumulated Plastic Work for STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CDX	253	C	Dr. Qu Report Figure XII.166 – Accumulated Plastic Work for STM-S-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	254	C	Dr. Qu Report Figure XII.167 – Accumulated Plastic Work for STM-S-HCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	255	C	Dr. Qu Report Figure XII.168 – Accumulated Plastic Work for STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CDX	256	C	Dr. Qu Report Figure XII.169 – Accumulated Plastic Work for STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	257					Withdrawn
CDX	258	C	Dr. Qu Report Figure XII.170 – Accumulated Plastic Work for STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	259	C	Dr. Qu Report Figure XII.171 – Accumulated Plastic Work for STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	260	C	Dr. Qu Report Figure XII.172 – Accumulated Plastic Work for STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	261	C	Dr. Qu Report Figure XII.173 – Accumulated Plastic Work for STM-S-Moire	Qu	INFRNG/NON-INFRNG	Admitted
CDX	262					Withdrawn
CDX	263	C	Dr. Qu Report Figure XIII.1 – Displacement vector of the solder due to both internal and external loads	Qu	INFRNG/NON-INFRNG	Admitted
CDX	264 - 285					Withdrawn
CDX	286	C	Dr. Qu Report Figure III.2 – Linear Stress-Strain Relationship	Qu	INFRNG/NON-INFRNG	Admitted
CDX	287	C	Dr. Qu Report Figure XIII.4 – Accumulated Plastic Work due to External Forces for ATI-M-S-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	288	C	Dr. Qu Report Figure XIII.5 – Accumulated Plastic Work due to External Forces for ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	289	C	Dr. Qu Report Figure XIII.6 – Accumulated Plastic Work due to External Forces for ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	290	C	Dr. Qu Report Figure XIII.7 – Accumulated Plastic Work due to External Forces for ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	291	C	Dr. Qu Report Figure XIII.8 – Accumulated Plastic Work due to External Forces for ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	292	C	Dr. Qu Report Figure XIII.9 – Accumulated Plastic Work due to External Forces for ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	293					Withdrawn
CDX	294	C	Dr. Qu Report Figure XIII.11 – Accumulated Plastic Work due to External Forces for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	295					Withdrawn
CDX	296	C	Dr. Qu Report Figure XIII.13 – Accumulated Plastic Work due to External Forces for FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	297					Withdrawn
CDX	298	C	Dr. Qu Report Figure XIII.15 – Accumulated Plastic Work due to External Forces for FRE-S-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	299					Withdrawn
CDX	300	C	Dr. Qu Report Figure XIII.17 – Accumulated Plastic Work due to External Forces for FRE-S-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	301					Withdrawn
CDX	302	C	Dr. Qu Report Figure XIII.19 – Accumulated Plastic Work due to External Forces for QUA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	303					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	304	C	Dr. Qu Report Figure XIII.20 – Accumulated Plastic Work due to External Forces for QUA-M-H-2-A	Qu	INFRNG/NON-INFRNG	Admitted
CDX	305					Withdrawn
CDX	306	C	Dr. Qu Report Figure XIII.22 – Accumulated Plastic Work due to External Forces for QUA-M-SCB-A	Qu	INFRNG/NON-INFRNG	Admitted
CDX	307					Withdrawn
CDX	308	C	Dr. Qu Report Figure XIII.24 – Accumulated Plastic Work due to External Forces for QUA-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	309					Withdrawn
CDX	310	C	Dr. Qu Report Figure XIII.26 – Accumulated Plastic Work due to External Forces for QUA-S-HFT-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	311					Withdrawn
CDX	312	C	Dr. Qu Report Figure XIII.28 – Accumulated Plastic Work due to External Forces for SPA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	313					Withdrawn
CDX	314	C	Dr. Qu Report Figure XIII.3 – Applying the displacement vector uex(x, T) to the off-board package is equivalent to applying external loads to the package	Qu	INFRNG/NON-INFRNG	Admitted
CDX	315	C	Dr. Qu Report Figure XIII.30 – Accumulated Plastic Work due to External Forces for SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	316	C	Dr. Qu Report Figure XIII.31 – Accumulated Plastic Work due to External Forces for SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	317	C	Dr. Qu Report Figure XIII.32 – Accumulated Plastic Work due to External Forces for SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	318	C	Dr. Qu Report Figure XIII.33 – Accumulated Plastic Work due to External Forces for SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CDX	319	C	Dr. Qu Report Figure XIII.34 – Accumulated Plastic Work due to External Forces for SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	320	C	Dr. Qu Report Figure XIII.35 – Accumulated Plastic Work due to External Forces for SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	321	C	Dr. Qu Report Figure XIII.36 – Accumulated Plastic Work due to External Forces for SPA-S-SFS	Qu	INFRNG/NON-INFRNG	Admitted
CDX	322	C	Dr. Qu Report Figure XIII.37 – Accumulated Plastic Work due to External Forces for STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	323	C	Dr. Qu Report Figure XIII.38 – Accumulated Plastic Work due to External Forces for STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CDX	324	C	Dr. Qu Report Figure XIII.39 – Accumulated Plastic Work due to External Forces for STM-M-SF	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	325					Withdrawn
CDX	326	C	Dr. Qu Report Figure XIII.40 – Accumulated Plastic Work due to External Forces for STM-M-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	327					Withdrawn
CDX	328	C	Dr. Qu Report Figure XIII.41 – Accumulated Plastic Work due to External Forces for STM-M-HCS-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	329	C	Dr. Qu Report Figure XIII.42 – Accumulated Plastic Work due to External Forces for STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CDX	330	C	Dr. Qu Report Figure XIII.43 – Accumulated Plastic Work due to External Forces for STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	331	C	Dr. Qu Report Figure XIII.44 – Accumulated Plastic Work due to External Forces for STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	332	C	Dr. Qu Report Figure XIII.45 – Accumulated Plastic Work due to External Forces for STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	333	C	Dr. Qu Report Figure XIII.46 – Accumulated Plastic Work due to External Forces for STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	334	C	Dr. Qu Report Figure XIII.47 – Accumulated Plastic Work due to External Forces for STM-S-Moire	Qu	INFRNG/NON-INFRNG	Admitted
CDX	335	C	Dr. Qu Report Figure XIV.45 – Compression due to external forces in ATI-M-S-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	336	C	Dr. Qu Report Figure XIV.46 – Compression due to external forces in ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	337	C	Dr. Qu Report Figure XIV.47 – Compression due to external forces in ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	338	C	Dr. Qu Report Figure XIV.48 – Compression due to external forces in ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	339	C	Dr. Qu Report Figure XIV.49 – Compression due to external forces in ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	340	C	Dr. Qu Report Figure XIV.5 – Deformation of the compliant layer from 125C to -25C for ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	341	C	Dr. Qu Report Figure XIV.50 – Compression due to external forces in ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	342	C	Dr. Qu Report Figure XIV.51 – Compression due to external forces in ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CDX	343	C	Dr. Qu Report Figure XIV.52 – Compression due to external forces in FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	344	C	Dr. Qu Report Figure XIV.53 – Compression due to external forces in FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	345	C	Dr. Qu Report Figure XIV.54 – Compression due to external forces in FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	346	C	Dr. Qu Report Figure XIV.55 – Compression due to external forces in FRE-S-SCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	347	C	Dr. Qu Report Figure XIV.56 – Compression due to external forces in FRE-S-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	348	C	Dr. Qu Report Figure XIV.57 – Compression due to external forces in FRE-S-SFB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	349	C	Dr. Qu Report Figure XIV.58 – Compression due to external forces in FRE-S-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	350	C	Dr. Qu Report Figure XIV.59 – Compression due to external forces in FRE-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	351	C	Dr. Qu Report Figure XIV.6 – Deformation of the compliant layer from 125C to -25C for ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	352	C	Dr. Qu Report Figure XIV.60 – Compression due to external forces in QUA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	353	C	Dr. Qu Report Figure XIV.61 – Compression due to external forces in QUA-M-H-2-A	Qu	INFRNG/NON-INFRNG	Admitted
CDX	354	C	Dr. Qu Report Figure XIV.62 – Compression due to external forces in QUA-M-H-2-B	Qu	INFRNG/NON-INFRNG	Admitted
CDX	355	C	Dr. Qu Report Figure XIV.63 – Compression due to external forces in QUA-M-SCB-A	Qu	INFRNG/NON-INFRNG	Admitted
CDX	356	C	Dr. Qu Report Figure XIV.64 – Compression due to external forces in QUA-M-SCB-B	Qu	INFRNG/NON-INFRNG	Admitted
CDX	357	C	Dr. Qu Report Figure XIV.65 – Compression due to external forces in QUA-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	358	C	Dr. Qu Report Figure XIV.66 – Compression due to external forces in QUA-S-HFT-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	359	C	Dr. Qu Report Figure XIV.67 – Compression due to external forces in QUA-S-HFT-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	360	C	Dr. Qu Report Figure XIV.68 – Compression due to external forces in QUA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	361	C	Dr. Qu Report Figure XIV.69 – Compression due to external forces in SPA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	362	C	Dr. Qu Report Figure XIV.7 – Deformation of the compliant layer from 125C to -25C for ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CDX	363	C	Dr. Qu Report Figure XIV.70 – Compression due to external forces in SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	364	C	Dr. Qu Report Figure XIV.71 – Compression due to external forces in SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	365	C	Dr. Qu Report Figure XIV.72 – Compression due to external forces in SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	366	C	Dr. Qu Report Figure XIV.73 – Compression due to external forces in SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	367	C	Dr. Qu Report Figure XIV.74 – Compression due to external forces in SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CDX	368	C	Dr. Qu Report Figure XIV.75 – Compression due to external forces in SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	369	C	Dr. Qu Report Figure XIV.76 – Compression due to external forces in SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	370	C	Dr. Qu Report Figure XIV.77– Compression due to external forces in SPA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CDX	371	C	Dr. Qu Report Figure XIV.78 – Compression due to external forces in STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	372	C	Dr. Qu Report Figure XIV.79 – Compression due to external forces in STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CDX	373	C	Dr. Qu Report Figure XIV.8 – Deformation of the compliant layer from 125C to -25C for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	374	C	Dr. Qu Report Figure XIV.80 – Compression due to external forces in STM-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	375	C	Dr. Qu Report Figure XIV.81 – Compression due to external forces in STM-S-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	376	C	Dr. Qu Report Figure XIV.82 – Compression due to external forces in STM-S-HCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	377	C	Dr. Qu Report Figure XIV.83 – Compression due to external forces in STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CDX	378	C	Dr. Qu Report Figure XIV.84 – Compression due to external forces in STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CDX	379	C	Dr. Qu Report Figure XIV.85 – Compression due to external forces in STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	380	C	Dr. Qu Report Figure XIV.86 – Compression due to external forces in STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	381	C	Dr. Qu Report Figure XIV.87 – Compression due to external forces in STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CDX	382	C	Qu Deposition Exhibit #260, Errata Sheet for January 11, 2008 Expert Report	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	383	C	Dr. Qu Report Figure IXB.6 – Assembled Packages with Two-Fold Symmetry	Qu	INFRNG/NON-INFRNG	Admitted
CDX	384					Withdrawn
CDX	385					Withdrawn
CDX	386 - 389					Withdrawn
CDX	390					Withdrawn
CDX	391					Withdrawn
CDX	392					Withdrawn
CDX	393					Withdrawn
CDX	394					Withdrawn
CDX	395 - 399					Withdrawn
CDX	400		Freyman Article, Figure 1	Ivey	VLD/INVLD	Admitted
CDX	401		Dual In-Line Package	Ivey	VLD/INVLD	Admitted
CDX	402		Pin Grid Array	Ivey	VLD/INVLD	Admitted
CDX	403		Bending Caused by Differential Thermal Expansion	Ivey	VLD/INVLD	Admitted
CDX	404		Modulus and CTE	Ivey	VLD/INVLD	Admitted
CDX	405		Differential Thermal Expansion in a BGA	Ivey	VLD/INVLD	Admitted
CDX	406		Glass Transition Temperature and Modulus of Elasticity	Ivey	VLD/INVLD	Admitted
CDX	407		CTE and Modulus	Ivey	VLD/INVLD	Admitted
CDX	408		Compliant Die Attach References	Ivey	VLD/INVLD	Admitted
CDX	409		First Level Problems in a BGA	Ivey	VLD/INVLD	Admitted
CDX	410		Ceramic Substrate	Ivey	VLD/INVLD	Admitted
CDX	411		Die Attach	Ivey	VLD/INVLD	Admitted
CDX	412		Saito Reference	Ivey	VLD/INVLD	Admitted
CDX	413		326 Patent, Figure 26	Ivey	VLD/INVLD	Admitted
CDX	414		Tessera's Licensees	Ivey	VLD/INVLD	Admitted
CDX	415		Solder Columns	Ivey	VLD/INVLD	Admitted
CDX	416		Quad Flat Pack and Leadless Chip Carrier	Ivey	VLD/INVLD	Admitted
CDX	417 - 424					Withdrawn
CDX	425					Withdrawn
CDX	426					Withdrawn
CDX	427					Withdrawn
CDX	428					Withdrawn
CDX	429					Withdrawn
CDX	430					Withdrawn
CDX	431					Withdrawn
CDX	432					Withdrawn
CDX	433					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	434					Withdrawn
CDX	435					Withdrawn
CDX	436					Withdrawn
CDX	437					Withdrawn
CDX	438					Withdrawn
CDX	439					Withdrawn
CDX	440					Withdrawn
CDX	441					Withdrawn
CDX	442					Withdrawn
CDX	443					Withdrawn
CDX	444					Withdrawn
CDX	445					Withdrawn
CDX	446					Withdrawn
CDX	447					Withdrawn
CDX	448					Withdrawn
CDX	449					Withdrawn
CDX	450					Withdrawn
CDX	451					Withdrawn
CDX	452					Withdrawn
CDX	453 - 459					Withdrawn
CDX	460					Withdrawn
CDX	461					Withdrawn
CDX	462					Withdrawn
CDX	463					Withdrawn
CDX	464					Withdrawn
CDX	465					Withdrawn
CDX	466					Withdrawn
CDX	467					Withdrawn
CDX	468					Withdrawn
CDX	469					Withdrawn
CDX	470					Withdrawn
CDX	471					Withdrawn
CDX	472					Withdrawn
CDX	473					Withdrawn
CDX	474					Withdrawn
CDX	475					Withdrawn
CDX	476					Withdrawn
CDX	477					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	478					Withdrawn
CDX	479					Withdrawn
CDX	480					Withdrawn
CDX	481					Withdrawn
CDX	482					Withdrawn
CDX	483					Withdrawn
CDX	484					Withdrawn
CDX	485					Withdrawn
CDX	486					Withdrawn
CDX	487					Withdrawn
CDX	488					Withdrawn
CDX	489					Withdrawn
CDX	490					Withdrawn
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CDX	494					Withdrawn
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CDX	502					Withdrawn
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CDX	506					Withdrawn
CDX	507					Withdrawn
CDX	508					Withdrawn
CDX	509					Withdrawn
CDX	510					Withdrawn
CDX	511					Withdrawn
CDX	512					Withdrawn
CDX	513					Withdrawn
CDX	514					Withdrawn
CDX	515					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	516					Withdrawn
CDX	517					Withdrawn
CDX	518					Withdrawn
CDX	519					Withdrawn
CDX	520					Withdrawn
CDX	521					Withdrawn
CDX	522					Withdrawn
CDX	523					Withdrawn
CDX	524					Withdrawn
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CDX	541					Withdrawn
CDX	542					Withdrawn
CDX	543					Withdrawn
CDX	544					Withdrawn
CDX	545					Withdrawn
CDX	546					Withdrawn
CDX	547					Withdrawn
CDX	548					Withdrawn
CDX	549					Withdrawn
CDX	550					Withdrawn
CDX	551					Withdrawn
CDX	552					Withdrawn
CDX	553					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	554					Withdrawn
CDX	555					Withdrawn
CDX	556					Withdrawn
CDX	557					Withdrawn
CDX	558					Withdrawn
CDX	559					Withdrawn
CDX	560					Withdrawn
CDX	561					Withdrawn
CDX	562					Withdrawn
CDX	563					Withdrawn
CDX	564					Withdrawn
CDX	565					Withdrawn
CDX	566					Withdrawn
CDX	567					Withdrawn
CDX	568					Withdrawn
CDX	569	C	Table of Packages	Qu	INFRNG/NON-INFRNG	Admitted
CDX	570	C	Geometric Dimensions of STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CDX	571	C	Geometric Dimensions of STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CDX	572	C	Geometric Dimension of STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	573	C	Geometric Dimension of STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CDX	574	C	Geometric Dimension of STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CDX	575	C	Geometric Dimension of STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CDX	576	C	Geometric Dimension of STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	577	C	Geometric Dimension of STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	578	C	CrossSection of STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CDX	579	C	CrossSection of STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	580	C	CrossSection of STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CDX	581	C	CrossSection of STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	582	C	CrossSection of STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CDX	583	C	CrossSection of STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	584	C	CrossSection of STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	585	C	CrossSection of STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CDX	586	C	Mesh for STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CDX	587	C	Mesh for STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CDX	588	C	Mesh for STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CDX	589	C	Mesh for STM-MC-TFBGA-103-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	590	C	Mesh for STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	591	C	Mesh for STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CDX	592	C	Mesh for STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CDX	593	C	Mesh for STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	594	C	Material Property FEA Inputs	Qu	INFRNG/NON-INFRNG	Admitted
CDX	595	C	Column Displacement STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CDX	596	C	Column Displacement STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CDX	597	C	Column Displacement STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	598	C	Column Displacement STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	599	C	Column Displacement STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	600	C	Column Displacement STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CDX	601	C	Column Displacement STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CDX	602	C	Column Displacement STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CDX	603	C	AC Movement STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CDX	604	C	AC Movement STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CDX	605	C	AC Movement STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CDX	606	C	AC Movement STM-SC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	607	C	AC Movement STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CDX	608	C	AC Movement STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	609	C	AC Movement STM-SC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	610	C	AC Movement STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CDX	611	C	Plastic Work STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CDX	612	C	Plastic Work STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CDX	613	C	Plastic Work STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CDX	614	C	Plastic Work STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	615	C	Plastic Work STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CDX	616	C	Plastic Work STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CDX	617	C	Plastic Work STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	618	C	Plastic Work STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	619	C	Percentage Life Improvement Table Method 1	Qu	INFRNG/NON-INFRNG	Admitted
CDX	620	C	Percentage Life Improvement Graph For New ST Products	Qu	INFRNG/NON-INFRNG	Admitted
CDX	621	C	Percentage Life Improvement Graph Comparison	Qu	INFRNG/NON-INFRNG	Admitted
CDX	622	C	Symmetry Results Plot	Qu	INFRNG/NON-INFRNG	Admitted
CDX	623	C	Copper Layer Mesh	Qu	INFRNG/NON-INFRNG	Admitted
CDX	624	C	Copper Layer Comparison Table	Qu	INFRNG/NON-INFRNG	Admitted
CDX	625	C	Polar Plot STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CDX	626	C	Polar Plot STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CDX	627	C	Polar Plot STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	628	C	Polar Plot STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	629	C	Polar Plot STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CDX	630	C	Polar Plot STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CDX	631	C	Polar Plot STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	632	C	Polar Plot STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CDX	633	C	Plastic Work External STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CDX	634	C	Plastic Work External STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CDX	635	C	Plastic Work External STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CDX	636	C	Plastic Work External STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CDX	637	C	Plastic Work External STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	638	C	Plastic Work External STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CDX	639	C	Plastic Work External STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CDX	640	C	Plastic Work External STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	641	C	Percentage Life Improvement Table Method 2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	642	C	Compression for STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CDX	643	C	Compression for STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CDX	644	C	Compression for STM-SC-TBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CDX	645	C	Compression for STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CDX	646	C	Compression for STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	647	C	Compression for STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CDX	648	C	Compression for STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CDX	649	C	Compression for STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CPX	1	C	01.11.2008 Dr. Qu Back-Up Data 1 (including fre_mc_pbga_289_2; qua_mc_nsp_432; spa_mc_fbga_188_2; spa_mc_lrbga_080; spa_sc_lrbga_080; spa_sc_vfbga_044_2; and stm_sc_lbga_288)	Qu	INFRNG/NON-INFRNG	Admitted
CPX	2	C	01.11.2008 Dr. Qu Back-Up Data - 2 (including ati_mc_stfbga_259; fre_sc_pbga_244_1; fre_sc_pbga_244_2; qua_mc_msp_351a; qua_sc_csp_064_2; spa_mc_fbga_188_1; spa_sc_fbga_048; and spa_sc_vfbga_044_1)	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CPX	3	C	01.11.2008 Dr. Qu Back-Up Data - 3 (including ati_mc_stfbga_259_moire; ati_sc_tfbga_104; ati_sc_tfbga_179_2; fre_sc_pbga_121; fre_sc_pbga_240; qua_sc_csp_060; qua_sc_csp_064; spa_mc_lrgba_064; spa_sc_frbga_064_moire; stm_mc_tfbga_088; stm_mc_tfbga_105; st	Qu	INFRNG/NON-INFRNG	Admitted
CPX	4	C	01.11.2008 Dr. Qu Back-Up Data - 4 (including ati_mc_stfbga_259_2; ati_sc_tfbga_179; fre_ms_pbga_289_1; fre_sc_pbga_280; moire_stm_sc_tfbga_084; qua_sc_csp_097; spa_mc_fbga_188_3; stm_mc_tfbga_044_1; stm_mc_tfbga_105_4cyc; stm_mc_tfbga_105_coarse; stm_mc	Qu	INFRNG/NON-INFRNG	Admitted
CPX	5	C	01.11.2008 Dr. Qu Back-Up Data - 5 (including ati_mc_lfbga_272; ati_sc_tfbga_104_2; ati_sc_tfbga_179_full; fre_sc_pbga_244_3; moire_qua_mc_csp_216; qua_mc_csp_216a; qua_mc_csp_216b; qua_mc_msp_351b; and stm_sc_tfbga_244)	Qu	INFRNG/NON-INFRNG	Admitted
CPX	6	C	01.25.2008 Dr. Qu Back-Up Data (including ati_mc_stfbga_257; qua_sc_csp_060_die_thk_177; supp_fre_sc_pbga_144; and supp_fre_sc_pbga_196)	Qu	INFRNG/NON-INFRNG	Admitted
CPX	7					Withdrawn
CPX	8					Withdrawn
CPX	9					Withdrawn
CPX	10					Withdrawn
CPX	11					Withdrawn
CPX	12					Withdrawn
CPX	13					Withdrawn
CPX	14					Withdrawn
CPX	15		Ceramic Substrate Sample	Griffin	RMDY, OWNR	Admitted
CPX	16		FR-4 Prepreg 110 um Substrate Sample	Griffin	RMDY, OWNR	Admitted
CPX	17		FR-4 CORE Substrate Sample	Griffin	RMDY, OWNR	Admitted
CPX	18		FR-4 with Cu Substrate Sample	Griffin	RMDY, OWNR	Admitted
CPX	19		BT Laminate .15 mm Substrate Sample	Griffin	RMDY, OWNR	Admitted
CPX	20		BT Laminate 100um Substrate Sample	Griffin	RMDY, OWNR	Admitted
CPX	21		BT Laminate 400um Substrate Sample	Griffin	RMDY, OWNR	Admitted
CPX	22		Polyimide Substrate Sample	Griffin	RMDY, OWNR	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CPX	23		Laminate Substrate Product: Intel 4050LOYBQ2, Motorola SLVR cellular phone	Griffin	RMDY, OWNR	Admitted
CPX	24		Laminate Substrate Product: Toshiba	Griffin	RMDY, OWNR	Admitted
CPX	25	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	26	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	27					Withdrawn
CPX	28	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	29	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	30	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	31	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	32	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	33	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	34	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	35	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	36	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	37	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	38	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	39	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	40	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	41(a)	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	41(b)	C	Tessera Technology Transfer CD	Warner	RMDY, DI	Admitted
CPX	41(c)	C	Bottoms Up Database	Mitchell	Domestic Industry	Admitted
CPX	41(d)	C	Tessera Royalty Databases ("Bottom-Up"), 2003-2005	Mitchell	RMDY, DI	Admitted
CPX	42	C	Khandros Laboratory Notebook	DiStefano	OWNR	Admitted
CPX	43					Withdrawn
CPX	44					Withdrawn
CPX	45					Withdrawn
CPX	46					Withdrawn
CPX	47					Withdrawn
CPX	48					Withdrawn
CPX	49					Withdrawn
CPX	50					Withdrawn
CPX	51					Withdrawn
CPX	52					Withdrawn
CPX	53					Withdrawn
CPX	54					Withdrawn
CPX	55					Withdrawn
CPX	56					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CPX	57					Withdrawn
CPX	58					Withdrawn
CPX	59					Withdrawn
CPX	60					Withdrawn
CPX	61					Withdrawn
CPX	62					Withdrawn
CPX	63					Withdrawn
CPX	64					Withdrawn
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CPX	71					Withdrawn
CPX	72					Withdrawn
CPX	73					Withdrawn
CPX	74					Withdrawn
CPX	75					Withdrawn
CPX	76					Withdrawn
CPX	77					Withdrawn
CPX	78					Withdrawn
CPX	79					Withdrawn
CPX	80					Withdrawn
CPX	81	C	Mawer Deposition Exhibit #022, Freescale Bill of Materials (This is the physical version of JX-083C)	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
CPX	82	C	Chopin Deposition Exhibit #003, Freescale Bill of Materials (This is the physical version of JX-084C)	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
CPX	83	C	Mawer Deposition Exhibit #024, Freescale Bill of Materials (This is the physical version of JX-085C)	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
CPX	84	C	Mawer Deposition Exhibit #10	Qu, Sitaraman, Mawer, Chopin, Kellar	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CPX	85	C	Older style chip packages	DiStefano	OWNR	Admitted
CX	1					Withdrawn
CX	2	C	Second Amendment to TCC License Agreement (Tessera & Walton Advanced Electronic, Ltd.)	Pickett	RMDY, OWNR	Admitted
CX	3					Withdrawn
CX	4	C	TCC License Agreement (Tessera & Toshiba Corp.)	Pickett	RMDY, OWNR	Admitted
CX	5					Withdrawn
CX	6					Withdrawn
CX	7					Withdrawn
CX	8	C	Limited TCC License Agreement (Tessera & Amkor Electronics, Inc.)	Griffin	RMDY, OWNR	Admitted
CX	9					Withdrawn
CX	10					Withdrawn
CX	11					Withdrawn
CX	12					Withdrawn
CX	13					Withdrawn
CX	14					Withdrawn
CX	15					Withdrawn
CX	16					Withdrawn
CX	17					Withdrawn
CX	18					Withdrawn
CX	19	C	License Agreement in conjunction with settlement of pending litigation (Tessera & Sharp Corp.)	Pickett	RMDY, OWNR	Admitted
CX	20	C	License Agreement in conjunction with settlement of pending litigation (Tessera & Texas Instruments, Inc.)	Pickett	RMDY, OWNR	Admitted
CX	21					Withdrawn
CX	22					Withdrawn
CX	23					Withdrawn
CX	24					Withdrawn
CX	25					Withdrawn
CX	26					Withdrawn
CX	27	C	Restated TCC License Agreement (Tessera & Samsung Electronics, Co.)	Pickett	RMDY, OWNR	Admitted
CX	28					Withdrawn
CX	29					Withdrawn
CX	30					Withdrawn
CX	31					Withdrawn
CX	32					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	33					Withdrawn
CX	34					Withdrawn
CX	35					Withdrawn
CX	36					Withdrawn
CX	37	C	Third Amendment to Limited TCC License Agreement between Tessera, Inc. and Intel Corporation	Pickett	RMDY, OWNR	Admitted
CX	38					Withdrawn
CX	39					Withdrawn
CX	40	C	Amendment to Immunity Agreement between Tessera, Inc. and Sharp Corporation	Pickett	RMDY, OWNR	Admitted
CX	41					Withdrawn
CX	42	C	Second Addendum to the Master License Agreement between Tessera, Inc. and Sony Corporation	Pickett	RMDY, OWNR	Admitted
CX	43					Withdrawn
CX	44	C	TCC Patent License Amendment Between Rohm Co., Ltd. and Tessera, Inc.	Pickett	RMDY, OWNR	Admitted
CX	45	C	First Amendment to TCC License Agreement between Tessera, Inc. and EEMS Italia, SpA	Pickett	RMDY, OWNR	Admitted
CX	46					Withdrawn
CX	47	C	Letter Amendment to TCC Master License Agreement, between Hitachi Ltd. and Tessera, Inc.	Pickett	RMDY, OWNR	Admitted
CX	48					Withdrawn
CX	49	C	TCC License Agreement between Tessera and Shinko Electric Industries	Pickett	RMDY, OWNR	Admitted
CX	50					Withdrawn
CX	51					Withdrawn
CX	52					Withdrawn
CX	53					Withdrawn
CX	54					Withdrawn
CX	55					Withdrawn
CX	56					Withdrawn
CX	57					Withdrawn
CX	58	C	01.11.08 Expert Report of Dr. Qu	Qu	INFRNG/NON-INFRNG	Admitted
CX	59	C	Expert Report of Dr. Qu, Exhibit 1 - CV of Jianmin Qu		INFRNG/NON-INFRNG	Admitted
CX	60	C	Expert Report of Dr. Qu, Exhibit 2 - Documents Considered by Dr. Qu		INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	61	C	Expert Report of Dr. Qu, Exhibit 3 - Individual Results for Five Samples	Qu	INFRNG/NON-INFRNG	Admitted
CX	62	C	Expert Report of Dr. Qu, Exhibit 4 - Values of Constants Used in Finite Element Analysis	Qu	INFRNG/NON-INFRNG	Admitted
CX	63					Withdrawn
CX	64(1)					Withdrawn
CX	64(2)					Withdrawn
CX	65					Withdrawn
CX	66					Withdrawn
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CX	285					Withdrawn
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CX	288	C	Dr. Qu Report Figure III.2 – Linear Stress-Strain Relationship	Qu	INFRNG/NON-INFRNG	Admitted
CX	289					Withdrawn
CX	290					Withdrawn
CX	291					Withdrawn
CX	292	C	Dr. Qu Report Figure III.5 – Solder Joints In a Package Assembly Are Subjected to Both Normal and Shear Strains Due To Differential Thermal Expansion And Warpage Caused By Differential Thermal Expansion	Qu	INFRNG/NON-INFRNG	Admitted
CX	293					Withdrawn
CX	294					Withdrawn
CX	295	C	Dr. Qu Report Figure IV.1 – Example of Chip Package	Qu	INFRNG/NON-INFRNG	Admitted
CX	296	C	Dr. Qu Report Figure IV.2	Qu	INFRNG/NON-INFRNG	Admitted
CX	297					Withdrawn
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CX	316	C	Dr. Qu Report Figure IXA.3 – Schematic View of Diffraction Grating Replication Process	Qu	INFRNG/NON-INFRNG	Admitted
CX	317	C	Dr. Qu Report Figure IXA.4 – Sample Module in Grating Replication Fixture	Qu	INFRNG/NON-INFRNG	Admitted
CX	318					Withdrawn
CX	319					Withdrawn
CX	320	C	Dr. Qu Report Figure IXA.7 – Cross-Section of the Specimen and the Peltier Device Setup on the Optical Table	Qu	INFRNG/NON-INFRNG	Admitted
CX	321					Withdrawn
CX	322	C	Dr. Qu Report Figure IXA.9 – Time History of the Temperature Profile Applied at the Aluminum Base Plate	Qu	INFRNG/NON-INFRNG	Admitted
CX	323	C	Dr. Qu Report Figure IXB.1 – An Example of Finite Element Mesh	Qu	INFRNG/NON-INFRNG	Admitted
CX	324					Withdrawn
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CX	326					Withdrawn
CX	327					Withdrawn
CX	328					Withdrawn
CX	329	C	Dr. Qu Report Figure IXB.6 – Assembled Packages with Two-Fold Symmetry	Qu	INFRNG/NON-INFRNG	Admitted
CX	330					Withdrawn
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CX	357	C	Dr. Qu Report Figure VIIIE.5 – Picture of solder joint failure study performed by AMD at SPAN-ITC 035311	Qu	INFRNG/NON-INFRNG	Admitted
CX	358					Withdrawn
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CX	360					Withdrawn
CX	361					Withdrawn
CX	362	C	Dr. Qu Report Figure XA.5 – Points of interest on the moiré cut for ST-TFBGA-84 (a) is an overall view of the package cross section, (b) is a close-up of the cross-section, and (c) indicates where the package was cut	Qu	INFRNG/NON-INFRNG	Admitted
CX	363					Withdrawn
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CX	385	C	Dr. Qu Report Figure XB.7 – Geometric Dimensions and Material Properties for STM-TFBGA-84	Qu	INFRNG/NON-INFRNG	Admitted
CX	386					Withdrawn
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CX	476	C	Dr. Qu Report Figure XII.10 – Relative movement between points A and C in FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	477	C	Dr. Qu Report Figure XII.100 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	478	C	Dr. Qu Report Figure XII.101 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	479	C	Dr. Qu Report Figure XII.102 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-2-A	Qu	INFRNG/NON-INFRNG	Admitted
CX	480	C	Dr. Qu Report Figure XII.103 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-2-B	Qu	INFRNG/NON-INFRNG	Admitted
CX	481	C	Dr. Qu Report Figure XII.104 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-SCB-A	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	482	C	Dr. Qu Report Figure XII.105 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-M-SCB-B	Qu	INFRNG/NON-INFRNG	Admitted
CX	483	C	Dr. Qu Report Figure XII.106 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	484	C	Dr. Qu Report Figure XII.107 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-S-HFT-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	485	C	Dr. Qu Report Figure XII.108 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-S-HFT-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	486	C	Dr. Qu Report Figure XII.109 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for QUA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	487	C	Dr. Qu Report Figure XII.11 - Relative movement between points A and C in FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	488	C	Dr. Qu Report Figure XII.110 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	489	C	Dr. Qu Report Figure XII.111 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	490	C	Dr. Qu Report Figure XII.112 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	491	C	Dr. Qu Report Figure XII.113 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CX	492	C	Dr. Qu Report Figure XII.114 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	493	C	Dr. Qu Report Figure XII.115 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CX	494	C	Dr. Qu Report Figure XII.116 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	495	C	Dr. Qu Report Figure XII.117 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	496	C	Dr. Qu Report Figure XII.118 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for SPA-S-SFS	Qu	INFRNG/NON-INFRNG	Admitted
CX	497	C	Dr. Qu Report Figure XII.119 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted
CX	498	C	Dr. Qu Report Figure XII.12 – Relative movement between points A and C in FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	499	C	Dr. Qu Report Figure XII.120 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CX	500	C	Dr. Qu Report Figure XII.121 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	501	C	Dr. Qu Report Figure XII.122 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	502	C	Dr. Qu Report Figure XII.123 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	503	C	Dr. Qu Report Figure XII.124 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CX	504	C	Dr. Qu Report Figure XII.125 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	505	C	Dr. Qu Report Figure XII.126 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	506	C	Dr. Qu Report Figure XII.127 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	507	C	Dr. Qu Report Figure XII.128 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	508	C	Dr. Qu Report Figure XII.129 – The external force vector (blue on the bottom of the solder ball and displacement vector (red) of the terminal for STM-S-Moire	Qu	INFRNG/NON-INFRNG	Admitted
CX	509	C	Dr. Qu Report Figure XII.13 – Relative movement between points A and C in FRE-S-SCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	510	C	Dr. Qu Report Figure XII.130 – Accumulated Plastic Work for ATI-M-S-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	511	C	Dr. Qu Report Figure XII.131 – Accumulated Plastic Work for ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	512	C	Dr. Qu Report Figure XII.132 – Accumulated Plastic Work for ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	513	C	Dr. Qu Report Figure XII.133 – Accumulated Plastic Work for ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	514	C	Dr. Qu Report Figure XII.134 – Accumulated Plastic Work for ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	515	C	Dr. Qu Report Figure XII.135 – Accumulated Plastic Work for ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	516	C	Dr. Qu Report Figure XII.136 – Accumulated Plastic Work for ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CX	517	C	Dr. Qu Report Figure XII.137 – Accumulated Plastic Work for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	518	C	Dr. Qu Report Figure XII.138 – Accumulated Plastic Work for FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	519	C	Dr. Qu Report Figure XII.139 – Accumulated Plastic Work for FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	520	C	Dr. Qu Report Figure XII.14 – Relative movement between points A and C in FRE-S-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	521	C	Dr. Qu Report Figure XII.140 – Accumulated Plastic Work for FRE-S-SCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	522	C	Dr. Qu Report Figure XII.141 – Accumulated Plastic Work for FRE-S-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	523	C	Dr. Qu Report Figure XII.142 – Accumulated Plastic Work for FRE-S-SFB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	524	C	Dr. Qu Report Figure XII.143 – Accumulated Plastic Work for FRE-S-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	525	C	Dr. Qu Report Figure XII.144 – Accumulated Plastic Work for FRE-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	526	C	Dr. Qu Report Figure XII.145 – Accumulated Plastic Work for QUA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	527	C	Dr. Qu Report Figure XII.146 – Accumulated Plastic Work for QUA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	528	C	Dr. Qu Report Figure XII.147 – Accumulated Plastic Work for QUA-M-H-2-B	Qu	INFRNG/NON-INFRNG	Admitted
CX	529	C	Dr. Qu Report Figure XII.148 – Accumulated Plastic Work for QUA-M-SCB-A	Qu	INFRNG/NON-INFRNG	Admitted
CX	530	C	Dr. Qu Report Figure XII.149 – Accumulated Plastic Work for QUA-M-SCB-B	Qu	INFRNG/NON-INFRNG	Admitted
CX	531	C	Dr. Qu Report Figure XII.15 – Relative movement between points A and C in FRE-S-SFB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	532	C	Dr. Qu Report Figure XII.150 – Accumulated Plastic Work for QUA-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	533	C	Dr. Qu Report Figure XII.151 – Accumulated Plastic Work for QUA-S-HFT-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	534	C	Dr. Qu Report Figure XII.152 – Accumulated Plastic Work for QUA-S-HFT-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	535	C	Dr. Qu Report Figure XII.153 – Accumulated Plastic Work for QUA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	536	C	Dr. Qu Report Figure XII.154 – Accumulated Plastic Work for SPA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	537	C	Dr. Qu Report Figure XII.155 – Accumulated Plastic Work for SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	538	C	Dr. Qu Report Figure XII.156 – Accumulated Plastic Work for SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	539	C	Dr. Qu Report Figure XII.157 – Accumulated Plastic Work for SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CX	540	C	Dr. Qu Report Figure XII.158 – Accumulated Plastic Work for SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	541	C	Dr. Qu Report Figure XII.159 – Accumulated Plastic Work for SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CX	542	C	Dr. Qu Report Figure XII.16 – Relative movement between points A and C in FRE-S-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	543	C	Dr. Qu Report Figure XII.160 – Accumulated Plastic Work for SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CX	544	C	Dr. Qu Report Figure XII.161 – Accumulated Plastic Work for SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	545	C	Dr. Qu Report Figure XII.162 – Accumulated Plastic Work for SPA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	546	C	Dr. Qu Report Figure XII.163 – Accumulated Plastic Work for STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted
CX	547	C	Dr. Qu Report Figure XII.164 – Accumulated Plastic Work for STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CX	548	C	Dr. Qu Report Figure XII.165 – Accumulated Plastic Work for STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CX	549	C	Dr. Qu Report Figure XII.166 – Accumulated Plastic Work for STM-S-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	550	C	Dr. Qu Report Figure XII.167 – Accumulated Plastic Work for STM-S-HCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	551	C	Dr. Qu Report Figure XII.168 – Accumulated Plastic Work for STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CX	552	C	Dr. Qu Report Figure XII.169 – Accumulated Plastic Work for STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	553	C	Dr. Qu Report Figure XII.17 – Relative movement between points A and C in FRE-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	554	C	Dr. Qu Report Figure XII.170 – Accumulated Plastic Work for STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	555	C	Dr. Qu Report Figure XII.171 – Accumulated Plastic Work for STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	556	C	Dr. Qu Report Figure XII.172 – Accumulated Plastic Work for STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	557	C	Dr. Qu Report Figure XII.173 – Accumulated Plastic Work for STM-S-Moire	Qu	INFRNG/NON-INFRNG	Admitted
CX	558	C	Dr. Qu Report Figure XII.174 – Shear Strain	Qu	INFRNG/NON-INFRNG	Admitted
CX	559	C	Dr. Qu Report Figure XII.18 – Relative movement between points A and C in QUA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	560	C	Dr. Qu Report Figure XII.19 – Relative movement between points A and C in QUA-M-H-2-A	Qu	INFRNG/NON-INFRNG	Admitted
CX	561	C	Dr. Qu Report Figure XII.2 – Illustration of Local Coordinate System in 2 Dimensions	Qu	INFRNG/NON-INFRNG	Admitted
CX	562	C	Dr. Qu Report Figure XII.20 – Relative movement between points A and C in QUA-M-H-2-B	Qu	INFRNG/NON-INFRNG	Admitted
CX	563	C	Dr. Qu Report Figure XII.21 – Relative movement between points A and C in QUA-M-SCB-A	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	564	C	Dr. Qu Report Figure XII.22 – Relative movement between points A and C in QUA-M-SCB-B	Qu	INFRNG/NON-INFRNG	Admitted
CX	565	C	Dr. Qu Report Figure XII.23 – Relative movement between points A and C in QUA-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	566	C	Dr. Qu Report Figure XII.24 – Relative movement between points A and C in QUA-S-HFT-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	567	C	Dr. Qu Report Figure XII.25 – Relative movement between points A and C in QUA-S-HFT-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	568	C	Dr. Qu Report Figure XII.26 – Relative movement between points A and C in QUA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	569	C	Dr. Qu Report Figure XII.27 – Relative movement between points A and C in SPA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	570	C	Dr. Qu Report Figure XII.28 – Relative movement between points A and C in SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	571	C	Dr. Qu Report Figure XII.29 – Relative movement between points A and C in SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	572	C	Dr. Qu Report Figure XII.3 – Relative movement between points A and C in ATI-M-S-1			Admitted
CX	573	C	Dr. Qu Report Figure XII.30 – Relative movement between points A and C in SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CX	574	C	Dr. Qu Report Figure XII.31 – Relative movement between points A and C in SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	575	C	Dr. Qu Report Figure XII.32 – Relative movement between points A and C in SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CX	576	C	Dr. Qu Report Figure XII.33 – Relative movement between points A and C in SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CX	577	C	Dr. Qu Report Figure XII.34 – Relative movement between points A and C in SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	578	C	Dr. Qu Report Figure XII.35 – Relative movement between points A and C in SPA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	579	C	Dr. Qu Report Figure XII.36 – Relative movement between points A and C in STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted
CX	580	C	Dr. Qu Report Figure XII.37 – Relative movement between points A and C in STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CX	581	C	Dr. Qu Report Figure XII.38 – Relative movement between points A and C in STM-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	582	C	Dr. Qu Report Figure XII.39 – Relative movement between points A and C in STM-S-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	583	C	Dr. Qu Report Figure XII.4 – Relative movement between points A and C in ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	584	C	Dr. Qu Report Figure XII.40 – Relative movement between points A and C in STM-HCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	585	C	Dr. Qu Report Figure XII.41 – Relative movement between points A and C in STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CX	586	C	Dr. Qu Report Figure XII.42 – Relative movement between points A and C in STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	587	C	Dr. Qu Report Figure XII.43 – Relative movement between points A and C in STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	588	C	Dr. Qu Report Figure XII.44 – Relative movement between points A and C in STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	589	C	Dr. Qu Report Figure XII.45 – Relative movement between points A and C in STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	590	C	Dr. Qu Report Figure XII.46 – Relative movement between points A and C in STM-S-Moiré	Qu	INFRNG/NON-INFRNG	Admitted
CX	591	C	Dr. Qu Report Figure XII.47 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-M-S-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	592	C	Dr. Qu Report Figure XII.48 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	593	C	Dr. Qu Report Figure XII.49 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	594	C	Dr. Qu Report Figure XII.5 – Relative movement between points A and C in ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	595	C	Dr. Qu Report Figure XII.50 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	596	C	Dr. Qu Report Figure XII.51 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	597	C	Dr. Qu Report Figure XII.52 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	598	C	Dr. Qu Report Figure XII.53 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for ATI-M-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CX	599	C	Dr. Qu Report Figure XII.54 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	600	C	Dr. Qu Report Figure XII.55 – Comparison of movement in (a) baseline package versus (b) actual package under 10X magnification for FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	601					Withdrawn
CX	602					Withdrawn
CX	603					Withdrawn
CX	604					Withdrawn
CX	605					Withdrawn
CX	606					Withdrawn
CX	607					Withdrawn
CX	608					Withdrawn
CX	609					Withdrawn
CX	610					Withdrawn
CX	611					Withdrawn
CX	612					Withdrawn
CX	613					Withdrawn
CX	614					Withdrawn
CX	615					Withdrawn
CX	616	C	Dr. Qu Report Figure X11.7 - Relative movement between points A and C in ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	617					Withdrawn
CX	618					Withdrawn
CX	619					Withdrawn
CX	620					Withdrawn
CX	621					Withdrawn
CX	622					Withdrawn
CX	623					Withdrawn
CX	624					Withdrawn
CX	625					Withdrawn
CX	626					Withdrawn
CX	627	C	Dr. Qu Report Figure XII.8 – Relative movement between points A and C in ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	628					Withdrawn
CX	629					Withdrawn
CX	630					Withdrawn
CX	631					Withdrawn
CX	632					Withdrawn
CX	633					Withdrawn
CX	634	C	Dr. Qu Report Figure XII.86 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-M-S-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	635	C	Dr. Qu Report Figure XII.87 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	636	C	Dr. Qu Report Figure XII.88 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	637	C	Dr. Qu Report Figure XII.89 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	638	C	Dr. Qu Report Figure XII.9 – Relative movement between points A and C in ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CX	639	C	Dr. Qu Report Figure XII.90 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	640	C	Dr. Qu Report Figure XII.91 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	641	C	Dr. Qu Report Figure XII.92 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CX	642	C	Dr. Qu Report Figure XII.93 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	643	C	Dr. Qu Report Figure XII.94 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	644	C	Dr. Qu Report Figure XII.95 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	645	C	Dr. Qu Report Figure XII.96 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	646	C	Dr. Qu Report Figure XII.97 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	647	C	Dr. Qu Report Figure XII.98 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SFB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	648	C	Dr. Qu Report Figure XII.99 – The external force vector (blue) on the bottom of the solder ball and displacement vector (red) of the terminal for FRE-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	649	C	Dr. Qu Report Figure XIII.1 – Displacement vector of the solder due to both internal and external loads	Qu	INFRNG/NON-INFRNG	Admitted
CX	650	C	Dr. Qu Report Figure XIII.10 – Accumulated Plastic Work due to External Forces for ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CX	651	C	Dr. Qu Report Figure XIII.11 – Accumulated Plastic Work due to External Forces for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	652	C	Dr. Qu Report Figure XIII.12 – Accumulated Plastic Work due to External Forces for FRE-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	653	C	Dr. Qu Report Figure XIII.13 – Accumulated Plastic Work due to External Forces for FRE-S-HFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	654	C	Dr. Qu Report Figure XIII.14 – Accumulated Plastic Work due to External Forces for FRE-S-SCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	655	C	Dr. Qu Report Figure XIII.15 – Accumulated Plastic Work due to External Forces for FRE-S-SCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	656	C	Dr. Qu Report Figure XIII.16 – Accumulated Plastic Work due to External Forces for FRE-S-SFB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	657	C	Dr. Qu Report Figure XIII.17 – Accumulated Plastic Work due to External Forces for FRE-S-SFB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	658	C	Dr. Qu Report Figure XIII.18 – Accumulated Plastic Work due to External Forces for FRE-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	659	C	Dr. Qu Report Figure XIII.19 – Accumulated Plastic Work due to External Forces for QUA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	660	C	Dr. Qu Report Figure XIII.2 – Displacement vector of the solder due to both internal loads	Qu	INFRNG/NON-INFRNG	Admitted
CX	661	C	Dr. Qu Report Figure XIII.20 – Accumulated Plastic Work due to External Forces for QUA-M-H-2-A	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	662	C	Dr. Qu Report Figure XIII.21 – Accumulated Plastic Work due to External Forces for QUA-M-H-2-B	Qu	INFRNG/NON-INFRNG	Admitted
CX	663	C	Dr. Qu Report Figure XIII.22 – Accumulated Plastic Work due to External Forces for QUA-M-SCB-A	Qu	INFRNG/NON-INFRNG	Admitted
CX	664	C	Dr. Qu Report Figure XIII.23 – Accumulated Plastic Work due to External Forces for QUA-M-SCB-B	Qu	INFRNG/NON-INFRNG	Admitted
CX	665	C	Dr. Qu Report Figure XIII.24 – Accumulated Plastic Work due to External Forces for QUA-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	666	C	Dr. Qu Report Figure XIII.25 – Accumulated Plastic Work due to External Forces for QUA-S-HFT-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	667	C	Dr. Qu Report Figure XIII.26 – Accumulated Plastic Work due to External Forces for QUA-S-HFT-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	668	C	Dr. Qu Report Figure XIII.27 – Accumulated Plastic Work due to External Forces for QUA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	669	C	Dr. Qu Report Figure XIII.28 – Accumulated Plastic Work due to External Forces for SPA-M-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	670	C	Dr. Qu Report Figure XIII.29 – Accumulated Plastic Work due to External Forces for SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	671	C	Dr. Qu Report Figure XIII.3 – Applying the displacement vector uex(x, T) to the off-board package is equivalent to applying external loads to the package	Qu	INFRNG/NON-INFRNG	Admitted
CX	672	C	Dr. Qu Report Figure XIII.30 – Accumulated Plastic Work due to External Forces for SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	673	C	Dr. Qu Report Figure XIII.31 – Accumulated Plastic Work due to External Forces for SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CX	674	C	Dr. Qu Report Figure XIII.32 – Accumulated Plastic Work due to External Forces for SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	675	C	Dr. Qu Report Figure XIII.33 – Accumulated Plastic Work due to External Forces for SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CX	676	C	Dr. Qu Report Figure XIII.34 – Accumulated Plastic Work due to External Forces for SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CX	677	C	Dr. Qu Report Figure XIII.35 – Accumulated Plastic Work due to External Forces for SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	678	C	Dr. Qu Report Figure XIII.36 – Accumulated Plastic Work due to External Forces for SPA-S-SFS	Qu	INFRNG/NON-INFRNG	Admitted
CX	679	C	Dr. Qu Report Figure XIII.37 – Accumulated Plastic Work due to External Forces for STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	680	C	Dr. Qu Report Figure XIII.38 – Accumulated Plastic Work due to External Forces for STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CX	681	C	Dr. Qu Report Figure XIII.39 – Accumulated Plastic Work due to External Forces for STM-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	682	C	Dr. Qu Report Figure XIII.4 – Accumulated Plastic Work due to External Forces for ATI-M-S-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	683	C	Dr. Qu Report Figure XIII.40 – Accumulated Plastic Work due to External Forces for STM-M-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	684	C	Intentionally Left Blank	Qu	INFRNG/NON-INFRNG	Admitted
CX	685	C	Dr. Qu Report Figure XIII.41 – Accumulated Plastic Work due to External Forces for STM-M-HCS-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	686	C	Dr. Qu Report Figure XIII.42 – Accumulated Plastic Work due to External Forces for STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CX	687	C	Dr. Qu Report Figure XIII.43 – Accumulated Plastic Work due to External Forces for STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	688	C	Dr. Qu Report Figure XIII.44 – Accumulated Plastic Work due to External Forces for STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	689	C	Dr. Qu Report Figure XIII.45 – Accumulated Plastic Work due to External Forces for STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	690	C	Dr. Qu Report Figure XIII.46 – Accumulated Plastic Work due to External Forces for STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	691	C	Dr. Qu Report Figure XIII.47 – Accumulated Plastic Work due to External Forces for STM-S-Moire	Qu	INFRNG/NON-INFRNG	Admitted
CX	692	C	Dr. Qu Report Figure XIII.5 – Accumulated Plastic Work due to External Forces for ATI-M-S-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	693	C	Dr. Qu Report Figure XIII.6 – Accumulated Plastic Work due to External Forces for ATI-M-S-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	694	C	Dr. Qu Report Figure XIII.7 – Accumulated Plastic Work due to External Forces for ATI-S-H-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	695	C	Dr. Qu Report Figure XIII.8 – Accumulated Plastic Work due to External Forces for ATI-S-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	696	C	Dr. Qu Report Figure XIII.9 – Accumulated Plastic Work due to External Forces for ATI-S-H-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	697					Withdrawn
CX	698					Withdrawn
CX	699					Withdrawn
CX	700					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	701					Withdrawn
CX	702					Withdrawn
CX	703					Withdrawn
CX	704					Withdrawn
CX	705					Withdrawn
CX	706					Withdrawn
CX	707					Withdrawn
CX	708					Withdrawn
CX	709					Withdrawn
CX	710					Withdrawn
CX	711					Withdrawn
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CX	718					Withdrawn
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CX	720					Withdrawn
CX	721					Withdrawn
CX	722					Withdrawn
CX	723					Withdrawn
CX	724					Withdrawn
CX	725					Withdrawn
CX	726					Withdrawn
CX	727					Withdrawn
CX	728					Withdrawn
CX	729					Withdrawn
CX	730					Withdrawn
CX	731					Withdrawn
CX	732					Withdrawn
CX	733					Withdrawn
CX	734					Withdrawn
CX	735					Withdrawn
CX	736	C	Dr. Qu Report Figure XIV.45 – Compression due to external forces in ATI-M-S-1	QU	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	737	C	Dr. Qu Report Figure XIV.46 – Compression due to external forces in ATI-M-S-2	QU	INFRNG/NON-INFRNG	Admitted
CX	738	C	Dr. Qu Report Figure XIV.47 – Compression due to external forces in ATI-M-S-3	QU	INFRNG/NON-INFRNG	Admitted
CX	739	C	Dr. Qu Report Figure XIV.48 – Compression due to external forces in ATI-S-H-1	QU	INFRNG/NON-INFRNG	Admitted
CX	740	C	Dr. Qu Report Figure XIV.49 – Compression due to external forces in ATI-S-H-2	QU	INFRNG/NON-INFRNG	Admitted
CX	741	C	Dr. Qu Report Figure XIV.5 – Deformation of the compliant layer from 125C to -25C for ATI-S-H-2	QU	INFRNG/NON-INFRNG	Admitted
CX	742	C	Dr. Qu Report Figure XIV.50 – Compression due to external forces in ATI-S-H-3	QU	INFRNG/NON-INFRNG	Admitted
CX	743	C	Dr. Qu Report Figure XIV.51 – Compression due to external forces in ATI-S-S	QU	INFRNG/NON-INFRNG	Admitted
CX	744	C	Dr. Qu Report Figure XIV.52 – Compression due to external forces in FRE-S-HCB	QU	INFRNG/NON-INFRNG	Admitted
CX	745	C	Dr. Qu Report Figure XIV.53 – Compression due to external forces in FRE-S-HFB	QU	INFRNG/NON-INFRNG	Admitted
CX	746	C	Dr. Qu Report Figure XIV.54 – Compression due to external forces in FRE-S-HFT	QU	INFRNG/NON-INFRNG	Admitted
CX	747	C	Dr. Qu Report Figure XIV.55 – Compression due to external forces in FRE-S-SCB-1	QU	INFRNG/NON-INFRNG	Admitted
CX	748	C	Dr. Qu Report Figure XIV.56 – Compression due to external forces in FRE-S-SCB-2	QU	INFRNG/NON-INFRNG	Admitted
CX	749	C	Dr. Qu Report Figure XIV.57 – Compression due to external forces in FRE-S-SFB-1	QU	INFRNG/NON-INFRNG	Admitted
CX	750	C	Dr. Qu Report Figure XIV.58 – Compression due to external forces in FRE-S-SFB-2	QU	INFRNG/NON-INFRNG	Admitted
CX	751	C	Dr. Qu Report Figure XIV.59 – Compression due to external forces in FRE-S-SFT	QU	INFRNG/NON-INFRNG	Admitted
CX	752	C	Dr. Qu Report Figure XIV.6 – Deformation of the compliant layer from 125C to -25C for ATI-S-H-3	QU	INFRNG/NON-INFRNG	Admitted
CX	753	C	Dr. Qu Report Figure XIV.60 – Compression due to external forces in QUA-M-H-1	QU	INFRNG/NON-INFRNG	Admitted
CX	754	C	Dr. Qu Report Figure XIV.61 – Compression due to external forces in QUA-M-H-2-A	QU	INFRNG/NON-INFRNG	Admitted
CX	755	C	Dr. Qu Report Figure XIV.62 – Compression due to external forces in QUA-M-H-2-B	QU	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	756	C	Dr. Qu Report Figure XIV.63 – Compression due to external forces in QUA-M-SCB-A	QU	INFRNG/NON-INFRNG	Admitted
CX	757	C	Dr. Qu Report Figure XIV.64 – Compression due to external forces in QUA-M-SCB-B	QU	INFRNG/NON-INFRNG	Admitted
CX	758	C	Dr. Qu Report Figure XIV.65 – Compression due to external forces in QUA-S-HFB	QU	INFRNG/NON-INFRNG	Admitted
CX	759	C	Dr. Qu Report Figure XIV.66 – Compression due to external forces in QUA-S-HFT-1	QU	INFRNG/NON-INFRNG	Admitted
CX	760	C	Dr. Qu Report Figure XIV.67 – Compression due to external forces in QUA-S-HFT-2	QU	INFRNG/NON-INFRNG	Admitted
CX	761	C	Dr. Qu Report Figure XIV.68 – Compression due to external forces in QUA-S-SFT	QU	INFRNG/NON-INFRNG	Admitted
CX	762	C	Dr. Qu Report Figure XIV.69 – Compression due to external forces in SPA-M-H-1	QU	INFRNG/NON-INFRNG	Admitted
CX	763	C	Dr. Qu Report Figure XIV.7 – Deformation of the compliant layer from 125C to -25C for ATI-S-S	Qu	INFRNG/NON-INFRNG	Admitted
CX	764	C	Dr. Qu Report Figure XIV.70 – Compression due to external forces in SPA-M-H-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	765	C	Dr. Qu Report Figure XIV.71 – Compression due to external forces in SPA-M-SCB	Qu	INFRNG/NON-INFRNG	Admitted
CX	766	C	Dr. Qu Report Figure XIV.72 – Compression due to external forces in SPA-M-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CX	767	C	Dr. Qu Report Figure XIV.73 – Compression due to external forces in SPA-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	768	C	Dr. Qu Report Figure XIV.74 – Compression due to external forces in SPA-S-H	Qu	INFRNG/NON-INFRNG	Admitted
CX	769	C	Dr. Qu Report Figure XIV.75 – Compression due to external forces in SPA-S-SCT	Qu	INFRNG/NON-INFRNG	Admitted
CX	770	C	Dr. Qu Report Figure XIV.76 – Compression due to external forces in SPA-S-SFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	771	C	Dr. Qu Report Figure XIV.77– Compression due to external forces in SPA-S-SFT	Qu	INFRNG/NON-INFRNG	Admitted
CX	772	C	Dr. Qu Report Figure XIV.78 – Compression due to external forces in STM-M-HF	Qu	INFRNG/NON-INFRNG	Admitted
CX	773	C	Dr. Qu Report Figure XIV.79 – Compression due to external forces in STM-M-SC	Qu	INFRNG/NON-INFRNG	Admitted
CX	774	C	Dr. Qu Report Figure XIV.8 – Deformation of the compliant layer from 125C to -25C for FRE-S-HCB	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	775	C	Dr. Qu Report Figure XIV.80 – Compression due to external forces in STM-M-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	776	C	Dr. Qu Report Figure XIV.81 – Compression due to external forces in STM-S-HCB-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	777	C	Dr. Qu Report Figure XIV.82 – Compression due to external forces in STM-S-HCB-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	778	C	Dr. Qu Report Figure XIV.83 – Compression due to external forces in STM-S-HCS	Qu	INFRNG/NON-INFRNG	Admitted
CX	779	C	Dr. Qu Report Figure XIV.84 – Compression due to external forces in STM-S-HFB	Qu	INFRNG/NON-INFRNG	Admitted
CX	780	C	Dr. Qu Report Figure XIV.85 – Compression due to external forces in STM-S-HFS-1	Qu	INFRNG/NON-INFRNG	Admitted
CX	781	C	Dr. Qu Report Figure XIV.86 – Compression due to external forces in STM-S-HFS-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	782	C	Dr. Qu Report Figure XIV.87 – Compression due to external forces in STM-S-SF	Qu	INFRNG/NON-INFRNG	Admitted
CX	783					Withdrawn
CX	784					Withdrawn
CX	785					Withdrawn
CX	786					Withdrawn
CX	787					Withdrawn
CX	788					Withdrawn
CX	789					Withdrawn
CX	790					Withdrawn
CX	791					Withdrawn
CX	792					Withdrawn
CX	793					Withdrawn
CX	794					Withdrawn
CX	795					Withdrawn
CX	796					Withdrawn
CX	797					Withdrawn
CX	798					Withdrawn
CX	799	C	Technical design document	Qu	Infrng/Non-infrng	Admitted
CX	800					Withdrawn
CX	801					Withdrawn
CX	802					Withdrawn
CX	803		http://www.freescale.com/webapp/sps/site/homepage.jsp?nodeId=06		Importation, Remedies	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	804		http://www.freescale.com/webapp/sps/site/overview.jsp?nodeID=060A60		Importation, Remedies	Admitted
CX	805					Withdrawn
CX	806					Withdrawn
CX	807					Withdrawn
CX	808	C	Motorola's Third Amended Responses to Tessera's First Set of Interrogatories with Appendices	Qu	Infrng/Non-infrng	Admitted
CX	809	C	ST-NV's First Amended Response to Tessera's First Set of Interrogatories with Appendices	Qu	Infrng/Non-infrng	Admitted
CX	810	C	ST-NV's Response to Tessera's Seventh Set of Interrogatories	Qu	Infrng/Non-infrng	Admitted
CX	811	C	Tessera's First Set of Interrogatories to ST-NV	Qu	Infrng/Non-infrng	Admitted
CX	812	C	Tessera's Objections and Responses to Qualcomm's First Set of Interrogatories	Schaper	VLD/INVLD	Admitted
CX	813	C	Bonding Diagrams	Qu	Infrng/Non-infrng	Admitted
CX	814					Withdrawn
CX	815	C	Qualcomm, "280 CSP Board Level Characterization Plan/Report", 09.11.2002	Qu	INFRNG/NON-INFRNG	Admitted
CX	816					Withdrawn
CX	817					Withdrawn
CX	818	C	AMD FBGA User's Guide, Version 2.3.1	Qu	INFRNG/NON-INFRNG	Admitted
CX	819	C	AMD Paper: "Characterization of a Novel Fine-pitch Ball Grid Array Package for Flash Memory Application" by Sidharth, et al.; Electronics Component and Technology Conference	Qu	INFRNG/NON-INFRNG	Admitted
CX	820	C	AMD Paper: "Reliability Evaluation of Chip Scale Packages" by Gannamani, et al.	Qu	INFRNG/NON-INFRNG	Admitted
CX	821	C	Wire Bond Diagrams	Qu	INFRNG/NON-INFRNG	Admitted
CX	822	C	AMD FBGA User's Guide, Ch. 4, Board Design and Layout Considerations	Qu	INFRNG/NON-INFRNG	Admitted
CX	823					Withdrawn
CX	824		"Design Analysis of TFBGA with Customized Solder Joint Fatigue Model," T. Lee, M. Lim etc.	Qu	Infrng/Non-infrng	Admitted
CX	825					Withdrawn
CX	826					Withdrawn
CX	827					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	828					Withdrawn
CX	829					Withdrawn
CX	830	C	Qualcomm's Responses to Tessera's Interrogatory No. 6 with Appendices	Stipulation	Infrng/Non-infrng	Admitted
CX	831	C	Qualcomm's Supplemental Response to Tessera's Interrogatory No. 6 with Appendices	Stipulation	Infrng/Non-infrng	Admitted
CX	832					Withdrawn
CX	833	C	Amkor Drawings related to Customer Device W2240A	Qu	Infrng/Non-infrng	Admitted
CX	834	C	Amkor Drawings related to Customer Device W2240A	Qu	Infrng/Non-infrng	Admitted
CX	835	C	AT Bonding Diagram for Customer Device W2240A	Qu	Infrng/Non-infrng	Admitted
CX	836	C	ATI Diagram related to W2240G	Qu	Infrng/Non-infrng	Admitted
CX	837	C	ATI Diagram related to W2240G	Qu	Infrng/Non-infrng	Admitted
CX	838	C	ATI Diagrams for Customer Device Name: W2240G(B11)	Qu	Infrng/Non-infrng	Admitted
CX	839	C	ATI Drawings for Customer Device Name: W2240G(B12)	Qu	Infrng/Non-infrng	Admitted
CX	840	C	ATI Package Outline Drawing	Qu	Infrng/Non-infrng	Admitted
CX	841	C	ATI Package Outline Drawing	Qu	Infrng/Non-infrng	Admitted
CX	842	C	ATI Substrate Design for 104L TFBGA (8x8 MM)	Qu	Infrng/Non-infrng	Admitted
CX	843	C	ATI Substrate Design for 104L TFBGA (8x8 MM)	Qu	Infrng/Non-infrng	Admitted
CX	844	C	ATI Substrate Design for 179L TFBGA (10x10 MM) for Device Name W2240G(B11)	Qu	Infrng/Non-infrng	Admitted
CX	845	C	ATI Wire Bond Diagram for Customer Device W2240G(B11)	Qu	Infrng/Non-infrng	Admitted
CX	846	C	Bonding Diagram for Customer Device W2240A	Qu	Infrng/Non-infrng	Admitted
CX	847	C	Bonding Diagram for Customer Device W2240A	Qu	Infrng/Non-infrng	Admitted
CX	848	C	Bonding Diagram for Customer Device W2240A	Qu	Infrng/Non-infrng	Admitted
CX	849	C	Bonding Diagrams for W2240A	Qu	Infrng/Non-infrng	Admitted
CX	850	C	Bonding Diagrams for W2240A	Qu	Infrng/Non-infrng	Admitted
CX	851					Withdrawn
CX	852					Withdrawn
CX	853					Withdrawn
CX	854					Withdrawn
CX	855					Withdrawn
CX	856					Withdrawn
CX	857					Withdrawn
CX	858	C	Package Outline Drawing for TFBGA, 10x10, Drawing No. 002153L	Qu	Infrng/Non-infrng	Admitted
CX	859	C	Reliability Test Report for Qualifcation Test of LFBGA (12x12) 272L	Qu	Infrng/Non-infrng	Admitted

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CX	860	C	Reliability Test Report for Qualification Test of TFBGA (8x) 104L	Qu	Infrng/Non-infrng	Admitted
CX	861	C	SPIL All Wires Drawing for W2284J	Qu	Infrng/Non-infrng	Admitted
CX	862	C	SPIL Drawing for W2288J	Qu	Infrng/Non-infrng	Admitted
CX	863					Withdrawn
CX	864	C	SPIL Drawing for W2288J	Qu	Infrng/Non-infrng	Admitted
CX	865	C	STATSChipPAC Assembly Report for ATI 215W2240BPB12NG	Qu	Infrng/Non-infrng	Admitted
CX	866	C	STATSChipPAC Bonding Diagram for Customer Device Name: W2240A	Qu	Infrng/Non-infrng	Admitted
CX	867	C	STATSChipPAC Drawing Number 010081Adrd for Customer Device W2240A	Qu	Infrng/Non-infrng	Admitted
CX	868	C	STATSChipPAC Drawings for Device Name: W2240A	Qu	Infrng/Non-infrng	Admitted
CX	869	C	Substrate Design 104L TFBGA (8x MM) for Customer Device Name W2240A	Qu	Infrng/Non-infrng	Admitted
CX	870	C	Substrate Design 104L TFBGA (8x MM) for Customer Device Name W2240A	Qu	Infrng/Non-infrng	Admitted
CX	871	C	98ARE10502D	Qu	INFRNG/NON-INFRNG	Admitted
CX	872	C	98ARE10525D	Qu	Infrng/Non-infrng	Admitted
CX	873	C	98ARE10527D	Qu	Infrng/Non-infrng	Admitted
CX	874					Withdrawn
CX	875					Withdrawn
CX	876	C	Freescale's Amended Appendix A and B to Tessera's Interrogatory No. 6	Qu	Infrng/Non-infrng	Admitted
CX	877	C	409 CSP Package Secification	Qu	Infrng/Non-infrng	Admitted
CX	878	C	Ablestik Pilot Technical Datasheet for Ablebond 2300 Electrically Conductive Adhesive for PBGA	Qu	Infrng/Non-infrng	Admitted
CX	879	C	Ablestik Technical Datasheet for Ablebond 2000, Electrically Conductive Adhesive for PBGA	Qu	Infrng/Non-infrng	Admitted
CX	880	C	Assembly Material Set, MSM6500, 409CSP	Qu	Infrng/Non-infrng	Admitted
CX	881	C	Assembly Material Sets	Qu	Infrng/Non-infrng	Admitted
CX	882	C	Marking Diagram/Assembly Material Set for Digital Die	Qu	Infrng/Non-infrng	Admitted
CX	883	C	Marking Diagram/Assembly Material Set for MSM6000	Qu	Infrng/Non-infrng	Admitted
CX	884	C	Marking Diagram/Assembly Material Set for Material Die	Qu	Infrng/Non-infrng	Admitted
CX	885	C	Marking Diagram/Assembly Material Sets	Qu	Infrng/Non-infrng	Admitted
CX	886					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	887					Withdrawn
CX	888					Withdrawn
CX	889					Withdrawn
CX	890	C	Package Specifications	Qu	Infrng/Non-infrng	Admitted
CX	891	C	Package Specifications	Qu	Infrng/Non-infrng	Admitted
CX	892	C	Qualcomm BGA Package User Guide, 80-V2560-1 Rev. R	Qu	Infrng/Non-infrng	Admitted
CX	893	C	Supplier Substrate Drawings	Qu	Infrng/Non-infrng	Admitted
CX	894	C	Supplier Substrate Drawings	Qu	Infrng/Non-infrng	Admitted
CX	895					Withdrawn
CX	896					Withdrawn
CX	897					Withdrawn
CX	898					Withdrawn
CX	899					Withdrawn
CX	900					Withdrawn
CX	901					Withdrawn
CX	902					Withdrawn
CX	903	C	Reliabililty Qualification re LSC080	Qu	Infrng/Non-infrng	Admitted
CX	904	C	Reliability Qualification re LSA064	Qu	Infrng/Non-infrng	Admitted
CX	905	C	Reliability Qualification re BEA188	Qu	Infrng/Non-infrng	Admitted
CX	906	C	Reliability Qualification re FBC048	Qu	Infrng/Non-infrng	Admitted
CX	907					Withdrawn
CX	908					Withdrawn
CX	909	C	Reliability Qualification re Package VDE044	Qu	Infrng/Non-infrng	Admitted
CX	910	C	Reliability Qualification re VDE044	Qu	Infrng/Non-infrng	Admitted
CX	911	C	Spec F04-0027131 Henkel-QMI 546	Qu	Infrng/Non-infrng	Admitted
CX	912	C	Spec F04-0027803 Rev. A Hitachi Chemical HS-231 W Insulated Film Die Attach Adhesive	Qu	Infrng/Non-infrng	Admitted
CX	913	C	Spec F04-0028082 Rev. B Hitachi Chemical HS232 Insulated Film Die Attach Adhesive	Qu	Infrng/Non-infrng	Admitted
CX	914	C	Spec F04-0029734 Rev. A Hitachi Chemical FH-900T-20 Tape	Qu	Infrng/Non-infrng	Admitted
CX	915	C	Technical Drawing re Package BEA188	Qu	Infrng/Non-infrng	Admitted
CX	916	C	Technical Drawings re 64 Ball LBGA	Qu	Infrng/Non-infrng	Admitted
CX	917	C	Technical Drawings re BEA188	Qu	Infrng/Non-infrng	Admitted
CX	918	C	Technical Drawings re FBC048	Qu	Infrng/Non-infrng	Admitted
CX	919	C	Technical Drawings re FBC048	Qu	Infrng/Non-infrng	Admitted
CX	920	C	Technical Drawings re FBC048	Qu	Infrng/Non-infrng	Admitted
CX	921					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	922					Withdrawn
CX	923	C	Technical Drawings re LAA080	Qu	Infrng/Non-infrng	Admitted
CX	924	C	Technical Drawings re LSC080 Package 27828	Qu	Infrng/Non-infrng	Admitted
CX	925	C	Technical Drawings re Package 188 Ball FBGA	Qu	Infrng/Non-infrng	Admitted
CX	926	C	Technical Drawings re Package FBC048	Qu	Infrng/Non-infrng	Admitted
CX	927	C	Technical Drawings re Package LSA064	Qu	Infrng/Non-infrng	Admitted
CX	928	C	Technical Drawings re Package LSA064	Qu	Infrng/Non-infrng	Admitted
CX	929	C	Technical Drawings re Package LSC080	Qu	Infrng/Non-infrng	Admitted
CX	930	C	Technical Drawings re Section 4.1: LRBGA-R Package LSA064	Qu	Infrng/Non-infrng	Admitted
CX	931	C	Technical Drawings re Section 4.1: LRBGA-R Package LSC080	Qu	Infrng/Non-infrng	Admitted
CX	932	C	Technical Drawings re Section 4.1: LBGA Packages	Qu	Infrng/Non-infrng	Admitted
CX	933	C	Technical Drawings re VDE044	Qu	Infrng/Non-infrng	Admitted
CX	934	C	Technical Drawings re VDE044	Qu	Infrng/Non-infrng	Admitted
CX	935	C	Technical Drawings re VDE044	Qu	Infrng/Non-infrng	Admitted
CX	936	C	Technical Drawings re VDE044	Qu	Infrng/Non-infrng	Admitted
CX	937	C	Technical Drawings for Various Packages	Qu	Infrng/Non-infrng	Admitted
CX	938	C	Ablestik Pilot Technical Datasheet for Ablebond 2025D High Performance Adhesive for Array Packaging	Qu	Infrng/Non-infrng	Admitted
CX	939	C	Ablestik Pilot Technical Datasheet for Ablebond 2300 Electrically Conductive Adhesive for PBGA	Qu	Infrng/Non-infrng	Admitted
CX	940	C	98ASE19645D	Qu	Infrng/Non-infrng	Admitted
CX	941	C	Spansion's Amended Appendix A and B to Tessera's Interrogatory No. 6	Qu	Infrng/Non-infrng	Admitted
CX	942	C	Documents relating to ATI Representative Products	Qu	Infrng/Non-infrng	Admitted
CX	943	C	Documents relating to ATI Representative Products	Qu	Infrng/Non-infrng	Admitted
CX	944	C	Documents relating to ATI Representative Products	Qu	Infrng/Non-infrng	Admitted
CX	945	C	Documents relating to ATI Representative Products	Qu	Infrng/Non-infrng	Admitted
CX	946	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	947	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	948	C	Documents relating to Freescale Representative Products	Qu	Infrng/Non-infrng	Admitted
CX	949		Documents relating to Freescale Representative Products	Mawer	INFRNG/NON-INFRNG	Admitted
CX	950	C	Documents relating to Freescale Representative Products	Qu	Infrng/Non-infrng	Admitted

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CX	951		Documents relating to Freescale Representative Products	Mawer	INFRNG/NON-INFRNG	Admitted
CX	952	C	Documents relating to Freescale Representative Products	Qu	Infrng/Non-infrng	Admitted
CX	953	C	Documents relating to Freescale Representative Products	Qu	Infrng/Non-infrng	Admitted
CX	954	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	955	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	956	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	957	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	958					Withdrawn
CX	959					Withdrawn
CX	960					Withdrawn
CX	961					Withdrawn
CX	962	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	963	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	964	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	965	C	Documents relating to Moire Testing	Qu	Infrng/Non-infrng	Admitted
CX	966		Balog Deposition Exhibit #002, Tessera's Notice of Deposition of Motorola, Inc.	Balog	RMDY	Admitted
CX	967	C	Balog Deposition Exhibit #003, Tessera's Notice of Deposition of Motorola, Inc., of December 21, 2007	Balog	RMDY	Admitted
CX	968	C	Balog Deposition Exhibit #004, Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Complainant Tessera's First Set of Interrogatories (1-5)	Balog	RMDY	Admitted
CX	969	C	Balog Deposition Exhibit #005, Verification	Balog	RMDY	Admitted
CX	970	C	Balog Deposition Exhibit #006, Respondent Motorola Inc.'s Responses to Complainant Tessera's Amended Fifth Set of Interrogatories (32-79)	Balog	Infrng/Non-infrng, Importation, Remedies	Admitted
CX	971	C	Balog Deposition Exhibit #007, Motorola chart of semiconductor parts	Balog	RMDY	Admitted
CX	972	C	Balog Deposition Exhibit #008, Chart with shipping information from one of Motorola's suppliers	Balog	RMDY	Admitted
CX	973					Withdrawn
CX	974	C	Balog Deposition Exhibit #010, PCNs chart	Balog	RMDY	Admitted
CX	975	C	Balog Deposition Exhibit #011, Component Review Report	Balog	RMDY	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	976	C	Balog Deposition Exhibit #012, Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Complainant Tessera's First Set of Interrogatories (#6-20)	Balog	RMDY	Admitted
CX	977					Withdrawn
CX	978	C	Balog Deposition Exhibit #015, Excel spreadsheet from Motorola's Enterprise Mobility group and sales information of their respective products from Jan. 1-Nov. 30 2007	Balog	RMDY	Admitted
CX	979		Balog Deposition Exhibit #1, Tessera's Notice of Deposition of Motorola, Inc.	Balog	RMDY	Admitted
CX	980					Withdrawn
CX	981					Withdrawn
CX	982					Withdrawn
CX	983					Withdrawn
CX	984					Withdrawn
CX	985					Withdrawn
CX	986					Withdrawn
CX	987	C	Bradley Deposition Exhibit #007, List of components and their purchase price	Bradley	INFRNG/NON-INFRNG	Admitted
CX	988					Withdrawn
CX	989					Withdrawn
CX	990	C	Bradley Deposition Exhibit #010, CTE Component Report for 5170200A58	Bradley	INFRNG/NON-INFRNG	Admitted
CX	991	C	Bradley Deposition Exhibit #011, Chart: Investigation 337-TA-605	Bradley	INFRNG/NON-INFRNG	Admitted
CX	992					Withdrawn
CX	993					Withdrawn
CX	994					Withdrawn
CX	995					Withdrawn
CX	996					Withdrawn
CX	997	C	Brda Deposition Exhibit #002, Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Complainant Tessera's First Set of Interrogatories (1-5)	Brda	RMDY	Admitted
CX	998	C	Brda Deposition Exhibit #004, Document entitled "Mobile Devices- All Products"	Brda	RMDY	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	999		Brda Deposition Exhibit #005, Respondent Motorola, Inc.'s Response to Complainant Tessera's Amended Firfth Set of Interrogatories (32-79)	Brda	RMDY	Admitted
CX	1000	C	Brda Deposition Exhibit #006, Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Complainant Tessera's Second Set of Interrogatories (6-29)	Brda	Infrng/Non-infrng, Importation, Remedies	Admitted
CX	1001		Brown Deposition Exhibit #001, Tessera's Notice of Deposition of Motorola, Inc.	Brown	INFRNG/NON-INFRNG	Admitted
CX	1002		Brown Deposition Exhibit #002, Complaintant Tessera's First Set of Interrogatories (1-5) to Respondent Motorola, Inc.	Brown	INFRNG/NON-INFRNG	Admitted
CX	1003		Brown Deposition Exhibit #003, Complaintant Tessera's Second Set of Interrogatories (6-20) to Respondent Motorola, Inc.	Brown	INFRNG/NON-INFRNG	Admitted
CX	1004	C	Brown Deposition Exhibit #004, Respondent Motorola, Inc.'s Second Amended Confidential Responses and Objections to Complainant Tessera's First Set of Interrogatories (1-5)	Brown	Infrng/Non-infrng	Admitted
CX	1005	C	Brown Deposition Exhibit #005, Respondent Motorola, Inc.'s Second Amended Confidential Responses and Objections to Complainant Tessera's Second Set of Interrogatories (6-20)	Brown	Infrng/Non-infrng	Admitted
CX	1006		Brown Deposition Exhibit #006, Motorola Product Page from the Motorola U.S. Website	Brown	INFRNG/NON-INFRNG	Admitted
CX	1007	C	Brown Deposition Exhibit #007, Atlas Ultra-Lite Preliminary Detailed Technical Specification Rev 2.3	Brown	INFRNG/NON-INFRNG	Admitted
CX	1008	C	Brown Deposition Exhibit #008, M36LOR8060T1, M36L0R8060B1 Multi-Chip Package Technical Specification	Brown	INFRNG/NON-INFRNG	Admitted
CX	1009	C	Brown Deposition Exhibit #009, Motorola Material or Method Specification No. 51R99190J01	Qu	INFRNG/NON-INFRNG	Admitted
CX	1010	C	Brown Deposition Exhibit #010, Motorola Material or Methods Specification No. 51R85353D38 Javelin IC	Brown	INFRNG/NON-INFRNG	Admitted
CX	1011	C	Brown Deposition Exhibit #011, Motorola Atlas UL Mechanical Strength Characterization Multiple Hit to Failure by Mat Brown	Brown	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1012	C	Brown Deposition Exhibit #012, J0201 Update Presentation by Tony Gallagher of Libertyville (MOT/TES 001596-001627) and BGA Mechanical Reliability Design Process by Matt Brown and Tony Galagher (MOT/TES 001628-001651)	Brown	INFRNG/NON-INFRNG	Admitted
CX	1013	C	Brown Deposition Exhibit #013, Motorola Material or Methods Specification No. 62G13933D51 Specification Template for Integrated Circuits	Brown	INFRNG/NON-INFRNG	Admitted
CX	1014	C	Brown Deposition Exhibit #014, Motorola Material or Methods Specification No. 12G02897W18 Controlled and Reportable Materials Disclosure	Brown	INFRNG/NON-INFRNG	Admitted
CX	1015	C	Brown Deposition Exhibit #015, Motorola Material or Methods Specification No. 71M70269A30 IC Design Requirements and Recommendations for Manufacturing (BGA and LGA devices)	Qu	INFRNG/NON-INFRNG	Admitted
CX	1016	C	Brown Deposition Exhibit #016, Motorola Material or Methods Specification No. 12M09195A97 Dynamic 4-Point Bend Test: BGA & LGA	Brown	INFRNG/NON-INFRNG	Admitted
CX	1017	C	Brown Deposition Exhibit #017, Motorola Specification No. 71G13933J03 Component Padstack Specification	Brown	INFRNG/NON-INFRNG	Admitted
CX	1018	C	Brown Deposition Exhibit #018, Motorola Materials or Methods Specification No. 51R999190J02	Brown	INFRNG/NON-INFRNG	Admitted
CX	1019	C	Brown Deposition Exhibit #019, Motorola Materials or Methods Specification No. 51R85941F60	Qu	Infrng/Non-infrng	Admitted
CX	1020		Brown II Deposition Exhibit #001, Tessera's Notice of Deposition of Motorola, Inc.	Brown	INFRNG/NON-INFRNG	Admitted
CX	1021	C	Brown II Deposition Exhibit #002, Respondent Motorola, Inc.'s Second Amended Confidential Responses and Objections to Complainant Tessera's First Set of Interrogatories (1-5)	Brown	INFRNG/NON-INFRNG	Admitted
CX	1022	C	Brown II Deposition Exhibit #003, Document CIMT-570: Physical Symbol Specification for Master Component Library CDS Engineering Design Automation	Brown	INFRNG/NON-INFRNG	Admitted
CX	1023	C	Brown II Deposition Exhibit #004, Master Component Library Geometry Specification 71G13933j21	Brown	INFRNG/NON-INFRNG	Admitted
CX	1024	C	Brown II Deposition Exhibit #005, NPI Dashboard Mobile Devices Search Results	Brown	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1025	C	Brown II Deposition Exhibit #006, Document entitled "Multi Phys Table"	Brown	INFRNG/NON-INFRNG	Admitted
CX	1026	C	Brown II Deposition Exhibit #007, Email from David Patten to Anthony Gallagher and Mark Guilford re Questions on LTE2 Daisy Chains from STATS	Brown	INFRNG/NON-INFRNG	Admitted
CX	1027	C	Brown II Deposition Exhibit #008, Motorola Material or Methods Specification, File: Qualification Procedure for Integrated Circuits	Brown	INFRNG/NON-INFRNG	Admitted
CX	1028	C	Brown II Deposition Exhibit #009, Freescale Sphere Shorting on Argon PoP 15X15 Warpage Evaluation & Optimization Plan, Version 1	Brown	INFRNG/NON-INFRNG	Admitted
CX	1029	C	Brown II Deposition Exhibit #010, Motorola PCS: BGA Reliability	Qu	INFRNG/NON-INFRNG	Admitted
CX	1030	C	Brown II Deposition Exhibit #011, Technical Paper: Reliability Considerations of Electrically Conductive Adhesives by Darryl J. Small (Loctite Corporation)	Brown	INFRNG/NON-INFRNG	Admitted
CX	1031	C	Brown II Deposition Exhibit #012, Indium's SAC-X Solder Alloy Mechanical Reliability Study by Matthew Brown	Brown	INFRNG/NON-INFRNG	Admitted
CX	1032	C	Brown II Deposition Exhibit #013, Introduction of a Few Optical Measurement Methods by YinYan Want (Motorola Labs MATC Predictive Reliability Group)	Qu	INFRNG/NON-INFRNG	Admitted
CX	1033	C	Brown II Deposition Exhibit #014, Predictive Reliability - How We Win	Qu	INFRNG/NON-INFRNG	Admitted
CX	1034	C	Brown II Deposition Exhibit #015, Motorola Finite Element Model	Qu	INFRNG/NON-INFRNG	Admitted
CX	1035	C	Brown II Deposition Exhibit #016, Motorola Requirements for Evaluation of Advanced IC Packages	Brown	INFRNG/NON-INFRNG	Admitted
CX	1036	C	Brown II Deposition Exhibit #017, Motorola Personal Communications Sector CTE-Materials & Failure Analysis Laboratory	Brown	INFRNG/NON-INFRNG	Admitted
CX	1037	C	Brown II Deposition Exhibit #018, Multi-Packaging Solutions for Portable Applications	Brown	INFRNG/NON-INFRNG	Admitted
CX	1038	C	Brown II Deposition Exhibit #019, Multi-Packaging Technology Update	Brown	INFRNG/NON-INFRNG	Admitted
CX	1039		Chopin Deposition Exhibit #001, Tessera's Notice of Deposition of Freescale Semiconductor	Chopin	OWNR, INFRNG/NON-INFRNG.	Admitted

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CX	1040	C	Chopin Deposition Exhibit #002, E-mail to T. David et al from S. Wilson regarding Package Intrinsic Reliability	Chopin	OWNR, INFRNG/NON-INFRNG.	Admitted
CX	1041	C	Chopin Deposition Exhibit #004, Freescale Bill of Materials	Chopin	OWNR, INFRNG/NON-INFRNG.	Admitted
CX	1042	C	Chopin Deposition Exhibit #005, Sumitomo Meeting - Place Holder E-mail	Chopin	OWNR, INFRNG/NON-INFRNG.	Admitted
CX	1043					Withdrawn
CX	1044	C	Chopin Deposition Exhibit #007, Appointment e-mail regarding Ablestik's meeting with Freescale	Chopin	OWNR, INFRNG/NON-INFRNG.	Admitted
CX	1045	C	Chopin Deposition Exhibit #008, Appointment e-mail for meeting for review of material propery data	Chopin	OWNR, INFRNG/NON-INFRNG.	Admitted
CX	1046					Withdrawn
CX	1047					Withdrawn
CX	1048	C	DiStefano Deposition Exhibit #149, Confidentail photographs of Chip Packages	DiStefano	OWNR	Admitted
CX	1049	C	Foong Deposition Exhibit #002, Spansion Bill of Materials	Qu	Infrng/Non-infrng	Admitted
CX	1050					Withdrawn
CX	1051					Withdrawn
CX	1052					Withdrawn
CX	1053					Withdrawn
CX	1054					Withdrawn
CX	1055					Withdrawn
CX	1056	C	Frankel Deposition Exhibit #003, Qualcomm Presentation	Frankel	RMDY	Admitted
CX	1057					Withdrawn
CX	1058	C	Frankel Deposition Exhibit #005, Email from L. Pineda to M. Frankel	Frankel	RMDY	Admitted
CX	1059					Withdrawn
CX	1060	C	Gerfin Deposition Exhibit #002, Respondent Qualcomm Incorporated's First Supplemental Response to Complainant Tessera, Inc.'s First Set of Interrogatories to Qualcom Inc.	Gerfin	Importation, Remedies	Admitted
CX	1061	C	Gerfin Deposition Exhibit #004	Gerfin	RMDY	Admitted

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CX	1062	C	Gerfin Deposition Exhibit #005	Gerfin	RMDY	Admitted
CX	1063	C	Gerfin Deposition Exhibit #003	Gerfin	RMDY	Admitted
CX	1064	C	Gerfin Deposition Exhibit #006	Gerfin	RMDY	Admitted
CX	1065	C	Gerfin Deposition Exhibit #007	Gerfin	RMDY	Admitted
CX	1066					Withdrawn
CX	1067					Withdrawn
CX	1068					Withdrawn
CX	1069					Withdrawn
CX	1070	C	Greb Deposition Exhibit #005, Respondent Motorola, Inc.'s Third Amended Confidential Responses and Objections to Complainant Tessera's First Set of Interrogatories (1-5)	Greb	Infrng/Non-infrng, Importation, Remedies	Admitted
CX	1071	C	Greb Deposition Exhibit #006, Respondent Motorola, Inc.'s Confidential Responses and Objections to Complainant Tessera's Fourth Set of Interrogatories (31)	Greb	Infrng/Non-infrng, Importation, Remedies	Admitted
CX	1072	C	Greb Deposition Exhibit #007, Chart of Supplier Name and Part	Greb	RMDY, DI	Admitted
CX	1073	C	Greb Deposition Exhibit #008, Respondent Motorola Inc.'s Third Amended Confidential Responses and Objections to Complainant Tessera's Second Set of Interrogatories (6-20)	Greb	Infrng/Non-infrng, Importation, Remedies	Admitted
CX	1074	C	Greb Deposition Exhibit #009, Respondent Motorola, Inc.'s Responses to Complainant Tessera's Amended Fifth Set of Interrogatories (32-79)	Greb	Infrng/Non-infrng, Importation, Remedies	Admitted
CX	1075					Withdrawn
CX	1076					Withdrawn
CX	1077					Withdrawn
CX	1078					Withdrawn
CX	1079					Withdrawn
CX	1080					Withdrawn
CX	1081	C	Greb Deposition Exhibit #016, Lot Number Inventory Spreadsheet	Greb	RMDY, DI	Admitted
CX	1082	C	Greb Deposition Exhibit #017, Import Entry Data for Mobile Devices Iden Phones Chart	Greb	RMDY, DI	Admitted
CX	1083	C	Greb Deposition Exhibit #018, Import Entry Data for Mobile Devices' Products	Greb	RMDY, DI	Admitted
CX	1084	C	Greb Deposition Exhibit #019, List of Part Numbers deemed to potentially include the accused chips	Greb	RMDY, DI	Admitted

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CX	1085		Gregorich Deposition Exhibit #001, Tessera's Notice of Deposition of Qualcomm, Inc.	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	1086		Gregorich Deposition Exhibit #002, Complaintant Tessera's First Set of Interrogatories (1-5) to Respondent Qualcomm, Inc.	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	1087	C	Gregorich Deposition Exhibit #003, Respondent Qualcomm Incorporated's Second Supplemental Response to Complainant Tessera, Inc.'s First Set of Interrogatories to Qualcomm Incorporated	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	1088		Gregorich Deposition Exhibit #012, U.S. Patent No. 5,852,326 (Khandros, et al.)- Face-Up Semiconductor Chip Assembly dated 12/22/1998	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	1089		Gregorich Deposition Exhibit #013, U.S. Patent No. 6,433,419 B2 (Khandros et al.)- Face-Up Semiconductor Chip Assemblies dated 8/13/2002	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	1090	C	Gregorich Deposition Exhibit #18, Email from J. Riley to E. Reyes et al., re Micro-BGA Data	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	1091	C	Gregorich Deposition Exhibit #23, Finite Element	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	1092		Holmes Deposition Exhibit #001, Tessera's Notice of Deposition of Qualcomm	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1093					Withdrawn
CX	1094					Withdrawn
CX	1095	C	Holmes Deposition Exhibit #004, Qualcomm's Second Supplemental Response to Tessera's First Set of Interrogatories	Holmes	Infrng/Non-infrng	Admitted
CX	1096					Withdrawn
CX	1097					Withdrawn
CX	1098	C	Holmes Deposition Exhibit #008, Documents for product name MBP1600 - Document 1	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1099	C	Holmes Deposition Exhibit #009, Documents for product name MSM6280	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1100	C	Holmes Deposition Exhibit #010, Documents for product name MSM6280	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1101	C	Holmes Deposition Exhibit #011, Package Outline Drawing, 409 CSP Drawing Number NT90-V2970-1	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1102	C	Holmes Deposition Exhibit #012, Documents for product name BTS4050	Holmes	INFRNG/NON-INFRNG	Admitted

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CX	1103	C	Holmes Deposition Exhibit #013, Documents for product number MSM6025	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1104	C	Holmes Deposition Exhibit #014, Qualcomm's Response to Tessera's Fourth Set of Interrogatories	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1105	C	Holmes Deposition Exhibit #015, Qualcomm's First Supplemental Response to Tessera's Second Set of Interrogatories	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1106	C	Holmes Deposition Exhibit #016-I, Qualcomm Process Flow Chart Specification for 2-DIE Stacked CSP	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1107	C	Holmes Deposition Exhibit #016-J, Process Flow Chart Specification for Package on Package (POP) CSP	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1108	C	Holmes Deposition Exhibit #016-K, Qualcomm Process Flow Chart Specification for 3-DIE Stacked CSP	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1109	C	Holmes Deposition Exhibit #017, Qualcomm CDMA Technologies Package Outline Drawing, 409CSP, Drawing Number NT90-V2970-2	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1110	C	Holmes Deposition Exhibit #018, Qualcomm Bonding Diagram WFB4130/XXX, 289FBGA	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1111	C	Holmes Deposition Exhibit #019, Qualcomm Bonding Diagram MSM7600 (XXX) Drawing Number BL90-VB720-3	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1112					Withdrawn
CX	1113					Withdrawn
CX	1114					Withdrawn
CX	1115					Withdrawn
CX	1116					Withdrawn
CX	1117					Withdrawn
CX	1118		Homes II Deposition Exhibit #001, Tessera's Notice of Deposition of Qualcomm, Inc.	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1119	C	Homes II Deposition Exhibit #002, Documents collectively marked (Assembly Material Set, MSM6500 , 409CSP	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1120	C	Homes II Deposition Exhibit #003, Email from Thuyen Dinh re Material Data Sheet on Livelinks dated 08/11/2000	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1121					Withdrawn
CX	1122					Withdrawn

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CX	1123	C	Homes II Deposition Exhibit #006, Documents for production name 543 CSP collectively marked	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1124	C	Homes II Deposition Exhibit #007, Bill of Materials for Product MSM7200A	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1125	C	Homes II Deposition Exhibit #008, Documents collectively marked (Bonding Diagrams)	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1126	C	Homes II Deposition Exhibit #009, Bill of Materials for Product MSM6250A	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1127	C	Homes II Deposition Exhibit #010, Documents collectively marked (208 FBGA Package Specification)	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1128	C	Homes II Deposition Exhibit #011, Bill of Materials for Product MSM5105	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1129	C	Homes II Deposition Exhibit #012, Email chain beginning 10/28/2002	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1130	C	Homes II Deposition Exhibit #015, Email from Rick Horvath	Holmes	INFRNG/NON-INFRNG	Admitted
CX	1131	C	Kellar Deposition Exhibit #007, Freescale Circuit Configuration 252 I/O MAP PBGS, 21 x 21 PKG, 1.27 MM PITCH	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1132	C	Kellar Deposition Exhibit #008, Document Action Request regarding 252 STD BGA (56305/56301) .30 SAW STREET 84ARS24067W	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1133	C	Kellar Deposition Exhibit #009, Updated document request form for Document: 84ARS24067W submitted by Carol Armendariz	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1134	C	Kellar Deposition Exhibit #010, Freescale Circuit Configuration 252 I/O MAP PBGS, 21 x 21 PKG, 1.27 MM PITCH	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1135	C	Kellar Deposition Exhibit #011, ReadMe files re: part #84ARS24067W001_B and W002	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1136	C	Kellar Deposition Exhibit #012, Screen shot of directory structure	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1137	C	Kellar Deposition Exhibit #013, Document the Freescale Administration puts together before submitting something to the SAP to release it as an official part number regarding 84ARS24067W	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1138	C	Kellar Deposition Exhibit #014, Bonding Diagram Information Forms NPI, REV O for Device Name 56301	Kellar	INFRNG/NON-INFRNG	Admitted

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CX	1139	C	Kellar Deposition Exhibit #015, Wire Bond Diagram Document for the Device Name ONYX 56301_56305	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1140	C	Kellar Deposition Exhibit #016, Bonding Diagram Information Forms for Device Name ONYX 56301_56305	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1141		Kellar Deposition Exhibit #1, Tessera's First Amended Notice of Deposition of Freescale Semiconductor, Inc.	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1142		Kellar Deposition Exhibit #2, Complaintant Tessera's First Set of Interrogatories (1-5) to Respondent Freescale Semiconductor, Inc.	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1143		Kellar Deposition Exhibit #3, Complaintant Tessera's Second Set of Interrogatories (6-20) to Respondent Freescale Semiconductor, Inc.	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1144	C	Kellar Deposition Exhibit #4, Respondent Freescale Semiconductor, Inc.'s Supplemental Responses to Complainant Tesesera's First Set of Interrogatories (Nos. 1-5)	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1145	C	Kellar Deposition Exhibit #5, Respondent Freescale Semiconductor, Inc.'s Supplemental Responses to Complainant Tessera's Second Set of Interrogatories (Nos. 6-20)	Kellar	INFRNG/NON-INFRNG	Admitted
CX	1146		Leoni Deposition Exhibit #001, Tessera's Notice of Deposition of Freescale Semiconductor	Leoni	INFRNG/NON-INFRNG	Admitted
CX	1147	C	Leoni Deposition Exhibit #002, Tessera ITC Investigation No. 337-TA-605 Complaint	Leoni	INFRNG/NON-INFRNG	Admitted
CX	1147					Withdrawn
CX	1148	C	Leoni Deposition Exhibit #003, Optical Photos of Freescale SC13890P23A	Leoni	INFRNG/NON-INFRNG	Admitted
CX	1149		Leoni Deposition Exhibit #004, Tessera's First Set of Interrogatories (1-5) to Freescale	Leoni	INFRNG/NON-INFRNG	Admitted
CX	1150	C	Leoni Deposition Exhibit #005, Freescale's Supplemental Responses to Tessera's First Set of Interrogatories (1-5)	Leoni	Infrng/Non-infrng	Admitted
CX	1151					Withdrawn
CX	1152					Withdrawn
CX	1153		Mawer Deposition Exhibit #001, Tessera's Notice of Deposition of Freescale Semiconductor	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1154	C	Mawer Deposition Exhibit #002, Freescale's Supplemental Responses to Tessera's Second Set of Interrogatories (Nos. 6-20)	Mawer	INFRNG/NON-INFRNG	Admitted

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CX	1155	C	Mawer Deposition Exhibit #003, Motorola document titled,"PBGA Solder Joint Reliability Improvement Study"	Qu	INFRNG/NON-INFRNG	Admitted
CX	1156	C	Mawer Deposition Exhibit #004, Motorola Presentation titled,"BAT-1 CBGA Ball Attach Solder Paste and Ball Type Qualification Results"	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1157	C	Mawer Deposition Exhibit #005, Meeting Notification e-mail for the meeting regarding Delphi-Jupiter update	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1158	C	Mawer Deposition Exhibit #006, Meeting Notification e-mail for the meeting regarding PQ38 Pkg NPI - Carlsbad I	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1159	C	Mawer Deposition Exhibit #008, E-mail from F. Utama to C. Foong et al regarding TSO Thermal Moire with the TSO - WPSL Kuala Lumpur Material Research Laboratory Report	Qu	INFRNG/NON-INFRNG	Admitted
CX	1160	C	Mawer Deposition Exhibit #009, E-mail from T. Koschmieder to D. Wells et al regarding meeting and the HDP presenation titled,"Thermo-Electromigration in WL-CSP Pb-Free Solder Joints" by K. N. Tu	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1161	C	Mawer Deposition Exhibit #011, E-mail from M. Ding to F. Wulfert et al regarding SnAgCu => SnAg solder ball	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1162	C	Mawer Deposition Exhibit #012, E-mail from T. Koschmieder to S. Safai, A. Mawer, T. Burnette, and P. Galles regarding Python SJR results	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1163	C	Mawer Deposition Exhibit #013, E-mail from M. Tsuriya to B. Carpenter regarding GPE Japan Weekly: WW21-07	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1164	C	Mawer Deposition Exhibit #014, E-mail from V. Marquez to T. Burnette regarding APEC1. Package Code: 5253 MAPBGA 208 17*17*0.8P1.0 (lead free)	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1165	C	Mawer Deposition Exhibit #015, E-mail from T. Koschmieder to M. Tsuriya et al regarding HDP-ug: Mechanical Fatigue Test for Solder Joint Test	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1166	C	Mawer Deposition Exhibit #016, E-mail from M. Tsuriya to T. Koschmieder regarding Japan GAP - 0.4mmP BLR Test	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1167	C	Mawer Deposition Exhibit #017, E-mail from T. Koschmieder to W. Lindsay et al regarding ramblings on FC-PBGA ball size	Mawer	INFRNG/NON-INFRNG	Admitted

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CX	1168	C	Mawer Deposition Exhibit #018, E-mail from M. Tsuriya to A. Mawer et al regarding JEITA Spec: BGA Package Warpage during Reflow	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1169	C	Mawer Deposition Exhibit #019, E-mail from A. Mawer to L. Leon et el regarding Moccasin/Viper Substrate Qual Update	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1170	C	Mawer Deposition Exhibit #020, Freescale Drawing Number: 67ARE10249D for Device Name: XPC8260OZU	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1171	C	Mawer Deposition Exhibit #021, Freescale Drawing Number: 67ARE11089D for Device Name: Neptune LTE2C90	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1172					Withdrawn
CX	1173	C	Mawer Deposition Exhibit #026, E-mail from A. Mawer to W. Demarco regarding OMPAC Die Attach in Early 1990s	Mawer	INFRNG/NON-INFRNG	Admitted
CX	1174		McLellan Deposition Exhibit #001, Tessera's Notice of Deposition of ATI Technologies, Inc.	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1175		McLellan Deposition Exhibit #002, Complainant Tessera's First Set of Interrogatories (1-5) to Respondent ATI Technologies, ULC	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1176		McLellan Deposition Exhibit #003, Complainant Tessera's Second Set of Interrogatories (6-20) to Respondent ATI Technologies, ULC	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1177	C	McLellan Deposition Exhibit #004, Respondent ATI Technologies, ULC's Second Amended Responses to Tessera's First Set of Interrogatories (Nos. 1, 2, 3 and 5)	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1178	C	McLellan Deposition Exhibit #005, Respondent ATI Technologies, ULC's Second Amended Responses to Tessera's First Set of Interrogatories (Nos. 1, 2, 3 and 5)	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1179	C	McLellan Deposition Exhibit #006, Respondent ATI Technologies, ULC's Amended Responses to Tessera's Second Set of Interrogatories (No. 6, 7, 8, 10, 11, 12, 17, 19 and 20)	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1180	C	McLellan Deposition Exhibit #007, Respondent ATI Technologies, ULC's Second Amended Responses to Tessera's Second Set of Interrogatories (No. 6, 7, 8, 10, 11, 12, 17, 19 and 20)	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1181	C	McLellan Deposition Exhibit #008, Package ID W2040	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1182	C	McLellan Deposition Exhibit #009, Package ID W2250	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1183	C	McLellan Deposition Exhibit #010, Package ID W2240	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1184	C	McLellan Deposition Exhibit #011, Package ID W2282	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1185	C	McLellan Deposition Exhibit #012, Package ID W2261	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1186	C	McLellan Deposition Exhibit #013, Package ID W2182	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1187	C	McLellan Deposition Exhibit #014, Package ID W2284	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1188	C	McLellan Deposition Exhibit #015, Package ID W2262	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1189	C	McLellan Deposition Exhibit #016, BT Materials for IC Plastic Package with attachments	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1190		McLellan II Deposition Exhibit #101, Tessera's Notice of Deposition of ATI Technologies, Inc.	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1191		McLellan II Deposition Exhibit #102, Complainant {sic} Tessera's First Set of Interrogatories to Respondent ATI Technologies, Inc.	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1192	C	McLellan II Deposition Exhibit #103, Amended Appendix A	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1193	C	McLellan II Deposition Exhibit #104, Respondent ATI Technologies, ULC's Second Amended Responses to Tessera's Second Set of Interrogatories (No. 6-12, 17, 19, 20), Amended Appendix A	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1194		McLellan II Deposition Exhibit #105, U.S. Patent No. 5,852,326 (Khandros et al.)- Face-Up Semiconductor Chip Assembly	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1195		McLellan II Deposition Exhibit #106, U.S. Patent No. 6,433,419 B2 (Khandros et al.)- Face-Up Semiconductor Chip Assemblies	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1196	C	McLellan II Deposition Exhibit #107, Advanced Payment Agreement	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted

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CX	1197	C	McLellan II Deposition Exhibit #108-1, Package ID W2282	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1198	C	McLellan II Deposition Exhibit #108-2, Continuation: Package ID W2282	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1199		McLellan II Deposition Exhibit #109, Complainant {sic} Tessera's First Set of Interrogatories to Production of Documents and Things (No. 1-13) to Respondent ATI Technologies, ULC.	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1200		McLellan II Deposition Exhibit #110, Complainant {sic} tessera's Second Set of Requests for Production of Documents and Things (Nos. 4-56) to Respondent ATI Technologies, ULC,	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1201	C	McLellan II Deposition Exhibit #111, Purchase Order Terms and Conditions	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1202	C	McLellan II Deposition Exhibit #112, Chart	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1203	C	McLellan II Deposition Exhibit #113, Loctite Technical Data Sheet, Hysol QMI 546	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1204	C	McLellan II Deposition Exhibit #114, Material Safety Data Sheet	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1205					Withdrawn
CX	1206	C	McLellan II Deposition Exhibit #116, SPIL New Package/Device/Material Qualification Report	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1207	C	McLellan II Deposition Exhibit #117, Branding Diagram for MINIME 215W2240BKB12G	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1208	C	McLellan II Deposition Exhibit #118, ATI Spreadsheet of January - June 2007 Actuals for Motorola	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1209	C	McLellan II Deposition Exhibit #119, "Reliability Evaluation of Chip Sale Packages," by R. Gannamani, et al.	McLellan	INFRNG/NON-INFRNG, RMDY	Admitted
CX	1210					Withdrawn
CX	1211		McShane Deposition Exhibit #001, Tessera's Notice of Deposition of Freescale Semiconductor	McShane	INFRNG/NON-INFRNG	Admitted
CX	1212		McShane Deposition Exhibit #002, Tessera's First Set of Interrogatories (1-5) to Freescale	McShane	INFRNG/NON-INFRNG	Admitted
CX	1213	C	McShane Deposition Exhibit #004, Motorola PBGA Presentation	McShane	INFRNG/NON-INFRNG	Admitted

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CX	1214	C	McShane Deposition Exhibit #005, Freescale document titled,"Freescale Low K Expoxy Mold Compound Development Challenges & Methods"	McShane	INFRNG/NON-INFRNG	Admitted
CX	1215	C	McShane Deposition Exhibit #006, Presentation with Equations and specifications	McShane	INFRNG/NON-INFRNG	Admitted
CX	1216	C	McShane Deposition Exhibit #007, Motorola document titled,"Non-Conductive Die Attach Final Recommendation Management Summary"	McShane	INFRNG/NON-INFRNG	Admitted
CX	1217	C	McShane Deposition Exhibit #008, Ablestik presentation titled,"Curing Conditions and Bond line Thickness Effect on Warpage of Ablebond 8290" by C. Deekitwong	McShane	INFRNG/NON-INFRNG	Admitted
CX	1218	C	McShane Deposition Exhibit #009, Ablestik presentation titled,"Basic Die Attach Adhesive Properties"	McShane	INFRNG/NON-INFRNG	Admitted
CX	1219	C	McShane Deposition Exhibit #010, Sumitomo Bakelite Co. document titled,"2.2.1 Concept to achieve higher MSL performance"	McShane	INFRNG/NON-INFRNG	Admitted
CX	1220	C	McShane Deposition Exhibit #011, Tessera Presentation titled,"Multi-Die Packaging Technology Update"	McShane	INFRNG/NON-INFRNG	Admitted
CX	1221	C	McShane Deposition Exhibit #013, Motorola Presentation titled,"Tessera 46 µBGA Board-Level Thermal Cycling Data"	McShane	INFRNG/NON-INFRNG	Admitted
CX	1222		Montgomery Deposition Exhibit #001, Tessera's Notice of Deposition of Freescale Semiconductor	Montgomery	INFRNG/NON-INFRNG, RMDY, DI	Admitted
CX	1223		Montgomery Deposition Exhibit #002, Tessera ITC Investigation No. 337-TA-605 Complaint	Montgomery	INFRNG/NON-INFRNG, RMDY, DI	Admitted
CX	1224		Montgomery Deposition Exhibit #003, Complaintant Tessera's First Set of Interrogatories (1-5) to Freescale	Montgomery	INFRNG/NON-INFRNG, RMDY, DI	Admitted
CX	1225	C	Montgomery Deposition Exhibit #004, Freescale's Supplemental Responses to Tessera's First Set of Interrogatories (1-5)	Montgomery	Infrng/Non-infrng, Importation, Remedies	Admitted
CX	1226					Withdrawn
CX	1227	C	Montgomery Deposition Exhibit #005, Freescale's Supplemental Responses to Tessera's Second Set of Interrogatories (Nos. 6-20)	Montgomery	INFRNG/NON-INFRNG, RMDY, DI	Admitted

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CX	1228	C	Montgomery Deposition Exhibit #012, Freescale list regarding Part Ids and Corporations who purchased them in 2007	Montgomery	INFRNG/NON-INFRNG, RMDY, DI	Admitted
CX	1229	C	Montgomery Deposition Exhibit #014, Freescale list regarding Part Ids	Montgomery	INFRNG/NON-INFRNG, RMDY, DI	Admitted
CX	1230		O'Leary Deposition Exhibit #001, Tessera's Notice of Deposition of Freescale Semiconductor, Inc.	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1231	C	O'Leary Deposition Exhibit #002, Respondent Freescale Semiconductor, Inc.'s Supplemental Response to Complaint Tessera's First Set of Interrogatories (Nos. 1-5)	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1232	C	O'Leary Deposition Exhibit #003, Respondent Freescale Semiconductor, Inc.'s Supplemental Responses to Complainant Tessera's Second Set of Interrogatories (Nos. 6-20)	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1233	C	O'Leary Deposition Exhibit #004, Freescale Semiconductor, Inc.'s Confidential Business Information	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1234	C	O'Leary Deposition Exhibit #005, Piece Part Document, "IBM-Bromont Piece Parts", Doc.# 01ARS10523D, Issue II, 3 pgs	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1235	C	O'Leary Deposition Exhibit #006, Contract House Piece Parts, "STATS Singapore Piece Part Document", Doc.# 01ACM1059D, Issue IV, 8 pgs	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1236	C	O'Leary Deposition Exhibit #007, Contract House Piece Parts, "ASE-TAIWAN Piece Parts Document", Doc.# 01ASH00613A", Issue KB, 24 pgs	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1237	C	O'Leary Deposition Exhibit #008, Contract House Piece Parts, "Piece Part Document", Doc.# 01ASA10523D, Issue DN, 13 pgs	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1238	C	O'Leary Deposition Exhibit #009, Contract House Piece Parts, "ANAM Piece Part Document", Doc.# 17CSH00482A, Issue GT, 19 pgs	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1239	C	O'Leary Deposition Exhibit #010, Contract House Piece Parts, "ANAM Piece Part Document", Doc.# 17ARE10001W, Issue AU, 4 pgs	O'Leary	INFRNG/NONINFRNG	Admitted

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CX	1240	C	O'Leary Deposition Exhibit #011, Piece Part Document, "Final Manufacturing Operation, Misc. Contract Piece Parts", Doc. # 01ASH70609A, Issue DM, 11 pgs	O'Leary	INFRNG/NONINFRNG	Admitted
CX	1241					Withdrawn
CX	1242					Withdrawn
CX	1243					Withdrawn
CX	1244	C	Preecha Deposition Exhibit #002, Qualcomm's Second Supplemental Response to Tessera's First Set of Interrogatories	Preecha	Infrng/Non-infrng	Admitted
CX	1245					Withdrawn
CX	1246		Roosien Deposition Exhibit #001, Tessera's Notice of Deposition of Freescale Semiconductor, Inc.	Roosien	RMDY, DI	Admitted
CX	1247	C	Roosien Deposition Exhibit #002, Respondent Freescale Semiconductor, Inc.'s Responses to Complainant Tessera's First Set of Interrogatories (Nos. 1-5)	Roosien	Infrng/Non-infrng, Importation, Remedies	Admitted
CX	1248					Withdrawn
CX	1249					Withdrawn
CX	1250	C	Roosien Deposition Exhibit #005, Email from Park Changhae to Robert Rodriguez, Michael Noonan and Paul Reidy re Freescale Royalty	Roosien	RMDY, DI	Admitted
CX	1251	C	Roosien Deposition Exhibit #006, Redacted Email String re Second Amendment on Freescale Immunity Agreement	Roosien	RMDY, DI	Admitted
CX	1252					Withdrawn
CX	1253	C	Roosien Deposition Exhibit #008, Immunity Agreement by and between Motorola, Inc. and AMKOR Electronics, Inc.	Roosien	RMDY, DI	Admitted
CX	1254	C	Roosien Deposition Exhibit #009, Motorola Inter-Office Correspondencce to Jim Smith re Immunity from Suit Agreement for ASE and the SPS vault	Roosien	RMDY, DI	Admitted
CX	1255					Withdrawn
CX	1256					Withdrawn
CX	1257					Withdrawn
CX	1258					Withdrawn
CX	1259					Withdrawn
CX	1260					Withdrawn
CX	1261					Withdrawn
CX	1262					Withdrawn

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CX	1263					Withdrawn
CX	1264					Withdrawn
CX	1265					Withdrawn
CX	1266					Withdrawn
CX	1267		Suresh Deposition Exhibit #002, Respondents Spansion Inc. and Spansion LLC's Repsponses to Tesserea's Second Set of Interrogatories (6-20)	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1268	C	Suresh Deposition Exhibit #003, Report regarding the Bill of Materials for Certain Packages	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1269	C	Suresh Deposition Exhibit #004, Report regarding the Bill of Materials for Certain Packages	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1270	C	Suresh Deposition Exhibit #005, Documents containing names and information of customers of Spansion	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1271	C	Suresh Deposition Exhibit #006, Respondents Spansion Inc. and Spansion LLC's Supplemental Responses to Tessera's Second Set of Interrogatories (6, 8)	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1272	C	Suresh Deposition Exhibit #007, Complaintant Tessera's Second Set of Interrogatories (6-20) To Respondent Spansion, INc.	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1273	C	Suresh Deposition Exhibit #008, Reliability Qualifaction Document for Package ASD188	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1274	C	Suresh Deposition Exhibit #009, Collection of technical documents relating to ASD188 that were cited in Amended Appendix A and Appendix B	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1275	C	Suresh Deposition Exhibit #010, FBA48 Package Using 98F08 in Bangkok for MSD Project #224 by Shankar Subramanian	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1276	C	Suresh Deposition Exhibit #011, Technical Drawing Document relating to Package No. 27383	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1277	C	Suresh Deposition Exhibit #012, TSD 084 (MCP) Package for XS257A6K3 (Micron) Device Assembled in BKK/PNG/SUZ by Alex Tain (completed 09/01/2005)	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1278	C	Suresh Deposition Exhibit #013, Technical Drawing Document relating to TFRBGA-R Package - TSD 084	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1279	C	Suresh Deposition Exhibit #014, AMD Advance Information Report for AM29N128J/Am29N643J	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1280		Suresh Deposition Exhibit #1, Tessera's Notice of Deposition of Spansion, Inc.	Suresh	INFRNG/NON-INFRNG	Admitted

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CX	1281		Suresh Deposition Exhibit #101, Tessera's Notice of Deposition of Spansion, Inc.	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1282		Suresh Deposition Exhibit #102, Tessera's Notice of Deposition of Spansion, Inc.	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1283	C	Suresh Deposition Exhibit #103, Document titled "Spansion's Confidential Business Information- Listing of Spansion Products"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1284	C	Suresh Deposition Exhibit #104, Document entitled "Concode for FBGA & MCP Package Family (Per F09-000)	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1285	C	Suresh Deposition Exhibit #105, Document entitled "Reliability Qualification, Project Name: 98U03A VBH084 QUAL"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1286	C	Suresh Deposition Exhibit #106, Document entitled "Henkel-QMI 546 DIE ATTACH PASTE"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1287	C	Suresh Deposition Exhibit #107, Document entitled "Technical Data Sheet- Hysol QMI 546"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1288	C	Suresh Deposition Exhibit #108, Document entitled "Hitachi Chemical HS-23H Insulated Film Die Attach Adhesive, Spec # F04-0X28289"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1289	C	Suresh Deposition Exhibit #109, Document entitled "Hitachi Chemical HS-23H Insulated Film Die Attach Adhesive, Spec #F04-0028082"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1290	C	Suresh Deposition Exhibit #110, Document entitled "Hitachi Chemical HS-23H Insulated Film Die Attach Adhesive, Spec # F04-0027803"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1291	C	Suresh Deposition Exhibit #111, Document entitled "Hitachi Chemical HS-23H Insulated Film Die Attach Adhesive, Spec # F04-0029734"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1292	C	Suresh Deposition Exhibit #112, Document entitled "Hitachi Chemical HS-23H Insulated Film Die Attach Adhesive, Spec # F04-0X29759"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1293	C	Suresh Deposition Exhibit #113, Document entitled "Critical Functional Quality Criteria- Molded Product"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1294	C	Suresh Deposition Exhibit #114, Document entitled "Request for Engineering Build"	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1295	C	Suresh Deposition Exhibit #115, Document entitled "LAA064 Package Qualification"	Suresh	INFRNG/NON-INFRNG	Admitted

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CX	1296	C	Suresh Deposition Exhibit #116, Document relating to LAC064 Package	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1297	C	Suresh Deposition Exhibit #117, Email from Foong, YH to Tina Chow, John Yan, Du Yong, Bharalwaj Ramakrishnan, LK Suresh, Bruce Symons and Niranjan Vijayaragavan re Assembly Data	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1298	C	Suresh Deposition Exhibit #118, Email from Weera Mahajuntakam to W. Sabyeying, D. Duong, G. Subramanian, S. Foong, S. Samaititchon, V. Valluri, P. Kirawongsapiwat and N. Chuenpeng re Critical Dimensional Inspection on JCI Substrate- 27628	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1299	C	Suresh Deposition Exhibit #119, VBL088 (VFBGA) Package for 98U03A Device Assembled in BKK, MSD Project # 3714	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1300	C	Suresh Deposition Exhibit #120, Email from G. Subramanian to J. Gomez et al., re LAA daisy chain for customer	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1301	C	Suresh Deposition Exhibit #121, PDL128G Package Options	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1302	C	Suresh Deposition Exhibit #122, Email from E.T. Yeoh to J. Chang et al., re 98R08A FBE63 & LAA64 Qual Summary	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1303					Withdrawn
CX	1304	C	Suresh Deposition Exhibit #124, Email from F. Classe to M. Mizutani et al., re VBN048 Issue (98M57)	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1305	C	Suresh Deposition Exhibit #125, Document titled "98K03 LLA064 1mm FBGA Package Qualification	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1306	C	Suresh II Deposition Exhibit #126, Reliability Qualification, Project Name PGN 64/64.FSA063JIC0.45BALL	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1307	C	Suresh II Deposition Exhibit #127, FSA 063 Wire Bond Diagram	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1308	C	Suresh II Deposition Exhibit #128, Group of Emails beginning with email to Bansal, Dhiraj, et al., from Smamatitchon, Surasez re LV640 Device	Suresh	INFRNG/NON-INFRNG	Admitted
CX	1309	C	Suresh II Deposition Exhibit #129, Email string beginning with email to Garcia, Margot, from Tanaka, Neal re WS128J VBH084 Package	Suresh	INFRNG/NON-INFRNG	Admitted

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CX	1310	C	Veatch Deposition Exhibit #001, Respondent Qualcomm Incorporated's Second Supplementak Response to Complainant Tessera, Inc.'s First Set of Interrogatories to Qualcomm Incorporated.	Veatch	INFRNG/NONINFRNG	Admitted
CX	1311	C	Veatch Deposition Exhibit #002, Monthly report from Nov. 2001 for the IC Package engineering department	Veatch	INFRNG/NONINFRNG	Admitted
CX	1312	C	Veatch Deposition Exhibit #003, Email from C. Bai to Mark Veatch et al., re January 2002 Activity Report	Veatch	INFRNG/NONINFRNG	Admitted
CX	1313	C	Veatch Deposition Exhibit #004, Monthy report inputs for February, 2002	Veatch	INFRNG/NONINFRNG	Admitted
CX	1314	C	Veatch Deposition Exhibit #005, Summary of CSP development Activities for the Package Engineering Group	Veatch	INFRNG/NONINFRNG	Admitted
CX	1315	C	Veatch Deposition Exhibit #006, Qualcomm Memorandum from James Burrell to Mark Veatch & C. Bai re Toshiba PDA System Level Thermal Analysis	Veatch	INFRNG/NONINFRNG	Admitted
CX	1316	C	Veatch Deposition Exhibit #007, August 2005 monthly report for the package engineering department	Veatch	INFRNG/NONINFRNG	Admitted
CX	1317	C	Veatch Deposition Exhibit #008, IC Package Characterization Requirements	Veatch	INFRNG/NONINFRNG	Admitted
CX	1318	C	Veatch Deposition Exhibit #009, Email from K. Kaskoun to info@tessera.com re Through Silicon Stacking	Veatch	INFRNG/NONINFRNG	Admitted
CX	1319					Withdrawn
CX	1320	C	Veatch Deposition Exhibit #011, Email from amri-support@qualcomm.com to Mark Veatch re Electronic MR 1196601 changes	Veatch	INFRNG/NONINFRNG	Admitted
CX	1321	C	Veatch Deposition Exhibit #014, TSMC Thermal and Mechanical Core Competency Development	Veatch	INFRNG/NONINFRNG	Admitted
CX	1322					Withdrawn
CX	1323					Withdrawn
CX	1324	C	Witten Deposition Exhibit #003, Tessera Product Family and Item Numbers.xls	Witten	RMDY	Admitted
CX	1325	C	Witten Deposition Exhibit #004, Qualcomm's First Supplemental Response to Tessera's First Set of Interrogatories to Qualcomm	Witten	Infrng/Non-infrng, Importation, Remedies	Admitted
CX	1326	C	Witten Deposition Exhibit #006, Tessera Import data Jan 1 2007-November 30 2007 Spreadsheet	Witten	RMDY	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1327	C	Witten Deposition Exhibit #007, Diebank Inventory Status List	Witten	RMDY	Admitted
CX	1328	C	Witten Deposition Exhibit #008, Tessera Inventory report	Witten	RMDY	Admitted
CX	1329					Withdrawn
CX	1330	C	DiStefano Deposition Exhibit #147, Highly Confidential document entitled "Record"	DiStefano	OWNR	Admitted
CX	1331	C	Balog Deposition Exhibit #013, Motorola excel spreadsheet used by sourcing team to do cost modeling of devices	Balog	RMDY	Admitted
CX	1332	C	Qu Deposition Exhibit #260, Errata Sheet for January 11, 2008 Expert Report	Qu	INFRNG/NON-INFRNG	Admitted
CX	1333	C	Qu Deposition Exhibit #269, Updated Figures and Tables from January 11, 2008 Expert Report	Qu	INFRNG/NON-INFRNG	Admitted
CX	1334		Hundt Deposition Exhibit #005 - Form 20-F, filed March 14, 2007	Qu	INFRNG/NON-INFRNG	Admitted
CX	1335		Hundt Deposition Exhibit #008 - Advanced Packaging - Plastic BGA - Low profile fine pitch BGA - Thin Fine Pitch BGA	Qu	INFRNG/NON-INFRNG	Admitted
CX	1336	C	Hundt Deposition Exhibit #010, Pilot Technical Datasheet for Ablebond 2300	Hundt	INFRNG/NON-INFRNG	Admitted
CX	1337	C	Hundt Deposition Exhibit #011, Technical Datasheet for Loctite Die Attach Materials	Hundt	INFRNG/NON-INFRNG	Admitted
CX	1338	C	Hundt Deposition Exhibit #012, Technical Datasheet for Hitachi Chemical Die Bonding Pastes	Hundt	INFRNG/NON-INFRNG	Admitted
CX	1339	C	Hundt Deposition Exhibit #013, Design for Package and Board Level Reliability with CAE	Hundt	INFRNG/NON-INFRNG	Admitted
CX	1340	C	Hundt Deposition Exhibit #014 - How to Solder a BGA on a Printed Circuit board	Qu	INFRNG/NON-INFRNG	Admitted
CX	1341	C	Malone Deposition Exhibit #003, Document Entitled, "ST-NV Form 20F"	Malone	INFRNG/NON-INFRNG	Admitted
CX	1342		Malone Deposition Exhibit #014, Document Entitled, "Response of STMicroelectronics N.V. to the Complaint, as Supplemented, Under Section 337 of the Tariff Act of 1930, as Amended"	Malone	INFRNG/NON-INFRNG	Admitted
CX	1343		Malone Deposition Exhibit #017, STMicroelectronics Digital Satellite Broadcast Chips Enable In-Vehicle Sirius Backseat TV	Malone	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1344		Malone Deposition Exhibit #018 - Document Entitled, "STA264 Sirius overlay decoder"	Malone	INFRNG/NON-INFRNG	Admitted
CX	1345	C	Richards Deposition Exhibit #002, Motorola Failure Analysis Report on GSM T720 Phone	Richards	INFRNG/NONINFRNG	Admitted
CX	1346	C	Richards Deposition Exhibit #003, Motorola Email re: Approval of STM Flash on GSM V3	Richards	INFRNG/NONINFRNG	Admitted
CX	1347	C	Richards Deposition Exhibit #004, Motorola Component Report on Part No. 5199190J01 (STM Flash Memory)	Richards	INFRNG/NONINFRNG	Admitted
CX	1348					Withdrawn
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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
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Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
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CX	1554					Withdrawn
CX	1555					Withdrawn
CX	1556	C	Qualcomm Presentation	Qu	Infrng/Non-infrng	Admitted
CX	1557	C	ATI All Wires Diagram for Device W2284D, Version G	Qu	Infrng/Non-infrng	Admitted
CX	1558	C	ATI Package Outline Drawing, Drawing No. POD 100100025905001	Qu	Infrng/Non-infrng	Admitted
CX	1559	C	ATI Substrate Design for Customer Dwg. No. SUB-W2284GDB11g_1A-Rev B	Qu	Infrng/Non-infrng	Admitted
CX	1560	C	ATI Wire Bond Diagram for Customer Device W2284D	Qu	Infrng/Non-infrng	Admitted
CX	1561	C	ATI Wire Bond Diagram for Customer Device W2284D	Qu	Infrng/Non-infrng	Admitted
CX	1562					Withdrawn
CX	1563	C	SPIL Reliability Test Report for ATI STFBGA259(10*10)(LF) New Device Qual, No. R0605250789	Qu	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1564	C	Customer Applications Support and Reliability Test Center," PBGA Customer Presentation	Qu	Infrng/Non-infrng	Admitted
CX	1565	C	Digital DNA from Motorola Presentation entitled, "Customer Applications Support and Reliability Test Center"	Qu	Infrng/Non-infrng	Admitted
CX	1566	C	Freesale Wire Bond Drawing, Dwg. No. 67ASA11241D	Qu	Infrng/Non-infrng	Admitted
CX	1567	C	Freescale Circuit Configuration Drawing, Dwg. No. 84ARE11469D	Qu	Infrng/Non-infrng	Admitted
CX	1568	C	Freescale Circuit Configuration Drawing, Dwg. No. 84ASA10642D	Qu	Infrng/Non-infrng	Admitted
CX	1569		Freescale MPC8XXFADS Design Specification - Rev. 0.1, Preliminary	Qu	Infrng/Non-infrng	Admitted
CX	1570	C	Freescale Wire Bond Drawing, Dwg. No. 67ARE11027D	Qu	Infrng/Non-infrng	Admitted
CX	1571	C	Motorola Materials or Methods Specification, "Manufacturing Requirements for IC Packages (BGA and LGA devices)"	Qu	Infrng/Non-infrng	Admitted
CX	1572	C	Chart of Supplier Parent, Parts	Qu	Infrng/Non-infrng	Admitted
CX	1573					Withdrawn
CX	1574					Withdrawn
CX	1575					Withdrawn
CX	1576	C	Spansion Amended Appendix A	Qu	Infrng/Non-infrng	Admitted
CX	1577					Withdrawn
CX	1578					Withdrawn
CX	1579					Withdrawn
CX	1580					Withdrawn
CX	1581					Withdrawn
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CX	1587					Withdrawn
CX	1588					Withdrawn
CX	1589					Withdrawn
CX	1590					Withdrawn
CX	1591					Withdrawn
CX	1592		AMD Am29DL800B Advanced Information	Qu	Infrng/Non-infrng	Admitted
CX	1593		AMD FBGA User's Guide, Version 2.3.1	Qu	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1594					Withdrawn
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CX	1622					Withdrawn
CX	1623					Withdrawn
CX	1624	C	AMD FBGA User's Guide, Version 2.3.1	Qu	Infrng/Non-infrng	Admitted
CX	1625	C	Concode for FBGA & MCP Package Family (per F09-000)	Qu	Infrng/Non-infrng	Admitted
CX	1626		Package code nomenclature for single chip packages	Qu	Infrng/Non-infrng	Admitted
CX	1627	C	Reliability Qualification for Project 96M73 MASK REVISION, Internal Device 98M73A2E	Qu	Infrng/Non-infrng	Admitted
CX	1628	C	Spansion Package Outline Drawing, Spec Number F16-038.9	Qu	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1629	C	Spansion Substrate Drawing, Dwg. No. 0028598	Qu	Infrng/Non-infrng	Admitted
CX	1630	C	Freescale Mechanical Outlines Dictionary, Document No. 98ARS23882W	Qu	Infrng/Non-infrng	Admitted
CX	1631					Withdrawn
CX	1632					Withdrawn
CX	1633		Certified Assignment of U.S. Patent No. 5,679,977 - Exhibit #16 to Complaint	DiStefano	OWNR	Admitted
CX	1634					Withdrawn
CX	1635					Withdrawn
CX	1636	C	Confidential Domestic Industry Information - Exhibit #5 to Complaint	Mitchell	RMDY, DI	Admitted
CX	1637	C	Confidential List of Licensees of the Asserted Patents - Exhibit #4 to Complaint	Griffin	RMDY, OWNR	Admitted
CX	1638					Withdrawn
CX	1639					Withdrawn
CX	1640					Withdrawn
CX	1641					Withdrawn
CX	1642					Withdrawn
CX	1643					Withdrawn
CX	1644					Withdrawn
CX	1645		Memorandum Opinion and Order on Claim Construction in *Tessera, Inc. v. Micron Technology, Inc., et al.* , Case No. 2:05cv94 - Exhibit #22 to Complaint	Qu	INFRNG/NON-INFRNG	Admitted
CX	1646		Order Construing Disputed Claims and Terms in *Samsung Electronics Co., Ltd., v. Tessera Technologies, Inc.* , Case No. C 02-5837 CW - Exhibit #20 to Complaint	Qu / Griffin	INFRNG/NON-INFRNG, RMDY, OWNR	Admitted
CX	1647		Order on Cross-Motions for Summary Judgment on Patent Issues, TI's Motion to Dismiss and Tessera's Motion for Summary Judgment on Contract Issues in *Texas Instruments, Inc. v. Tessera, Inc* ., Case No. C-00-2114 CW - Exhibit #19 to Complaint	Griffin / Ivey	RMDY, OWNR, VLD/INVLD	Admitted
CX	1648		Order on Parties' Cross Motions for Summary Judgment and Defendants' Motion to Amend in *Samsung Electronics Co., Ltd., v. Tessera Technologies, Inc.,* Case No. C 02-5837 CW - Exhibit #21 to Complaint	Griffin	RMDY, OWNR	Admitted
CX	1649					Withdrawn
CX	1650					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1651					Withdrawn
CX	1652		Initial Determination in the Matter of Certain Semiconductor Chips with Minimized Chip Package Size and Products Containing Same, ITC Inv. No. 432 - Public Version - Exhibit #7 to Complaint	Qu / Ivey / Pickett	INFRNG/NON-INFRNG, Invalid, OWNR, RMDY	Admitted
CX	1653	C	Order #13 - Initial Determination in the Matter of Certain Semiconductor Chips with Minimized Chip Package Size and Products Containing Same, ITC Inv. No. 432 - Confidential - Exhibit #3 to Complaint	Mitchell	RMDY, DI	Admitted
CX	1654		Order Construing Claims in Texas Instruments, Inc. v. Tessera, Inc., Case No. C-00-2114 CW - Exhibit #18 to Complaint	Qu / Griffin	INFRNG/NON-INFRNG, RMDY, OWNR	Admitted
CX	1655	C	Khandros Notebook	Ivey	VLD/INVLD	Admitted
CX	1656					Withdrawn
CX	1657					Withdrawn
CX	1658	C	Bottoms Up Database	Mitchell	RMDY, DI	Admitted
CX	1659					Withdrawn
CX	1660		Tessera 10-K	Mitchell	RMDY, DI	Admitted
CX	1661		Tessera 10-Q	Mitchell	RMDY, DI	Admitted
CX	1662					Withdrawn
CX	1663					Withdrawn
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CX	1728(B)					Withdrawn
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CX	1791(C)					Withdrawn
CX	1791(D)					Withdrawn
CX	1791(E)					Withdrawn
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CX	1793(A)					Withdrawn
CX	1793(B)					Withdrawn
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CX	1828					Withdrawn
CX	1829					Withdrawn
CX	1830	C	ATI's Responses to Tessera's Sixth Set of Interrogatories (#85-102)	Stipulation	Importation, Remedies	Admitted
CX	1831	C	Freescale's Responses to Tessera's Sixth Set of Interrogatories (#85-102)	Stipulation	Importation, Remedies	Admitted
CX	1832	C	Motorola's Amended Responses to Tessera's Sixth Set of Interrogatories (#85-102)	Stipulation	Importation, Remedies	Admitted
CX	1833	C	Motorola's Responses to Tessera's Sixth Set of Interrogatories (#85-102)	Stipulation	Importation, Remedies	Admitted
CX	1834	C	Qualcomm's Responses to Tessera's Sixth Set of Interrogatories (#85-102)	Stipulation	Importation, Remedies	Admitted
CX	1835					Withdrawn
CX	1836	C	Spansion's Responses to Tessera's Sixth Set of Interrogatories (#85-102)	Stipulation	Importation, Remedies	Admitted
CX	1837	C	STM's Supplemental Response to Tessera's Fifth Set of Interrogatories (#32-43)	Stipulation	Importation, Remedies	Admitted
CX	1838	C	STM's Supplemental Response to Tessera's Second Set of Interrogatories	Stipulation	Importation, Remedies	Admitted
CX	1839	C	STM's Supplemental Response to Tessera's Seventh Set of Interrogatories (#71-101)	Stipulation	Importation, Remedies	Admitted
CX	1840	C	STM's Supplemental Response to Tessera's Sixth Set of Interrogatories	Stipulation	Importation, Remedies	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1841	C	Supplemental Responses of Sony Ericsson Mobile Communications (USA) Inc. to Subpoena Duces Tecum	Mitchell and/or Pickett	Importation, Remedies	Admitted
CX	1842					Withdrawn
CX	1843					Withdrawn
CX	1844					Withdrawn
CX	1845					Withdrawn
CX	1846					Withdrawn
CX	1847	C	Spansion Inventory Report	Stipulation	Importation, Remedies	Admitted
CX	1848					Withdrawn
CX	1849					Withdrawn
CX	1850					Withdrawn
CX	1851					Withdrawn
CX	1852					Withdrawn
CX	1853		Freescale Form 10-Q for the Period Ending 09/28/07	Stipulation	Importation, Remedies	Admitted
CX	1854		Motorola 2007 Financial Analyst Update	Brda	RMDY	Admitted
CX	1855		Motorola Form 10-K for the Period Ending 12/31/06	Stipulation	Importation, Remedies	Admitted
CX	1856		Motorola Inc Q4 Earnings Call Transcript	Brda	RMDY	Admitted
CX	1857					Withdrawn
CX	1858					Withdrawn
CX	1859		Murray Exhibit #3: Pages from the Freescale website related to Manufacturing	Murray		Admitted
CX	1860		Qualcomm 10-K for the Fisal Year Ended Septemer 30, 2007	Stipulation	Importation, Remedies	Admitted
CX	1861		Qualcomm 10-Q for the Quarter Ended December 31, 2007	Stipulation	Importation, Remedies	Admitted
CX	1862		Qualcomm Form 10-K for the Period Ending 09/30/07	Qu	INFRNG/NON-INFRNG	Admitted
CX	1863		Qualcomm Form 10-Q for the Period Ending 04/01/07	Stipulation	Importation, Remedies	Admitted
CX	1864					Withdrawn
CX	1865					Withdrawn
CX	1866					Withdrawn
CX	1867					Withdrawn
CX	1868					Withdrawn
CX	1869					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1870					Withdrawn
CX	1871					Withdrawn
CX	1872					Withdrawn
CX	1873					Withdrawn
CX	1874					Withdrawn
CX	1875					Withdrawn
CX	1876					Withdrawn
CX	1877					Withdrawn
CX	1878	C	Motorola Personal Communications Sector, CTE - Materials & Failure Analysis Laboratory	Qu	Infrng/Non-infrng	Admitted
CX	1879	C	4-Dimensional Design Optimization of System-In-Package with CAE - PPT with BGA Package Structure	Qu	Infrng/Non-infrng	Admitted
CX	1880	C	9/23/97 Email - Die Attach	Qu	Infrng/Non-infrng	Admitted
CX	1881	C	Advanced Assembly and Substrate Design Rules Manual for Mixed Interconnect Modules BGA/LGA	Qu	Infrng/Non-infrng	Admitted
CX	1882	C	ANSYS Input files used in ST's FEA analysis of BGA packages (file paths:\STITC00122311\INTERPOSER2\DESIGN1A.MAC and DESIGN1F.MAC)	Qu	INFRNG/NON-INFRNG	Admitted
CX	1883	C	BGA Board Level Interconnect Reliability - PPT with BGA Package Structure	Qu	Infrng/Non-infrng	Admitted
CX	1884	C	Board Level Solder Joint Reliability Analysis and Optimization of Pyramidal Stacked Die BGA Packages	Qu	Infrng/Non-infrng	Admitted
CX	1885	C	Board Level Solder Joint Reliability Analysis of Stacked Die Mixed Flip-Chip and Wirebond BGA	Qu	Infrng/Non-infrng	Admitted
CX	1886	C	Board Level Solder Joint Reliability Modeling and Testing of TFBGA Packages for Telecommunication Applications	Qu	Infrng/Non-infrng	Admitted
CX	1887	C	Board Level Solder Joint Reliability Modeling and Testing of TFBGA Packages for Telecommunication Applications	Qu	Infrng/Non-infrng	Admitted
CX	1888	C	Built Sheet Assembly for A5HX*TO21AGP (TO21AHXT$GB1/LFA)	Qu	Infrng/Non-infrng	Admitted
CX	1889	C	Built Sheet Assembly for G52K*V440CAJ (STLC2500C)	Qu	Infrng/Non-infrng	Admitted
CX	1890	C	Built Sheet Assembly for M36L0R8060B7ZAQ	Qu	Infrng/Non-infrng	Admitted
CX	1891	C	Built Sheet Assembly for M36W0R7040U0ZC5U	Qu	Infrng/Non-infrng	Admitted
CX	1892	C	Built Sheet Assembly for M5R8*TU04DGP (TU04DR8T$GB/LFA)	Qu	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1893	C	Built Sheet Assembly for RL ADSY*N9YC8K9 (NAND512R3A2BZA6F)	Qu	Infrng/Non-infrng	Admitted
CX	1894	C	Built Sheet Assembly for RL FD2Z*5M5FS99 (M36P0R9070E0ZACF)	Qu	Infrng/Non-infrng	Admitted
CX	1895	C	Built Sheet Assembly for RL FD2Z*5M5GS99 (M36P0R9060E0ZACF)	Qu	Infrng/Non-infrng	Admitted
CX	1896	C	Built Sheet Assembly for RL ND2Z*5M9PA99 (M36P0R9070E1ZACF)	Qu	Infrng/Non-infrng	Admitted
CX	1897	C	Built Sheet Assembly for TFD8VWIT$P4/LFA	Qu	Infrng/Non-infrng	Admitted
CX	1898	C	Built Sheet Assembly for TO24C78T$GZ3/LFA	Qu	Infrng/Non-infrng	Admitted
CX	1899	C	Built Sheet Assembly for XCOZ*W4QN5KO (XCOZW4QN5KOT706U)	Qu	Infrng/Non-infrng	Admitted
CX	1900	C	Built Sheet Assembly for XTV0984-Moire Sample (STITC00133177)	Qu	Infrng/Non-infrng	Admitted
CX	1901	C	Comprehensive Design Analysis of QFN and Power QFN Packages for Enhanced Board Level Solder Joint Reliability	Qu	Infrng/Non-infrng	Admitted
CX	1902	C	CSP at ST Microelectronics	Qu	Infrng/Non-infrng	Admitted
CX	1903	C	Design Analysis and Optomization for Wirebond Stacked Die BGA Packages for Improved Board Level Solder Joint Reliabillity	Qu	Infrng/Non-infrng	Admitted
CX	1904	C	Design Analysis of QFN Package for Enhanced Solder Joint Reliability	Qu	Infrng/Non-infrng	Admitted
CX	1905	C	Design Analysis of Solder Joint Reliability for Stacked Die Mixed Flip-Chip and Wirebond BGA	Qu	Infrng/Non-infrng	Admitted
CX	1906	C	Design for Package with Board Level Reliabilty with CAE	Qu	Infrng/Non-infrng	Admitted
CX	1907	C	Development and Application of Lead-Free Solder Joint Fatigue Model for CSP	Qu	Infrng/Non-infrng	Admitted
CX	1908	C	Email from Laurent Herard attaching ST-NV TFBGA Development, Project Update, March 1999 - PPT with BGA Package Structure	Qu	INFRNG/NON-INFRNG	Admitted
CX	1909	C	Email message; Task Force BGA Material Cost, notes of Second Meeting in Grenoble, France, dated June 26, 1997; Journal Article mentioning Tessera Licensees	Qu	INFRNG/NON-INFRNG	Admitted
CX	1910					Withdrawn
CX	1911	C	Fine Pitch Ball Grid Array (fpBGA) Assembly Flow Chart in ASAT (HK)	Qu	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1912	C	Integrated Modeling and Testing of Fine-Pitch CSP Under Board Level Drop Test, Bend Test, and Thermal Cycling Test	Qu	Infrng/Non-infrng	Admitted
CX	1913	C	July 1, 1997 Email from Luc Mary (ST-NV) to Jacques Ferrera (ST-NV)	Qu	INFRNG/NON-INFRNG	Admitted
CX	1914	C	July 29, 1999 Email from Patrick Perillat to Laurent Herard	Qu	INFRNG/NON-INFRNG	Admitted
CX	1915	C	June 22, 1997 Email - uBGA	Qu	Infrng/Non-infrng	Admitted
CX	1916	C	Mount & Bond Diagram for A5HX*TO21AGP (TO21AHXT$GB1/LFA)	Qu	Infrng/Non-infrng	Admitted
CX	1917	C	Mount & Bond Diagram for M5R8*TU04DGP (TU04DR8T$GB/LFA)	Qu	Infrng/Non-infrng	Admitted
CX	1918	C	Mount & Bond Diagram for TFD8VWIT$P4/LFA	Qu	Infrng/Non-infrng	Admitted
CX	1919	C	Mount & Bond Diagram for TO24C78T$GZ3/LFA	Qu	Infrng/Non-infrng	Admitted
CX	1920	C	Mount & Bond Diagram for XCAIP5JF5KOB706F	Qu	Infrng/Non-infrng	Admitted
CX	1921	C	Mount & Bond Diagram for XTV0984-Moire Sample (STITC00133177)	Qu	Infrng/Non-infrng	Admitted
CX	1922	C	November 5, 1999 Email from Laurent Herard to Robert Bronner and Andre Clement	Qu	INFRNG/NON-INFRNG	Admitted
CX	1923	C	Package Outline Assembly for A5HX*TO21AGP (TO21AHXT$GB1/LFA)	Qu	Infrng/Non-infrng	Admitted
CX	1924	C	Package Outline Assembly for H5FN*MV86BAA (MV86BFNT$PB3/LFA)	Qu	Infrng/Non-infrng	Admitted
CX	1925	C	Package Outline Assembly for M36L0R8060B7ZAQ	Qu	Infrng/Non-infrng	Admitted
CX	1926	C	Package Outline Assembly for M5R8*TU04DGP (TU04DR8T$GB/LFA)	Qu	Infrng/Non-infrng	Admitted
CX	1927	C	Package Outline Assembly for MDR05363A99T705U	Qu	Infrng/Non-infrng	Admitted
CX	1928	C	Package Outline Assembly for TFBGA 8x11x1.20 (M36P0R9060E0ZACF)	Qu	Infrng/Non-infrng	Admitted
CX	1929	C	Package Outline Assembly for TFD8VWIT$P4/LFA	Qu	Infrng/Non-infrng	Admitted
CX	1930	C	Package Outline Assembly for WFBGA 4.5x4.5x0.8 (STLC2500C)	Qu	Infrng/Non-infrng	Admitted
CX	1931	C	Package Outline Assembly for XTV0984-Moire Sample (STITC00133177)	Qu	Infrng/Non-infrng	Admitted
CX	1932	C	Product Specification for ADSY*N9YC8K8 in Manufacturing Phase T&F (NAND512R3A2BZA6F)	Qu	Infrng/Non-infrng	Admitted
CX	1933					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1934	C	SGS Thompson Training Schedule and Cover Letter, 1997	Qu	Infrng/Non-infrng	Admitted
CX	1935	C	ST Datasheet for M36W0R6040T0 et al. (M36WOR6040T1ZAQF)	Qu	INFRNG/NON-INFRNG	Admitted
CX	1936	C	ST Datasheet for M39P0R9070E0 (M39POR9070E2ZADF / M39POR9070E4ZADF)	Qu	Infrng/Non-infrng	Admitted
CX	1937	C	ST Datasheet for NAND512-A et al. (NAND512R3A2BZA6F)	Qu	Infrng/Non-infrng	Admitted
CX	1938	C	ST Datasheet for STLC2500C (STLC2500C)	Qu	INFRNG/NON-INFRNG	Admitted
CX	1939	C	ST Datasheet for STLC2590 (STLC2590)	Qu	Infrng/Non-infrng	Admitted
CX	1940	C	ST Datasheet for STLC2592 (STLC2592)	Qu	Infrng/Non-infrng	Admitted
CX	1941	C	ST Datasheet for STw4141 (STW41411/T)	Qu	Infrng/Non-infrng	Admitted
CX	1942					Withdrawn
CX	1943	C	Substrate Technical Specs. For M36L0R8060B7ZAQ	Qu	Infrng/Non-infrng	Admitted
CX	1944	C	Substrate Technical Specs. for TFD8VWIT$P4/LFA	Qu	Infrng/Non-infrng	Admitted
CX	1945	C	Substrate Technical Specs. for XTV0984-Moire Sample (STITC00133177)	Qu	Infrng/Non-infrng	Admitted
CX	1946	C	TCD-TFBGA121 Daisy Chain Package Datasheet	Qu	Infrng/Non-infrng	Admitted
CX	1947					Withdrawn
CX	1948					Withdrawn
CX	1949					Withdrawn
CX	1950		A Complete Vision in Smartcard Technology	Qu	Infrng/Non-infrng	Admitted
CX	1951	C	BGA Substrate Technology Roadmap 2006 Rev. 2.0, Corporate Packaging & Automation	Qu	Infrng/Non-infrng	Admitted
CX	1952		CEA signs research contract with the partners of the Crolles2 Alliance for development of 45 nm and 32 nm CMOS nanoelectric technologies	Hundt, Qu, Tessera Corporate Designee	Infrng/Non-infrng, Remedy	Admitted
CX	1953		Consortium of Semiconductor and Consumer Electronics Companies Unveils Complete Joint Proposal for IEEE 802.11 Task Group N	Hundt, Qu, Tessera Corporate Designee	Infrng/Non-infrng, Remedy	Admitted
CX	1954					Withdrawn
CX	1955					Withdrawn
CX	1956					Withdrawn
CX	1957					Withdrawn
CX	1958					Withdrawn
CX	1959					Withdrawn
CX	1960					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1961					Withdrawn
CX	1962					Withdrawn
CX	1963					Withdrawn
CX	1964					Withdrawn
CX	1965		Enhanced efficiency and data security in health care 9,000,000 health cards for Lombardy	Tessera Designee	Vldy/Invldy	Admitted
CX	1966					Withdrawn
CX	1967		Infineon, Philips, and ST Welcome Freescale to E3 lead-free initiative	Qu	Infrng/Non-infrng, Remedy	Admitted
CX	1968		Interfacial Reaction and Shear Strength of Pb-free SnAg2.5Cu0.8Sb0.5 and SnAg3.0Cu0.5Sb0.2 Solder Bumps on Au/Ni(P) Metallization	Qu	INFRNG/NON-INFRNG	Admitted
CX	1969	C	Leadfree PBGA Balls Soldering Quality Improvement for Ni-Au BGA pads	Qu	INFRNG/NON-INFRNG	Admitted
CX	1970	C	Materials and Process Considerations for Lead-Free Electronic Assembly	Qu	INFRNG/NON-INFRNG	Admitted
CX	1971		Mechanical Properties of Lead-Free Solders	Qu	Infrng/Non-infrng	Admitted
CX	1972		Motorola and SGS-Thomson to Provide Interoperability of Microcontrollers for Contactless Smartcards and Readers	Qu	Infrng/Non-infrng	Admitted
CX	1973		Motorola, Philips and STMicroelectronics Introduces Debut Industry's First 90-Nanometer CMOS Design Platform	Qu	Infrng/Non-infrng	Admitted
CX	1974	C	Package Outline Assembly for LFBGA 16x16x1.7 (Package Code HY)	Qu	Infrng/Non-infrng	Admitted
CX	1975					Withdrawn
CX	1976		Pilot Technical Datasheet for Ablebond 2025D	Qu	INFRNG/NON-INFRNG	Admitted
CX	1977		Pilot Technical Datasheet for Ablebond 2300	Qu	Infrng/Non-infrng	Admitted
CX	1978	C	Presentation: Thermal-mechanical Simulation of Cu/Low-k FCBGA	Qu	INFRNG/NON-INFRNG	Admitted
CX	1979					Withdrawn
CX	1980					Withdrawn
CX	1981					Withdrawn
CX	1982					Withdrawn
CX	1983					Withdrawn
CX	1984					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	1985		Semiconductor Packaging Materials Product Selector Guide	Qu	Infrng/Non-infrng	Admitted
CX	1986		ST Website - "Talk with more intelligence"	Qu	Infrng/Non-infrng, Remedy	Admitted
CX	1987		ST Website - "We put more intelligence into everything"	Qu	Infrng/Non-infrng, Remedy	Admitted
CX	1988		ST Website - Glossary of Terms A-Z	Qu	Infrng/Non-infrng	Admitted
CX	1989		ST Website - Press Release - 16MBIT 3V Supply Flash Memory	Qu	Infrng/Non-infrng	Admitted
CX	1990		ST Website - Press Release - 8 MBIT 3v Supply Flash Memory	Qu	Infrng/Non-infrng	Admitted
CX	1991		ST Website - Products Index	Qu	Infrng/Non-infrng	Admitted
CX	1992		ST Website - Strategic Segments - "Behind Great Smartcards…"	Qu	Infrng/Non-infrng	Admitted
CX	1993		ST Website - Strategic Segments - "Inside Every Great Auto Design…"	Qu	Infrng/Non-infrng	Admitted
CX	1994		ST Website - Strategic Segments - "Inside Every Great Computer Design…"	Qu	Infrng/Non-infrng	Admitted
CX	1995		ST Website - Strategic Segments - "Inside Every Great Product Design…"	Qu	Infrng/Non-infrng	Admitted
CX	1996		ST Website - Strategic Segments - "Inside Great Wireless Systems…"	Qu	Infrng/Non-infrng	Admitted
CX	1997		ST Website - Technical Document - "STV0976 - 1.0 Megapixel SMIA Processor"	Qu	Infrng/Non-infrng	Admitted
CX	1998		ST Website - Technical Document - "STw5095 - Low Power Asynchronous Stereo Audio Codec with Integrated Power Amplifiers" Data Brief	Qu	INFRNG/NON-INFRNG	Admitted
CX	1999		ST Website - Testimonials - Altec Lansing - When Altec-Lansing Wanted to Bring Full Spectrum Sound to a Desktop ...ST's Systems'on-Silicon Struck All the Right Chords"	Qu	Infrng/Non-infrng	Admitted
CX	2000		ST Website - Testimonials - BMW - "We Helped the BMW Group Negotiate Technical Obstacles with our Advanced Systems-on-Silicon"	Qu	Infrng/Non-infrng	Admitted
CX	2001		ST Website - Testimonials - Bosch - "We Helped Bosch Accelerate the Move to Greener Diesel Engine Management With Our Advanced Systems-on-Silicon"	Qu	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2002		ST Website - Testimonials - Bose -"We Helped Bosch Accelerate the Move to Greener Diesel Engine Management With Our Advanced Systems-on-Silicon"	Qu	Infrng/Non-infrng	Admitted
CX	2003		ST Website - Testimonials - HP - "When Hewlett-Packard Wanted to Distance Themselves From the Competition ST's Systems-on-Silicon Gave Them a Head Start"	Qu	Infrng/Non-infrng	Admitted
CX	2004		ST Website - Testimonials - Jeep - "We Helped The Jeep Platform Create Roadmaps to Systems Solutions with Our Advanced Silicon"	Qu	Infrng/Non-infrng	Admitted
CX	2005		ST Website - Testimonials - Lutron	Qu	Infrng/Non-infrng	Admitted
CX	2006		ST Website - Testimonials - Pace	Qu	Infrng/Non-infrng	Admitted
CX	2007		ST Website - Testimonials - Pioneer - "Pioneer Car Audion Sound Found the Road to Higher Powe with ST's Advanced Systems-on-Silicon"	Qu	Infrng/Non-infrng	Admitted
CX	2008		ST Website - Testimonials - RCA - "Now Showing! Theater-Quality Movies with RCA Digital TV's Featuring ST Systems on-Silicon"	Qu	Infrng/Non-infrng	Admitted
CX	2009		ST Website - Testimonials - Schlumberger	Qu	Infrng/Non-infrng	Admitted
CX	2010		ST Website - Testimonials - Scientific-Atlanta - "When Scientific-Atlanta wanted to get on the multimedia superhighway ... ST's Systems-on-Silicon helped to pave the way"	Qu	Infrng/Non-infrng	Admitted
CX	2011		ST Website - Testimonials - Siemens	Qu	Infrng/Non-infrng	Admitted
CX	2012		ST Website - Testimonials - Visa	Qu	Infrng/Non-infrng	Admitted
CX	2013		ST Website - Testimonials - Visteon	Qu	Infrng/Non-infrng	Admitted
CX	2014		STMicroelectronics and IDEX Announce Agreement to Develop Fingerprint Recognition and Pointer Technology for the Wireless Market	Hundt, Qu, Tessera Corporate Designee	Remedy, Vldy/Invldy	Admitted
CX	2015		STMicroelectronics Announces Shipment of Two Million Chipsets for XM Satellite Radio Receivers; Delivers Latest System-on-Chip Solution	Qu	Remedy, Vldy/Invldy	Admitted
CX	2016		STMicroelectronics N.V. Company Presentation	Hundt, Qu, Tessera Corporate Designee	Infrng/Non-infrng, Remedy	Admitted
CX	2017		STMicroelectronics Receives Best Supplier Award from Seagate	Hundt, Qu, Tessera Corporate Designee	Remedy, Vldy/Invldy	Admitted
CX	2018					Withdrawn
CX	2019					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2020					Withdrawn
CX	2021		STMicroelectronics Rises in Buoyant Automotive Market	Hundt, Qu, Tessera Corporate Designee	Remedy, Vldy/Invldy	Admitted
CX	2022		STMicroelectronics Ships 355,000 XM Satellite Radio Chipsets to Radio Manufacturers	Hundt, Qu, Tessera Corporate Designee	Remedy, Vldy/Invldy	Admitted
CX	2023		STMicroelectronics Ships One-Millionth XM Satellite Radio Chipset to Radio Manufacturers	Hundt, Qu, Tessera Corporate Designee	Remedy, Vldy/Invldy	Admitted
CX	2024		STMicroelectronics Sustainable Development Report 2003	Hundt, Qu, Tessera Corporate Designee	Remedy, Vldy/Invldy	Admitted
CX	2025		Strategic Alliances and Industry Partnerships	Hundt, Qu, Tessera Corporate Designee	Remedy, Vldy/Invldy	Admitted
CX	2026		STw5095 Low-power asynchronous stereo audio Codec with integrated power amplifiers Features	Hundt, Qu, Tessera Corporate Designee	Remedy, Vldy/Invldy	Admitted
CX	2027		STw5095/E01 STw5095 evaluation board Features	Qu	INFRNG/NON-INFRNG	Admitted
CX	2028		Technical Datasheet for Hitachi Chemical Die Bonding Pastes	Qu	INFRNG/NON-INFRNG	Admitted
CX	2029		Technical Datasheet for Loctite Die Attach Materials	Qu	INFRNG/NON-INFRNG	Admitted
CX	2030					Withdrawn
CX	2031		Two More World Leaderships Confirmed for STMicroelectronics	Qu	Infrng/Non-infrng	Admitted
CX	2032		Unprecedented Alliance Created for Breakthrough Semiconductor R&D	Qu	Infrng/Non-infrng	Admitted
CX	2033					Withdrawn
CX	2034		World First for Sagem Communication and STMicroelectronics: First MPEG4 Set-Top Boxes Based on Single-Chip Video Decoder	Hundt, Qu, Tessera Corporate Designee	Remedy, Vldy/Invldy	Admitted
CX	2035					Withdrawn
CX	2036					Withdrawn
CX	2037	C	Hundt Deposition - March 28, 2007 - Exhibit 233 - Email regarding Micro BGA Evaluation Test Plan	Hundt	INFRNG/NON-INFRNG	Admitted
CX	2038	C	01/11/08 Letter from Nokia to Anthony Downs and suppl. response/objection with sales papers	Qu	Infrng/Non-infrng	Admitted
CX	2039	C	Hundt Deposition - March 28, 2007 - Exhibit 225 - Document entitled, "Solder Joint Reliability Modeling of Sirius Radio LBGA288"	Hundt	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2040		Hundt Deposition - March 28, 2007 - Exhibit 227 - Definitions - "Geometric Dimensions" and "Material Properties"	Hundt	INFRNG/NON-INFRNG	Admitted
CX	2041	C	Hundt Deposition - March 29, 2007 - Exhibit 236 - Extract of Master Spreadsheet of BGA Shipments	Hundt	INFRNG/NON-INFRNG	Admitted
CX	2042	C	Hundt Deposition - October 18, 2006 - Exhibit 7 - Dec. of Michael J. Hundt re So Called Exemplary Products	Hundt	INFRNG/NON-INFRNG	Admitted
CX	2043	C	Hundt Deposition - October 18, 2006 - Exhibit 8 - Dec. of Michael J. Hundt pursuant to paragraph 1B& 2A of the 9-08-06 Order	Hundt	INFRNG/NON-INFRNG	Admitted
CX	2044	C	Letter from David Young to Sony Ericsson attaching list with boxes drawn around accusable ST chips	Qu	Infrng/Non-infrng	Admitted
CX	2045	C	Letter From Nokia to Anthony Downs and response/objection with Attachment A listing respondents' chips in Nokia products	Qu	Infrng/Non-infrng	Admitted
CX	2046	C	Letter from Sony Ericsson to David Young attaching list of ST chips	Qu	Infrng/Non-infrng	Admitted
CX	2047	C	Letter from Sony Ericsson to David Young attaching spreadsheet of ST chips	Qu	Infrng/Non-infrng	Admitted
CX	2048					Withdrawn
CX	2049					Withdrawn
CX	2050					Withdrawn
CX	2051	C	Respondent Motorola, Inc.'s Confidential Responses and Objections to Complainant Tessera's First Set of Interrogatories (1-5)	Stipulation	Infrng/Non-infrng	Admitted
CX	2052	C	Respondent Motorola, Inc.'s Fourth Amended Confidential Responses and Objections to Complainant Tessera's First set of Interrogatories (1-5)	Stipulation	Infrng/Non-infrng	Admitted
CX	2053	C	Respondent Motorola, Inc.'s Fourth Amended Confidential Responses and Objections to Complainant Tessera's Second Set of Interrogatories (6-20)	Stipulation	Infrng/Non-infrng	Admitted
CX	2054	C	Respondent Motorola, Inc.'s Responses to Complainant Tessera's Amended Fifth Set of Interrogatories (32-79)	Stipulation	Infrng/Non-infrng	Admitted
CX	2055					Withdrawn
CX	2056	C	Respondent STMicroelectrics N.V.'s Responses to Tessera's Second Set of Interrogatorries (6 - 20)	Stipulation	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2057	C	Respondent STMicroelectronics N.V.'S Response to Tessera's Second Set of Requests for Admission	Stipulation	Infrng/Non-infrng	Admitted
CX	2058	C	Respondent STMicroelectronics N.V.'s First Amended Response to Tessera's First Set of Requests for Admission	Stipulation	Infrng/Non-infrng	Admitted
CX	2059	C	Respondent STMicroelectronics N.V.'s Response to Tessera's First Set of Requests for Admission	Stipulation	Infrng/Non-infrng	Admitted
CX	2060		Respondent STMicroelectronics N.V.'s Responses to Tessera's First Set of Interrogatories (1 - 5)	Stipulation	Infrng/Non-infrng	Admitted
CX	2061	C	Response and Objections of Sony Ericsson Mobile Communications (USA) Inc. to Subpoena Ad Tesitificandum (sic)	Qu	Infrng/Non-infrng	Admitted
CX	2062		Response and Objections of Sony Ericsson Mobile Communications (USA) Inc. to Subpoena Duces Tecum	Qu	Infrng/Non-infrng	Admitted
CX	2063		Response of ST-NV to the Complaint, as Supplemented, Under Section 337 of the Tariff Act of 1930, as Amended	Shah		Admitted
CX	2064		Seagate Technology LLC's Objections and Response to Subpoena Duces Tecum and Subpoena Ad Testificandum	Qu	Infrng/Non-infrng	Admitted
CX	2065					Withdrawn
CX	2066	C	ST-NV's Response to Tessera's Seventh Set of Interrogatories, No. 71	Stipulation	Infrng/Non-infrng	Admitted
CX	2067	C	ST's 1st Amended Response to Tessera's First Set of Interrogatories, Nos. 1-5	Stipulation	Infrng/Non-infrng	Admitted
CX	2068	C	Supplemental Responses of Sony Ericsson Mobile Communications (USA) Inc. to Subpoena Duces Tecum	Qu	Infrng/Non-infrng	Admitted
CX	2069					Withdrawn
CX	2070					Withdrawn
CX	2071					Withdrawn
CX	2072	C	Chart of Top Parent, Supplier Parent, Part descriptions	Stipulation	Importation, Remedies	Admitted
CX	2073	C	Network Business Segment Motorola Part Numbers	Stipulation	Importation, Remedies	Admitted
CX	2074	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2075	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2076	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2077	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2078	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2079	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2080	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2081	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2082	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2083	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2084	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2085	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2086	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2087	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2088	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2089	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2090	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2091	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2092	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2093	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted
CX	2094	C	Spreadsheet showing import entry data	Stipulation	Importation, Remedies	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2095	C	Spreadsheet showing monthly sales for various parts for 2007	Stipulation	Importation, Remedies	Admitted
CX	2096					Withdrawn
CX	2097					Withdrawn
CX	2098					Withdrawn
CX	2099	C	ATI's Amended Responses to Tessera's First Set of Interrogatories (#1, 2, 3 and 5)	Stipulation	Importation, Remedies	Admitted
CX	2100	C	ATI's Amended Responses to Tessera's Second Set of Interrogatores (#6-8, #10-12, 17, 19-20)	Stipulation	Importation, Remedies	Admitted
CX	2101		ATI's Responses to Tessera's Fifth Set of Interrogatories (#32-79)	Stipulation	Importation, Remedies	Admitted
CX	2102		ATI's Responses to Tessera's First Set of Interrogatories (#1-5)	Stipulation	Importation, Remedies	Admitted
CX	2103	C	ATI's Responses to Tessera's First Set of Requests for Admissions (#1-3)	Stipulation	Importation, Remedies	Admitted
CX	2104	C	ATI's Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2105	C	ATI's Second Amended Responses to Tessera's First Set of Interrogatories (#1, 2, 3 and 5)	Stipulation	Importation, Remedies	Admitted
CX	2106	C	ATI's Second Amended Responses to Tessera's Second Set of Interrogatores (#6-8, #10-12, 17, 19-20)	Stipulation	Importation, Remedies	Admitted
CX	2107		ATI's Supplemental Responses to Tessera's Fifth Set of Interrogatories (37-39, 41 and 42)	Stipulation	Importation, Remedies	Admitted
CX	2108	C	Frankel Deposition Exhibit #002, Qualcomm's Fourth Supplemental Responses to Tessera's First Set of Interrogatories (#1-5)	Frankel	Importation, Remedies	Admitted
CX	2109	C	Freescale's Responses to Tessera's Amended Fifth Set of Interrogatories (#32-83)	Stipulation	Importation, Remedies	Admitted
CX	2110	C	Freescale's Responses to Tessera's First Request for Admissions (#1-3)	Stipulation	Importation, Remedies	Admitted
CX	2111	C	Freescale's Responses to Tessera's First Set of Interrogatories (#1-5) including attached Schedule A	Stipulation	Importation, Remedies	Admitted
CX	2112	C	Freescale's Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2113	C	Freescale's Second Supplemental Responses to Tessera's First Set of Interrogatories (#1) including attached Schedule A	Stipulation	Importation, Remedies	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2114	C	Freescale's Supplemental Response to Tessera's First Request for Admissions (#2-3)	Stipulation	Importation, Remedies	Admitted
CX	2115	C	Freescale's Supplemental Responses to Tessera's First Set of Interrogatories (#1-5) including attached Schedule A	Montgomery	Importation, Remedies	Admitted
CX	2116	C	Freescale's Supplemental Responses to Tessera's Second Set of Interrogatories (#6-20)	Montgomery	Importation, Remedies	Admitted
CX	2117	C	Motorla's Supplemental Response to Tessera's Interrogatories #20, 32, 36, 40, and 51 including Appendices	Stipulation	Importation, Remedies	Admitted
CX	2118	C	Motorola's Amended Responses to Tessera's First Set of Interrogatories (#1-5) including Appendices A-G	Stipulation	Importation, Remedies	Admitted
CX	2119	C	Motorola's Amended Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2120	C	Motorola's Fourth Amended Responses to Tessera's First Set of Interrogatories (#1-5) including Appendices	Stipulation	Importation, Remedies	Admitted
CX	2121	C	Motorola's Fourth Amended Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2122	C	Motorola's Responses to Tessera's Amended Fifth Set of Interrogatories (32-79)	Stipulation	Importation, Remedies	Admitted
CX	2123	C	Motorola's Responses to Tessera's First Request for Admissions (#2-3)	Stipulation	Importation, Remedies	Admitted
CX	2124	C	Motorola's Responses to Tessera's First Set of Interrogatories (#1-5) including Appendices A-G	Stipulation	Importation, Remedies	Admitted
CX	2125	C	Motorola's Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2126	C	Motorola's Second Amended Responses to Tessera's First Set of Interrogatories (#1-5) including Appendices	Stipulation	Importation, Remedies	Admitted
CX	2127	C	Motorola's Second Amended Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2128	C	Motorola's Third Amended Responses to Tessera's First Set of Interrogatories (#1-5) including Appendices	Stipulation	Importation, Remedies	Admitted
CX	2129	C	Motorola's Third Amended Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2130	C	Qualcomm's Response to Tessera's First Request for Admissions (#1-4)	Stipulation	Importation, Remedies	Admitted
CX	2131	C	Qualcomm's Responses to Tessera's Amended Fifth Set of Interrogatories (#32-84)	Stipulation	Importation, Remedies	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2132	C	Qualcomm's Responses to Tessera's First Set of Interrogatories (#1-5)	Stipulation	Importation, Remedies	Admitted
CX	2133	C	Qualcomm's Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2134	C	Qualcomm's Revised Appendix B in Response to Tessera's First Set of Interrogatories (#1-5)	Stipulation	Importation, Remedies	Admitted
CX	2135	C	Qualcomm's Second Revised Appendix A in Response to Tessera's First Set of Interrogatories (#1-5)	Stipulation	Importation, Remedies	Admitted
CX	2136	C	Qualcomm's Second Supplemental Responses to Tessera's First Set of Interrogatories (#1-5)	Stipulation	Importation, Remedies	Admitted
CX	2137	C	Qualcomm's Second Supplemental Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2138	C	Qualcomm's Supplemental Responses to Tessera's Amended Fifth Set of Interrogatories (#32-84)	Stipulation	Importation, Remedies	Admitted
CX	2139	C	Qualcomm's Supplemental Responses to Tessera's First Set of Interrogatories (#1-5)	Stipulation	Importation, Remedies	Admitted
CX	2140	C	Qualcomm's Supplemental Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2141	C	Qualcomm's Third Supplemental Responses to Tessera's First Set of Interrogatories (#1-5)	Stipulation	Importation, Remedies	Admitted
CX	2142	C	Spansion's Response to Tessera's First Request for Admissions (#1-3)	Stipulation	Importation, Remedies	Admitted
CX	2143	C	Spansion's Responses to Tessera's Fifth Set of Interrogatories (#32-79)	Stipulation	Importation, Remedies	Admitted
CX	2144	C	Spansion's Responses to Tessera's First Set of Interrogatories (#1-5)	Stipulation	Importation, Remedies	Admitted
CX	2145	C	Spansion's Responses to Tessera's Second Set of Interrogatories (#6-20)	Stipulation	Importation, Remedies	Admitted
CX	2146	C	Spansion's Supplemental Responses to Tessera's First Set of Interrogatories (#1-5)	Stipulation	Importation, Remedies	Admitted
CX	2147					Withdrawn
CX	2148					Withdrawn
CX	2149					Withdrawn
CX	2150					Withdrawn
CX	2151					Withdrawn
CX	2152					Withdrawn
CX	2153					Withdrawn
CX	2154					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2155					Withdrawn
CX	2156					Withdrawn
CX	2157	C	Amkor Reliability Test Report for CZBGA 10x10/179LD for Qual	Qu	Infrng/Non-infrng	Admitted
CX	2158	C	Amkor Reliability Test Report for SCSP 10x10/259 LD for Qual	Qu	Infrng/Non-infrng	Admitted
CX	2159	C	ASE Group Reliability Test Report for Qualification Test of STKLFBGA (10x10) 2591 for AMD	Qu	Infrng/Non-infrng	Admitted
CX	2160					Withdrawn
CX	2161					Withdrawn
CX	2162	C	Reliability Test Report for ATI Package VFBGA (10*10) 191L	Qu	Infrng/Non-infrng	Admitted
CX	2163	C	Reliability Test Report for Qualification Test of LFBGA (12X12) 272L	Qu	Infrng/Non-infrng	Admitted
CX	2164	C	Reliability Test Report for Qualification Test of STKLFBGA (10x10) 259L for ATI	Qu	Infrng/Non-infrng	Admitted
CX	2165	C	Reliability Test Report for Reliability Test of TFBGA (8x0) 104L for ATI	Qu	Infrng/Non-infrng	Admitted
CX	2166	C	SPIL Reliability Test Interim Report for ATI-CA STFBGA259(10x10)(LF)Device:W228 QUAL	Qu	Infrng/Non-infrng	Admitted
CX	2167	C	SPIL Reliability Test Report for ATI W2182 New Device Qual	Qu	Infrng/Non-infrng	Admitted
CX	2168					Withdrawn
CX	2169					Withdrawn
CX	2170					Withdrawn
CX	2171	C	2600BT.pdf	Qu	Infrng/Non-infrng	Admitted
CX	2172		Abletherm 2600BT.pdf	Qu	Infrng/Non-infrng	Admitted
CX	2173	C	Absorbond - Datasheet - Rev7.pdf	Qu	Infrng/Non-infrng	Admitted
CX	2174					Withdrawn
CX	2175					Withdrawn
CX	2176					Withdrawn
CX	2177					Withdrawn
CX	2178					Withdrawn
CX	2179					Withdrawn
CX	2180					Withdrawn
CX	2181					Withdrawn
CX	2182					Withdrawn
CX	2183					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
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CX	2185					Withdrawn
CX	2186					Withdrawn
CX	2187					Withdrawn
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CX	2216					Withdrawn
CX	2217					Withdrawn
CX	2218					Withdrawn
CX	2219					Withdrawn
CX	2220					Withdrawn
CX	2221					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2222					Withdrawn
CX	2223					Withdrawn
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CX	2226					Withdrawn
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CX	2250					Withdrawn
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CX	2254					Withdrawn
CX	2255					Withdrawn
CX	2256					Withdrawn
CX	2257					Withdrawn
CX	2258					Withdrawn
CX	2259					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2260					Withdrawn
CX	2261					Withdrawn
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CX	2297					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2298					Withdrawn
CX	2299					Withdrawn
CX	2300					Withdrawn
CX	2301					Withdrawn
CX	2302					Withdrawn
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CX	2335					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2336					Withdrawn
CX	2337					Withdrawn
CX	2338					Withdrawn
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CX	2369					Withdrawn
CX	2370					Withdrawn
CX	2371					Withdrawn
CX	2372					Withdrawn
CX	2373					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2374					Withdrawn
CX	2375					Withdrawn
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CX	2400					Withdrawn
CX	2401					Withdrawn
CX	2402					Withdrawn
CX	2403					Withdrawn
CX	2404					Withdrawn
CX	2405	C	Product Description for Ablebond 2100A, Electrically Conductive Adhesive for PBGA	Qu	Infrng/Non-infrng	Admitted
CX	2406	C	Product Description for Ablebond 2100A, Electrically Conductive Adhesive for PBGA	Qu	Infrng/Non-infrng	Admitted
CX	2407	C	Product Description for Ablebond 8360, Electrically Conductive Die Attach Adhesive	Qu	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2408	C	Product Description for Ablebond 8510AA, Fast Cure Die Attach Adhesive	Qu	Infrng/Non-infrng	Admitted
CX	2409					Withdrawn
CX	2410					Withdrawn
CX	2411					Withdrawn
CX	2412					Withdrawn
CX	2413					Withdrawn
CX	2414					Withdrawn
CX	2415					Withdrawn
CX	2416					Withdrawn
CX	2417					Withdrawn
CX	2418					Withdrawn
CX	2419					Withdrawn
CX	2420					Withdrawn
CX	2421					Withdrawn
CX	2422					Withdrawn
CX	2423					Withdrawn
CX	2424					Withdrawn
CX	2425					Withdrawn
CX	2426					Withdrawn
CX	2427	C	98K03 LAA064 1mm FBGA Package Qualification	Qu	Infrng/Non-infrng	Admitted
CX	2428	C	98K03 LAA064 1mm FBGA Package Qualification RQ4688	Qu	Infrng/Non-infrng	Admitted
CX	2429					Withdrawn
CX	2430					Withdrawn
CX	2431					Withdrawn
CX	2432					Withdrawn
CX	2433	C	LAA064 Package Qualification	Qu	Infrng/Non-infrng	Admitted
CX	2434	C	PDL128G Package Options by Valluri and Suresh	Qu	Infrng/Non-infrng	Admitted
CX	2435	C	Reliability Qualification re Package FTA084	Qu	Infrng/Non-infrng	Admitted
CX	2436	C	Reliability Qualification re Package LAA064	Qu	Infrng/Non-infrng	Admitted
CX	2437					Withdrawn
CX	2438					Withdrawn
CX	2439					Withdrawn
CX	2440					Withdrawn
CX	2441					Withdrawn
CX	2442					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2443	C	Email string from A. Simphliphan to Various Recipients re D/A design rules evaluation (Sent 5:08 AM)	Suresh	INFRNG/NON-INFRNG	Admitted
CX	2444					Withdrawn
CX	2445					Withdrawn
CX	2446					Withdrawn
CX	2447					Withdrawn
CX	2448					Withdrawn
CX	2449					Withdrawn
CX	2450					Withdrawn
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CX	2474					Withdrawn
CX	2475					Withdrawn
CX	2476					Withdrawn
CX	2477					Withdrawn
CX	2478					Withdrawn
CX	2479					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2480					Withdrawn
CX	2481					Withdrawn
CX	2482					Withdrawn
CX	2483					Withdrawn
CX	2484					Withdrawn
CX	2485					Withdrawn
CX	2486					Withdrawn
CX	2487					Withdrawn
CX	2488					Withdrawn
CX	2489					Withdrawn
CX	2490					Withdrawn
CX	2491	C	Reliability Qualification re Package FTA084	Qu	Infrng/Non-infrng	Admitted
CX	2492	C	Technical Drawings re Package FEA/TSD 084	Qu	Infrng/Non-infrng	Admitted
CX	2493	C	Technical Drawings re Package FTA084	Qu	Infrng/Non-infrng	Admitted
CX	2494	C	Technical Drawings re Package FTA084	Qu	Infrng/Non-infrng	Admitted
CX	2495					Withdrawn
CX	2496					Withdrawn
CX	2497	C	Motorola's Third Amended Responses and Objections to Tessera's First Set of Interrogatories (1-5)	Stipulation	Importation, Remedies	Admitted
CX	2498					Withdrawn
CX	2499					Withdrawn
CX	2500					Withdrawn
CX	2501		Facsimile from J. Smith to R. Bowlby regarding Proposed License to Tessera patents	Pickett	RMDY, OWNR	Admitted
CX	2502					Withdrawn
CX	2503					Withdrawn
CX	2504					Withdrawn
CX	2505					Withdrawn
CX	2506					Withdrawn
CX	2507					Withdrawn
CX	2508					Withdrawn
CX	2509					Withdrawn
CX	2510					Withdrawn
CX	2511					Withdrawn
CX	2512					Withdrawn
CX	2513					Withdrawn
CX	2514					Withdrawn
CX	2515					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2516					Withdrawn
CX	2517					Withdrawn
CX	2518					Withdrawn
CX	2519					Withdrawn
CX	2520					Withdrawn
CX	2521					Withdrawn
CX	2522					Withdrawn
CX	2523					Withdrawn
CX	2524					Withdrawn
CX	2525					Withdrawn
CX	2526	C	Letter from L. Pfulghaupt to R. Warren regarding forwarding information about uBGA electronic chip packaging	Pickett	RMDY, OWNR	Admitted
CX	2527					Withdrawn
CX	2528					Withdrawn
CX	2529					Withdrawn
CX	2530					Withdrawn
CX	2531					Withdrawn
CX	2532					Withdrawn
CX	2533					Withdrawn
CX	2534					Withdrawn
CX	2535					Withdrawn
CX	2536					Withdrawn
CX	2537					Withdrawn
CX	2538					Withdrawn
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CX	2540					Withdrawn
CX	2541					Withdrawn
CX	2542					Withdrawn
CX	2543					Withdrawn
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CX	2545					Withdrawn
CX	2546					Withdrawn
CX	2547					Withdrawn
CX	2548					Withdrawn
CX	2549					Withdrawn
CX	2550					Withdrawn
CX	2551					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2552					Withdrawn
CX	2553					Withdrawn
CX	2554					Withdrawn
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CX	2556					Withdrawn
CX	2557					Withdrawn
CX	2558					Withdrawn
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CX	2583					Withdrawn
CX	2584					Withdrawn
CX	2585					Withdrawn
CX	2586					Withdrawn
CX	2587					Withdrawn
CX	2588					Withdrawn
CX	2589					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2590					Withdrawn
CX	2591					Withdrawn
CX	2592	C	First Amendment to Intel and Tessera Limited TCC License Agreement	Pickett	RMDY, OWNR	Admitted
CX	2593	C	IBM/MHT/Tessera Confidentiality Agreement	Pickett	RMDY, OWNR	Admitted
CX	2594	C	Letter & Memorandum of Understanding between IBM & Tessera	Pickett	RMDY, OWNR	Admitted
CX	2595					Withdrawn
CX	2596					Withdrawn
CX	2597					Withdrawn
CX	2598	C	Claim Chart for Respondent ATI	Qu	INFRNG/NON-INFRNG	Admitted
CX	2599	C	Claim Chart for Respondent Freescale	Qu	INFRNG/NON-INFRNG	Admitted
CX	2600	C	Claim Chart for Respondent Motorola	Qu	INFRNG/NON-INFRNG	Admitted
CX	2601	C	Claim Chart for Respondent Qualcomm	Qu	INFRNG/NON-INFRNG	Admitted
CX	2602	C	Claim Chart for Respondent Spansion	Qu	INFRNG/NON-INFRNG	Admitted
CX	2603	C	Claim Chart for Respondent ST, N.V	Qu	INFRNG/NON-INFRNG	Admitted
CX	2604					Withdrawn
CX	2605		CX-2605 - Mawer "Plastic Ball Grid Array (PBGA)," Motorola Semiconductor Technical Data	Ivey / Sitaraman	VLD/INVLD, INFRNG/NON-INFRNG.	Admitted
CX	2606					Withdrawn
CX	2607	C	Witness Statement of Christopher Pickett	Pickett	OWNR	Admitted
CX	2608	C	CX-2608C - Witness Statement for Mitchell	Mitchell	RMDY, DI	Admitted
CX	2609	C	Witness Statement for Marucci	Marcucci	RMDY	Admitted
CX	2610					Withdrawn
CX	2611					Withdrawn
CX	2612					Withdrawn
CX	2613					Withdrawn
CX	2614	C	Suhir Deposition Exhibit #159, Declaration of Dr. Ephraim Suhir	Ivey	Vldy/Invldy	Admitted
CX	2615		Ablestik Semiconductor Packaging Materials Product Selector Guide	Qu	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2616		Ablestik Technical Data Sheet for Ablebond 2000 Electrically Conductive Adhesive for PBGA	Qu	Infrng/Non-infrng	Admitted
CX	2617	C	Ablestik Pilot Technical Datasheet for Ablebond 2000B Electrically Conductive Adhesive for PBGA	Qu	Infrng/Non-infrng	Admitted
CX	2618		Ablestik Technical Data Sheet for Ablebond 2000T Electrically Conductive Epoxy Adhesive	Qu	Infrng/Non-infrng	Admitted
CX	2619		Ablestik Technical Data Sheet for Ablebond 2025D High Performance Adhesive for Array Packaging	Qu	Infrng/Non-infrng	Admitted
CX	2620		Ablestik Technical Data Sheet for Ablebond 2025DSI High Reliability Non-Conductive Die Attach Adhesive	Qu	Infrng/Non-infrng	Admitted
CX	2621		Ablestik Technical Data Sheet for Ablebond 2100A Electrically Conductive Adhestive for PBGA	Qu	Infrng/Non-infrng	Admitted
CX	2622		Ablestik Technical Data Sheet for Ablebond 2300 Electrically Conductive Adhestive for PBGA	Qu	Infrng/Non-infrng	Admitted
CX	2623		Ablestik Technical Data Sheet for Ablebond 8355F Electrically Conductie Die Attach Adhesive	Qu	Infrng/Non-infrng	Admitted
CX	2624		Ablestik Technical Data Sheet for Ablebond 8510AA Fast Cure Die Attach Adhesive	Qu	Infrng/Non-infrng	Admitted
CX	2625					Withdrawn
CX	2626		Loctite Technical Data Sheet for Hysol QMI 536, Non-Electrically Conductive Adhesive	Qu	Infrng/Non-infrng	Admitted
CX	2627	C	Loctite Technical Data Sheet for Hysol QMI 546 Non-Electrically Conductie Adhesive	Qu	Infrng/Non-infrng	Admitted
CX	2628		Ablestik Website List of Products	Qu	Infrng/Non-infrng	Admitted
CX	2629	C	Frankel Deposition Exhibit #008, Email from R. Tessitore to T. Gregorich	Frankel	RMDY	Admitted
CX	2630	C	2000-2000B-2100A-2300 Comparison	Qu	Infrng/Non-infrng	Admitted
CX	2631		Ablebond 2100A Technical Data Sheet	Qu	Infrng/Non-infrng	Admitted
CX	2632	C	Ablebond 2100A Data Package	Qu	Infrng/Non-infrng	Admitted
CX	2633	C	Ablestik 2053	Qu	Infrng/Non-infrng	Admitted
CX	2634	C	Hitachi CEL 9200	Qu	Infrng/Non-infrng	Admitted
CX	2635	C	Hitachi CEL 9200ZHF10FA, 9700HF10 9700ZHF10 Report	Qu	Infrng/Non-infrng	Admitted
CX	2636	C	CRM 1525 and 1580A	Qu	Infrng/Non-infrng	Admitted
CX	2637	C	CRM 1525 Thermal Die Attaches	Qu	Infrng/Non-infrng	Admitted
CX	2638	C	CRM 1525 Catalog	Qu	Infrng/Non-infrng	Admitted
CX	2639	C	CRM 1560 Catalog	Qu	Infrng/Non-infrng	Admitted
CX	2640	C	CRM 1580A and DC 7920 Material Properties	Qu	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2641	C	CRM 1580A Version 2	Qu	Infrng/Non-infrng	Admitted
CX	2642	C	CRM 1580A	Qu	Infrng/Non-infrng	Admitted
CX	2643	C	FH-900 Material Safety Data Sheet	Qu	Infrng/Non-infrng	Admitted
CX	2644	C	FH-900 Presentation	Qu	Infrng/Non-infrng	Admitted
CX	2645	C	Freescale Die Attach Thickness	Qu	Infrng/Non-infrng	Admitted
CX	2646	C	Sumitomo - G760 Material Specifications	Qu	Infrng/Non-infrng	Admitted
CX	2647	C	Hitachi CEL 9750HF 10 AK	Qu	Infrng/Non-infrng	Admitted
CX	2648	C	Hitachi Technical Data Sheet for CEL 9200HF 10 FA	Qu	Infrng/Non-infrng	Admitted
CX	2649	C	Hitachi E679 Lineup design guide	Qu	Infrng/Non-infrng	Admitted
CX	2650	C	Hitachi E679FBG	Qu	Infrng/Non-infrng	Admitted
CX	2651	C	Hitachi H230 Series (HS-231, HS-232) Product Description	Qu	Infrng/Non-infrng	Admitted
CX	2652	C	HS-231 and HS-232 Safety Data Sheet	Qu	Infrng/Non-infrng	Admitted
CX	2653		AMTECH Advanced SMT Solder Products, Product Data Sheet for Premium Case Bar Solder AMT 105	Qu	Infrng/Non-infrng	Admitted
CX	2654	C	Nitto GE-100L	Qu	Infrng/Non-infrng	Admitted
CX	2655	C	Nitto GE-100LFCS-V	Qu	Infrng/Non-infrng	Admitted
CX	2656	C	Sumitomo Bakelite Sumikon, EME-G760 Type SY	Qu	Infrng/Non-infrng	Admitted
CX	2657	C	Sumitomo Bakelite Sumikon, EME-G770	Qu	Infrng/Non-infrng	Admitted
CX	2658	C	Specification for HS-231	Qu	Infrng/Non-infrng	Admitted
CX	2659	C	Specification for HS-232	Qu	Infrng/Non-infrng	Admitted
CX	2660	C	Specification for FH-900T-40 Die Attach	Qu	Infrng/Non-infrng	Admitted
CX	2661	C	Specification for FH-900T-20 Die Attach	Qu	Infrng/Non-infrng	Admitted
CX	2662	C	Shinetsu Specification for Epoxy Molding Compound, KMC-358OLVA	Qu	Infrng/Non-infrng	Admitted
CX	2663	C	Shinetsu Material Safety Data Sheet for KMVC-358OLVA	Qu	Infrng/Non-infrng	Admitted
CX	2664	C	Markman Order (8 May 2007) in *Tessera, Inc. (USA) v. Amkor Technology, Inc. (USA),* Case No ICC 14265/EBS	Qu	INFRNG/NON-INFRNG	Admitted
CX	2665	C	ATI's Responses to Tessera's Seventh Set of Interrogatories	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2666					Withdrawn
CX	2667		ATI's Responses to Tessera's Third Set of Interrogatories	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2668	C	Expert Rebuttal Report of Peter Ivey, Exhibit 5 - AMICON C 990 J SPEC 333 M 1, Technical Data Sheet for Electrically Conductive Epoxy Adhesive for Microelectronics	Ivey	VLD/INVLD	Admitted
CX	2669		Expert Rebuttal Report of Peter Ivey, Exhibit 6 - Declaration of Glenn Urbish in *In re Reexamination of U.S. Patent No. 6,433,419*	Ivey	VLD/INVLD	Admitted
CX	2670	C	Expert Rebuttal Report of Peter Ivey, Exhibit 8 - Tessera's Proposed Claim Constructions for the Disputed Claim Terms	Qu / Ivey	INFRNG/NON-INFRNG, VLD/INVLD	Admitted
CX	2671					Withdrawn
CX	2672	C	Freescale's Responses to Tessera's Third Set of Interrogatories	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2673					Withdrawn
CX	2674					Withdrawn
CX	2675					Withdrawn
CX	2676					Withdrawn
CX	2677					Withdrawn
CX	2678					Withdrawn
CX	2679					Withdrawn
CX	2680		"Development of Low Elastic Modulus Die Attach Material and Clean Cure Process," by K. Suzuki, et al., Electronic Components and Technology Conference Proceedings, 40th	Ivey	VLD/INVLD	Admitted
CX	2681					Withdrawn
CX	2682		"Die Attach Reliability Prediction," K. Heinen, 1st International SAMPE Electronics Conference	Ivey	VLD/INVLD	Admitted
CX	2683		"Die Attachment Design and Its Influence on Thermal Stresses in the Die and the Attachment," by E. Suhir, Electronic Components Conference Proceedings, 37th	Ivey / Qu	INFRNG/NON-INFRNG, VLD/INVLD	Admitted
CX	2684					Withdrawn
CX	2685					Withdrawn
CX	2686		"Finite Element Analysis of Compliant Coating," by F. Shoraka, et al., Electronic Components Conference Proceedings, 38th IEEE 0569-5503/88/0000-0461	Ivey	VLD/INVLD	Admitted
CX	2687					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2688		"Flexible Silicone Adhesive with High Electrical Conductivity," by M. Lutz and R. Cole, Electronic Components Conference Proceedings, 39th, IEEE 0569-5503/89/0083	Ivey	VLD/INVLD	Admitted
CX	2689					Withdrawn
CX	2690		"High Reliability Mechanism of New Silicone Gel Sealing in Accelerated Environment Test," by K. Otsuka, et al., Proceedings of the Sixth Annual International Electronics Packaging Society Conference	Ivey	VLD/INVLD	Admitted
CX	2691					Withdrawn
CX	2692					Withdrawn
CX	2693		"Method of Testing Chips and Joining Chips to Substrates," F.E. Doany, et al., IBM Technical Disclosure Bulletin	Ivey	VLD/INVLD	Admitted
CX	2694		"Microelectronics Packaging Handbook," by R. Tummala and E. Rymaszewski	Ivey	VLD/INVLD	Admitted
CX	2695					Withdrawn
CX	2696					Withdrawn
CX	2697					Withdrawn
CX	2698					Withdrawn
CX	2699					Withdrawn
CX	2700		Freescale's Responses to Tessera's Third Set of Interrogatories	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2701					Withdrawn
CX	2702					Withdrawn
CX	2703					Withdrawn
CX	2704					Withdrawn
CX	2705					Withdrawn
CX	2706					Withdrawn
CX	2707					Withdrawn
CX	2708					Withdrawn
CX	2709		Hinrichsmeyer, IBM Technical Disclosure Bulletin	Ivey	VLD/INVLD	Admitted
CX	2710		"Stress Management Via Low Modulus Urethane Adhesives for Electronic Applications," by J. Vaccaro, Hybrid Circuit Technology	Ivey	VLD/INVLD	Admitted
CX	2711					Withdrawn
CX	2712					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2713					Withdrawn
CX	2714					Withdrawn
CX	2715					Withdrawn
CX	2716					Withdrawn
CX	2717					Withdrawn
CX	2718					Withdrawn
CX	2719					Withdrawn
CX	2720					Withdrawn
CX	2721					Withdrawn
CX	2722					Withdrawn
CX	2723		Amendment (traversing rejections) for '419 patent	Ivey	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted
CX	2724					Withdrawn
CX	2725		Declaration of Glenn Urbish in '419 Patent Reexamination	Urbish	INFRNG/NON-INFRNG	Admitted
CX	2726					Withdrawn
CX	2727					Withdrawn
CX	2728					Withdrawn
CX	2729					Withdrawn
CX	2730					Withdrawn
CX	2731					Withdrawn
CX	2732					Withdrawn
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CX	2735					Withdrawn
CX	2736					Withdrawn
CX	2737					Withdrawn
CX	2738					Withdrawn
CX	2739					Withdrawn
CX	2740					Withdrawn
CX	2741		Expert Rebuttal Report of Peter Ivey, Exhibit 1 - CV of Professor Peter Ivey	Ivey	VLD/INVLD	Admitted
CX	2742		Expert Rebuttal Report of Peter Ivey, Exhibit 2 - Materials Considered	Ivey	VLD/INVLD	Admitted
CX	2743					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2744					Withdrawn
CX	2745					Withdrawn
CX	2746					Withdrawn
CX	2747					Withdrawn
CX	2748					Withdrawn
CX	2749					Withdrawn
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CX	2752					Withdrawn
CX	2753					Withdrawn
CX	2754					Withdrawn
CX	2755					Withdrawn
CX	2756					Withdrawn
CX	2757					Withdrawn
CX	2758		Japanese Patent Application No. 61-177759 (Okinaga) (including translation)	Ivey	VLD/INVLD	Admitted
CX	2759					Withdrawn
CX	2760					Withdrawn
CX	2761		Japanese Unexamined Patent Application No. 63-51196 (Saito) (including translation)	Ivey	VLD/INVLD	Admitted
CX	2762					Withdrawn
CX	2763					Withdrawn
CX	2764					Withdrawn
CX	2765		Motorola's Responses and Objections to Tessera's Third Set of Interrogatories	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2766		Notice of Allowability (approving Asserted Claims for Issue)	Ivey	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted
CX	2767					Withdrawn
CX	2768					Withdrawn
CX	2769					Withdrawn
CX	2770					Withdrawn
CX	2771					Withdrawn
CX	2772					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2773		Patent Office, Ex Parte Reexamination Filing Data	Ivey	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted
CX	2774		Patent Office, Inter Partes Reexamination Filing Data	Ivey	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted
CX	2775					Withdrawn
CX	2776					Withdrawn
CX	2777	C	Qualcomm's Response to Tessera's Third Set of Interrogatories	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2778					Withdrawn
CX	2779					Withdrawn
CX	2780					Withdrawn
CX	2781					Withdrawn
CX	2782					Withdrawn
CX	2783		Respondents' Proposed Construction of Disputed Claim Terms	Ivey	VLD/INVLD	Admitted
CX	2784					Withdrawn
CX	2785		Response to Official Action regarding Reexamination of '419 patent	Ivey	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted
CX	2786		Spansion's Responses to Tessera's Third Set of Interrogatories (21-30), August 29, 2007	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2787		Spansion's Responses to Tessera's Third Set of Interrogatories (21, 23), December 7, 2007	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2788		STMicroelectronic's Responses to Tessera's Third Set of Interrogatories	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2789		Supplemental Declaration of Ephraim Suhir in the Reexamination of U.S. Patent No. 6,433,419	Ivey, Mitchell and/or Griffin	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted
CX	2790		Tessera Supplemental Response in Reexamination of '419 patent	Ivey	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted
CX	2791	C	Tessera's First Supplemental Objections and Responses to Freescale's First Set of Interrogatories	Schaper	VLD/INVLD	Admitted
CX	2792					Withdrawn
CX	2793					Withdrawn
CX	2794					Withdrawn
CX	2795		U.S. Patent Application No. 07/586,758	Ivey	VLD/INVLD	Admitted
CX	2796		U.S. Patent Application No. 07/673,020	Ivey	VLD/INVLD	Admitted
CX	2797					Withdrawn
CX	2798					Withdrawn
CX	2799					Withdrawn
CX	2800					Withdrawn
CX	2801					Withdrawn
CX	2802		U.S. Patent No. 4,601,526 (White, et al.)	Ivey	VLD/INVLD	Admitted
CX	2803					Withdrawn
CX	2804					Withdrawn
CX	2805		U.S. Patent No. 4,700,276 (Freyman et al.)	Ivey	VLD/INVLD	Admitted
CX	2806					Withdrawn
CX	2807					Withdrawn
CX	2808					Withdrawn
CX	2809					Withdrawn
CX	2810					Withdrawn
CX	2811					Withdrawn
CX	2812					Withdrawn
CX	2813					Withdrawn
CX	2814					Withdrawn
CX	2815					Withdrawn
CX	2816					Withdrawn
CX	2817		U.S. Patent No. 4,975,765 (Ackerman, et al.)	Ivey	VLD/INVLD	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2818					Withdrawn
CX	2819					Withdrawn
CX	2820					Withdrawn
CX	2821					Withdrawn
CX	2822					Withdrawn
CX	2823		U.S. Patent No. 5,216,278 (Lin)	Sitaraman / Ivey	INFRNG/NON-INFRNG, VLD/INVLD	Admitted
CX	2824		U.S. Patent No. 5,241,133 (Mullen)	Freyman / Urbish	INFRNG/NON-INFRNG	Admitted
CX	2825					Withdrawn
CX	2826					Withdrawn
CX	2827					Withdrawn
CX	2828		U.S. Patent No. 5,679,977	Griffin / Ivey	RMDY, OWNR, VLD/INVLD	Admitted
CX	2829					Withdrawn
CX	2830					Withdrawn
CX	2831					Withdrawn
CX	2832					Withdrawn
CX	2833					Withdrawn
CX	2834					Withdrawn
CX	2835					Withdrawn
CX	2836					Withdrawn
CX	2837	C	Tessera, Inc.'s Objections and Responses to Spansion Inc. and Spansion LLC's First Set of Interrogatories (16), July 23, 2007	Schaper	VLD/INVLD	Admitted
CX	2838					Withdrawn
CX	2839					Withdrawn
CX	2840					Withdrawn
CX	2841					Withdrawn
CX	2842					Withdrawn
CX	2843					Withdrawn
CX	2844					Withdrawn
CX	2845					Withdrawn
CX	2846					Withdrawn
CX	2847					Withdrawn
CX	2848					Withdrawn
CX	2849					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2850					Withdrawn
CX	2851					Withdrawn
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CX	2858					Withdrawn
CX	2859					Withdrawn
CX	2860					Withdrawn
CX	2861					Withdrawn
CX	2862					Withdrawn
CX	2863					Withdrawn
CX	2864					Withdrawn
CX	2865					Withdrawn
CX	2866		R&D Magazine article, 100 Most Technologically Significant Products of theYear	Ivey	OWNR	Admitted
CX	2867		"High Density Plastic 672-pin Package Enhances the HG72G/E Gate Array and Embedded Array Family," Hitachi	Ivey	OWNR	Admitted
CX	2868		Electronic Design, "Chip-Scale Packages Bridge the Gap Between Bare Die and BGAs"	Ivey	OWNR	Admitted
CX	2869					Withdrawn
CX	2870		1995 Milton S. Kiver Awards: "And the Winners Are…"	Ivey	OWNR	Admitted
CX	2871		1996 Solid State Technology magazine article	Ivey	OWNR	Admitted
CX	2872					Withdrawn
CX	2873		1996 Electronic News article on Intel's adoption of Tessera technology	Ivey	OWNR	Admitted
CX	2874		1996 Electronic News article on Intel's adoption of Tessera technology	Ivey	OWNR	Admitted
CX	2875		The Red Herring - "The Top 100 Technology Companies 1997"	Ivey	OWNR	Admitted
CX	2876					Withdrawn
CX	2877					Withdrawn
CX	2878					Withdrawn
CX	2879					Withdrawn
CX	2880					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2881					Withdrawn
CX	2882					Withdrawn
CX	2883					Withdrawn
CX	2884					Withdrawn
CX	2885					Withdrawn
CX	2886					Withdrawn
CX	2887					Withdrawn
CX	2888		TESST 017178	Ivey	OWNR	Admitted
CX	2889					Withdrawn
CX	2890					Withdrawn
CX	2891					Withdrawn
CX	2892(A)					Withdrawn
CX	2892(B)					Withdrawn
CX	2892(C)					Withdrawn
CX	2892(D)		Advanced Packaging Award for Best New Product in Package Design and Analysis to Tessera	Ivey	VLD/INVLD	Admitted
CX	2892(E)					Withdrawn
CX	2893					Withdrawn
CX	2894					Withdrawn
CX	2895					Withdrawn
CX	2896					Withdrawn
CX	2897					Withdrawn
CX	2898					Withdrawn
CX	2899					Withdrawn
CX	2900					Withdrawn
CX	2901					Withdrawn
CX	2902					Withdrawn
CX	2903					Withdrawn
CX	2904					Withdrawn
CX	2905					Withdrawn
CX	2906					Withdrawn
CX	2907					Withdrawn
CX	2908					Withdrawn
CX	2909	C	Freescale's response to Interrogatory No. 42	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2910					Withdrawn
CX	2911					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2912					Withdrawn
CX	2913					Withdrawn
CX	2914					Withdrawn
CX	2915					Withdrawn
CX	2916					Withdrawn
CX	2917					Withdrawn
CX	2918					Withdrawn
CX	2919					Withdrawn
CX	2920					Withdrawn
CX	2921					Withdrawn
CX	2922					Withdrawn
CX	2923					Withdrawn
CX	2924		U.S. Patent No. 5,241,133 (Mullen)	Ivey	VLD/INVLD	Admitted
CX	2925					Withdrawn
CX	2926					Withdrawn
CX	2927					Withdrawn
CX	2928					Withdrawn
CX	2929					Withdrawn
CX	2930					Withdrawn
CX	2931					Withdrawn
CX	2932					Withdrawn
CX	2933					Withdrawn
CX	2934					Withdrawn
CX	2935					Withdrawn
CX	2936					Withdrawn
CX	2937					Withdrawn
CX	2938					Withdrawn
CX	2939					Withdrawn
CX	2940					Withdrawn
CX	2941	C	Montgomery Exhibit 13: Referenced in Freescale Response to lnterrogatories 50, 51	Montgomery / Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2942					Withdrawn
CX	2943		Spansion Response to Request for Admission Nos.: 1-3	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2944		Amended Appendix A: Referenced in Spansion Response to Interrogatory No. 1	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2945	C	SPAN-ITC 036484 - 036923	Stipulation	Vldy/Invldy, Remedies, Infrng/Non-infrng	Admitted
CX	2946					Withdrawn
CX	2947					Withdrawn
CX	2948					Withdrawn
CX	2949					Withdrawn
CX	2950					Withdrawn
CX	2951					Withdrawn
CX	2952					Withdrawn
CX	2953					Withdrawn
CX	2954					Withdrawn
CX	2955	C	ATI Chart in Response to Interrogatory No. 6 (1/7/08)	Stipulation	Infrng/Non-infrng	Admitted
CX	2956	C	ATI Chart in Response to Interrogatory No. 6 (12/17/07)	Stipulation	Infrng/Non-infrng	Admitted
CX	2957	C	ATI's Responses to Tessera's Fourth Set of Interrogatories (9/6/07)	Stipulation	Infrng/Non-infrng	Admitted
CX	2958	C	Spansion's Responses to Tessera's Fourth Set of Interrogatories (9/6/07)	Stipulation	Infrng/Non-infrng	Admitted
CX	2959	C	Freescale's Responses to Tessera's Fourth Set of Interrogatories (9/6/07)	Stipulation	Infrng/Non-infrng	Admitted
CX	2960	C	Freescale's Second Supplemental Responses to Tessera's Second Set of Interrogatories (1/11/08)	Stipulation	Infrng/Non-infrng	Admitted
CX	2961	C	Motorola's Responses to Tessera's Fourth Set of Interrogatories (9/6/07)	Stipulation	Infrng/Non-infrng	Admitted
CX	2962		Mennitt '857 Patent	Sitaraman	INFRNG/NON-INFRNG	Admitted
CX	2963		Declaration of Christopher M. Pickett, from In re Inter Partes Reexamination of US Patent No. 6,433,419 (2/9/07)	Ivey	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2964		Rule 132 Declaration of Scot A. Griffin from In re Reexamination of US Patent No. 6,433,419	Ivey	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted
CX	2965		Petition to Strike Requestor's Comments, from In re Reexamination Application of: Khandros et al. (2/9/07)	Ivey	Vldy/Invldy, Conception, Reduction to Practice, and/or Ownership	Admitted
CX	2966					Withdrawn
CX	2967					Withdrawn
CX	2968(A)					Withdrawn
CX	2968(B)					Withdrawn
CX	2970					Withdrawn
CX	2971					Withdrawn
CX	2972					Withdrawn
CX	2973					Withdrawn
CX	2974					Withdrawn
CX	2975	C	Leonard Deposition Exhibit #003 - Confidential Exhibit 4 - List of Licenses of the Asserted Patents	Leonard	RMDY	Admitted
CX	2976		Leonard Deposition Exhibit #004 - Document entitled "Texas Instruments Update: Gradual Recovery, Analog to Lead" dated 4/23/07	Leonard	RMDY	Admitted
CX	2977		Leonard Deposition Exhibit #005 - Article: Broadcom and Verizon Wiless Enter into Licensing Agreement Allowing Verizon Wireless to Offer Cell Phones Banned by ITC; Companies Annouce Broad-Based Strategic Alliance	Leonard	RMDY	Admitted
CX	2978					Withdrawn
CX	2979					Withdrawn
CX	2980					Withdrawn
CX	2981		Leonard Deposition Exhibit #009 - U.S. Securities and Exchange Commision, Form 10-Q : Quarterly Report Pursuant to Section 13 or 15(d) of the Securities Exchange Act of 1934	Leonard	RMDY	Admitted
CX	2982		Leonard Deposition Exhibit #010 - Motorola Inc. Q4 2007 Earnings Call Transcript	Leonard	RMDY	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	2983					Withdrawn
CX	2984					Withdrawn
CX	2985					Withdrawn
CX	2986					Withdrawn
CX	2987					Withdrawn
CX	2988					Withdrawn
CX	2989					Withdrawn
CX	2990					Withdrawn
CX	2991					Withdrawn
CX	2992					Withdrawn
CX	2993					Withdrawn
CX	2994					Withdrawn
CX	2995					Withdrawn
CX	2996					Withdrawn
CX	2997					Withdrawn
CX	2998					Withdrawn
CX	2999					Withdrawn
CX	3000					Withdrawn
CX	3001					Withdrawn
CX	3002		Russell Deposition Exhibit # 2 - Notice of Deposition of Spansion, Inc.	Russell	RMDY	Admitted
CX	3003	C	Russell Deposition Exhibit # 3	Russell	RMDY	Admitted
CX	3004	C	Russell Deposition Exhibit # 4 - Spansion Financial Data 2007	Russell	RMDY	Admitted
CX	3005	C	Russell Deposition Exhibit # 5	Russell	RMDY	Admitted
CX	3006	C	Russell Deposition Exhibit # 6	Russell	RMDY	Admitted
CX	3007	C	Russell Deposition Exhibit # 7	Russell	RMDY	Admitted
CX	3008	C	Russell Deposition Exhibit # 8	Russell	RMDY	Admitted
CX	3009					Withdrawn
CX	3010					Withdrawn
CX	3011					Withdrawn
CX	3012					Withdrawn
CX	3013					Withdrawn
CX	3014					Withdrawn
CX	3015					Withdrawn
CX	3016					Withdrawn
CX	3017					Withdrawn
CX	3018					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3019					Withdrawn
CX	3020					Withdrawn
CX	3021					Withdrawn
CX	3022					Withdrawn
CX	3023	C	Khandros Performance Evaluation	Romankiw	OWNR	Admitted
CX	3024					Withdrawn
CX	3025					Withdrawn
CX	3026					Withdrawn
CX	3027	C	3/1990 Projects In Order of Priority, Romankiw	Romankiw	OWNR	Admitted
CX	3028	C	Sussenguth to Academy Members, Technical Agenda Report	Romankiw	OWNR	Admitted
CX	3029	C	Romankiw Academic Institution Interactions; Electrochemical Technology Environment, IBM vs. Competition	Romankiw	OWNR	Admitted
CX	3030	C	Pittler memo re Review of MR Plan	Romankiw	OWNR	Admitted
CX	3031	C	8/10/1988 Guibesault memo re D/431 All Managers Meeting	Romankiw	OWNR	Admitted
CX	3032	C	Romankiw Progress Report	Romankiw	OWNR	Admitted
CX	3033					Withdrawn
CX	3034	C	11/17/1997 Harris to DiStefano re proposal for a joint development effort with IBM on wafer level packaging	DiStefano	OWNR	Admitted
CX	3035					Withdrawn
CX	3036					Withdrawn
CX	3037					Withdrawn
CX	3038					Withdrawn
CX	3039					Withdrawn
CX	3040	C	Taheri to Smith encl Memorandum of Understanding between Tessera and IBM	DiStefano	OWNR	Admitted
CX	3041					Withdrawn
CX	3042					Withdrawn
CX	3043					Withdrawn
CX	3044					Withdrawn
CX	3045					Withdrawn
CX	3046					Withdrawn
CX	3047					Withdrawn
CX	3048					Withdrawn
CX	3049					Withdrawn
CX	3050	C	Mitchell Memorandum Re IBM	DiStefano	OWNR	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3051					Withdrawn
CX	3052					Withdrawn
CX	3053					Withdrawn
CX	3054					Withdrawn
CX	3055					Withdrawn
CX	3056					Withdrawn
CX	3057	C	DiStefano To Brown Enclosing Memorandum	DiStefano	OWNR	Admitted
CX	3058					Withdrawn
CX	3059					Withdrawn
CX	3060					Withdrawn
CX	3061					Withdrawn
CX	3062					Withdrawn
CX	3063					Withdrawn
CX	3064					Withdrawn
CX	3065	C	Respondent STMicroelectronics First Amended and Supplemental Response to Tessera's Second Set of Requests for Admission	Stipulation	Infrng/Non-infrng	Admitted
CX	3066					Withdrawn
CX	3067	C	Product Specs for MDRO *5363A99	Qu	Infrng/Non-infrng	Admitted
CX	3068	C	Mount & Bond Diagram for R0*5363	Qu	Infrng/Non-infrng	Admitted
CX	3069	C	Base LBGA 288L 19X19MM 2LY DP7.6x6.9MM Pitch 1MM	Qu	Infrng/Non-infrng	Admitted
CX	3070	C	RR V476 NEW MUAR - 0959/GNB - 0325	Qu	Infrng/Non-infrng	Admitted
CX	3071	C	Product Specs for F5RR*V476BDQ in Manufacturing Phase ASSY Plant MU1A ST MUAR - MALAYSIA 0959	Qu	Infrng/Non-infrng	Admitted
CX	3072	C	POA for LBGA 288 / 19x19x1.7 / 4R18 1.0 POA-ASG (GNB Package Outline)	Qu	Infrng/Non-infrng	Admitted
CX	3073					Withdrawn
CX	3074					Withdrawn
CX	3075	C	Letter regarding Amkor Agreement	Griffin	RMDY, OWNR	Admitted
CX	3076	C	Side-by-Side Comparison of Toshiba and STMicro FBGA's (1/22/2003)	Griffin	RMDY, OWNR	Admitted
CX	3077					Withdrawn
CX	3078	C	Freescale Work Instructions, Document No. 00ASM9781A	Qu	Infrng/Non-infrng	Admitted
CX	3079	C	Package Outline Drawing	Qu	Infrng/Non-infrng	Admitted
CX	3080	C	ASE Substrate Design	Qu	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3081	C	ASE Drawing	Qu	Infrng/Non-infrng	Admitted
CX	3082	C	Reliability Test Report for Qualification Test of TFBGA (10x10) 179L	Qu	Infrng/Non-infrng	Admitted
CX	3083	C	Qualcomm Substrate Drawing	Qu	Infrng/Non-infrng	Admitted
CX	3084	C	Qualcomm Drawing - Assembly Material Set	Qu	Infrng/Non-infrng	Admitted
CX	3085	C	Qualcomm Package Outline Drawing	Qu	Infrng/Non-infrng	Admitted
CX	3086	C	Qualcomm Bonding Diagram	Qu	Infrng/Non-infrng	Admitted
CX	3087	C	Spansion Drawing	Qu	Infrng/Non-infrng	Admitted
CX	3088	C	Spansion Ball FBGA Drawing	Qu	Infrng/Non-infrng	Admitted
CX	3089	C	Spansion Reliability Qualification	Qu	Infrng/Non-infrng	Admitted
CX	3090					Withdrawn
CX	3091					Withdrawn
CX	3092		Freescale News Release, "Elektrobit and Freescale Cut 3G Handset Development Time with New Reference Phone"		Remedies	Admitted
CX	3093					Withdrawn
CX	3094					Withdrawn
CX	3095					Withdrawn
CX	3096					Withdrawn
CX	3097					Withdrawn
CX	3098					Withdrawn
CX	3099					Withdrawn
CX	3100					Withdrawn
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CX	3109					Withdrawn
CX	3110					Withdrawn
CX	3111					Withdrawn
CX	3112					Withdrawn
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CX	3114					Withdrawn
CX	3115					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
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CX	3117					Withdrawn
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CX	3119					Withdrawn
CX	3120					Withdrawn
CX	3121					Withdrawn
CX	3122					Withdrawn
CX	3123					Withdrawn
CX	3124		Emerson & Cuming Selector Guide: Electrically Conductive Adhesives	Ivey	VLD/INVLD	Admitted
CX	3125		Emerson & Cuming Selector Guide: Adhesives and Coatings for Passive Components	Ivey	VLD/INVLD	Admitted
CX	3126					Withdrawn
CX	3127					Withdrawn
CX	3128					Withdrawn
CX	3129					Withdrawn
CX	3130					Withdrawn
CX	3131					Withdrawn
CX	3132					Withdrawn
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CX	3150					Withdrawn
CX	3151					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3152					Withdrawn
CX	3153					Withdrawn
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CX	3160					Withdrawn
CX	3161					Withdrawn
CX	3162					Withdrawn
CX	3163					Withdrawn
CX	3164					Withdrawn
CX	3165	C	Nagaraj,B., "Package-To-Board Reliability - Methodology and Case Study on OMPAC Package	Sitaraman	INFRNG/NON-INFRNG	Admitted
CX	3166					Withdrawn
CX	3167					Withdrawn
CX	3168					Withdrawn
CX	3169					Withdrawn
CX	3170					Withdrawn
CX	3171					Withdrawn
CX	3172					Withdrawn
CX	3173					Withdrawn
CX	3174	C	Bonding Diagram, BL90-V6698-1A	Qu	Infrng/Non-infrng	Admitted
CX	3175	C	SPIL Diagram for STF BGA (LF) 259	Qu	Infrng/Non-infrng	Admitted
CX	3176	C	SPIL Diagram for STF BGA (LF) 259	Qu	Infrng/Non-infrng	Admitted
CX	3177	C	Bonding Diagram, PM6652	Qu	Infrng/Non-infrng	Admitted
CX	3178	C	Bonding Diagram, Bal 4050	Qu	Infrng/Non-infrng	Admitted
CX	3179	C	Bonding Diagram, WFB4030	Qu	Infrng/Non-infrng	Admitted
CX	3180	C	Bonding Diagram	Qu	Infrng/Non-infrng	Admitted
CX	3181	C	Bonding Diagram, PM6610	Qu	Infrng/Non-infrng	Admitted
CX	3182					Withdrawn
CX	3183					Withdrawn
CX	3184					Withdrawn
CX	3185					Withdrawn
CX	3186					Withdrawn
CX	3187					Withdrawn
CX	3188					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3189					Withdrawn
CX	3190					Withdrawn
CX	3191					Withdrawn
CX	3192					Withdrawn
CX	3193					Withdrawn
CX	3194		US Patent No. 5,148,266	Ivey	VLD/INVLD	Admitted
CX	3195					Withdrawn
CX	3196	C	Corrected Witness Statement of Jianmin Qu	Qu / Sitaraman	INFRNG/NON-INFRNG	Admitted
CX	3197	C	Direct Witness Statement of Kirk E. Flatow	Flatow	RMDY	Admitted
CX	3198					Withdrawn
CX	3199	C	Direct Witness Statement of Scot A. Griffin	Griffin	RMDY, OWNR	Admitted
CX	3200					Withdrawn
CX	3201	C	Direct Witness Statement of Bruce McWilliams	McWilliams	RMDY, DI	Admitted
CX	3202					Withdrawn
CX	3203					Withdrawn
CX	3204	C	Rebuttal Witness Statement of Christopher Pickett	Pickett	RMDY, OWNR	Admitted
CX	3205	C	Rebuttal Witness Statement of Peter Ivey	Ivey	VLD/INVLD, OWNR	Admitted
CX	3206	C	Rebuttal Witness Statement of Scot Griffin	Griffin	RMDY, OWNR	Admitted
CX	3208	C	Rebuttal Witness Statement of Mike Warner	Warner	RMDY, DI	Admitted
CX	3209					Withdrawn
CX	3210					Withdrawn
CX	3211					Withdrawn
CX	3212					Withdrawn
CX	3213					Withdrawn
CX	3214					Withdrawn
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CX	3219					Withdrawn
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CX	3222					Withdrawn
CX	3223					Withdrawn
CX	3224					Withdrawn
CX	3225					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3226					Withdrawn
CX	3227					Withdrawn
CX	3228					Withdrawn
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CX	3235					Withdrawn
CX	3236					Withdrawn
CX	3237					Withdrawn
CX	3238					Withdrawn
CX	3239					Withdrawn
CX	3240					Withdrawn
CX	3241					Withdrawn
CX	3242					Withdrawn
CX	3243					Withdrawn
CX	3244					Withdrawn
CX	3246	C	Respondent STMicroelectronics First Amended and Supplemental Response to Tessera's Second Set of Requests for Admission	Stipulation	Remedies	Admitted
CX	3247					Withdrawn
CX	3248					Withdrawn
CX	3249					Withdrawn
CX	3250					Withdrawn
CX	3251					Withdrawn
CX	3252					Withdrawn
CX	3253					Withdrawn
CX	3254					Withdrawn
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CX	3259					Withdrawn
CX	3260					Withdrawn
CX	3261					Withdrawn
CX	3262					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
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CX	3264					Withdrawn
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CX	3298					Withdrawn
CX	3299					Withdrawn
CX	3300					Withdrawn
CX	3301					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3302					Withdrawn
CX	3303					Withdrawn
CX	3304	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7114359.	Qu	Infrng/Non-infrng	Admitted
CX	3305	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7609040	Qu	Infrng/Non-infrng	Admitted
CX	3306	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7132897	Qu	Infrng/Non-infrng	Admitted
CX	3307	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7517961	Qu	Infrng/Non-infrng	Admitted
CX	3308	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7517962	Qu	Infrng/Non-infrng	Admitted
CX	3309	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7185086	Qu	Infrng/Non-infrng	Admitted
CX	3310	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7385800	Qu	Infrng/Non-infrng	Admitted
CX	3311	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7286783	Qu	Infrng/Non-infrng	Admitted
CX	3312	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7104670	Qu	Infrng/Non-infrng	Admitted
CX	3313	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7515030	Qu	Infrng/Non-infrng	Admitted
CX	3314	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7131786	Qu	Infrng/Non-infrng	Admitted
CX	3315	C	TMI00433057-59	Warner	RMDY, DI	Admitted
CX	3316	C	TMI00228125-28	Warner	RMDY, DI	Admitted
CX	3317	C	TMI00182137	Warner	RMDY	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3318	C	TMI00263170-73	Warner	RMDY, DI	Admitted
CX	3319	C	TMI00251344-55	Warner	RMDY, DI	Admitted
CX	3320	C	TMI00196053-61	Warner	RMDY, DI	Admitted
CX	3321	C	Corrected Rebuttal Witness Statement of Urbish	Urbish	INFRNG/NON-INFRNG	Admitted
CX	3322		U.S. Patent No. 3, 795, 037 to Luttmer	Ivey	VLD/INVLD	Admitted
CX	3323		Solder-Filled Elastomeric Spacer	Ivey	VLD/INVLD	Admitted
CX	3324					Withdrawn
CX	3325					Withdrawn
CX	3326					Withdrawn
CX	3327					Withdrawn
CX	3328					Withdrawn
CX	3329					Withdrawn
CX	3330	C	Crowder Memo Re: Manufacturing Research	Romankiw	OWNR	Admitted
CX	3331		Corrected Rebuttal Witness Statement of Urbish	Ivey / Urbish	VLD/INVLD	Admitted
CX	3332					Withdrawn
CX	3333	C	Murray Deposition Exhibit #002 - List of all accused small format BGA chips identified by Fresscale	Murray		Admitted
CX	3334					Withdrawn
CX	3335	C	Frankel Deposition Exhibit #002 - Respondent Qualcomm, Inc.'s Fourth Supplemental Response to Complainant Tessera, Inc.'s First Set of Interrogatories to Qualcomm, Inc.	Frankel / Stipulation	Importation, Remedies	Admitted
CX	3336					Withdrawn
CX	3337	C	Frankel Deposition Exhibit #004	Frankel	RMDY	Admitted
CX	3338					Withdrawn
CX	3339	C	Frankel Deposition Exhibit #006	Frankel	RMDY	Admitted
CX	3340					Withdrawn
CX	3341	C	Frankel Deposition Exhibit #009	Frankel	RMDY	Admitted
CX	3342	C	Frankel Deposition Exhibit #010	Frankel	RMDY	Admitted
CX	3343					Withdrawn
CX	3344					Withdrawn
CX	3345					Withdrawn
CX	3346					Withdrawn
CX	3347					Withdrawn
CX	3348					Withdrawn
CX	3349					Withdrawn
CX	3350					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3351					Withdrawn
CX	3352					Withdrawn
CX	3353					Withdrawn
CX	3354					Withdrawn
CX	3355		Hasuman Deposition Exhibit #004 - Commission Opinion on RMNDY in ITC Investigation No. 337-TA-543	Hausman	RMDY	Admitted
CX	3356					Withdrawn
CX	3357	C	Hasuman Deposition Exhibit #006 - Qualcomm's Fourth Supplemental Response to Tessera's First Set of Interrogatories	Hausman / Stipulation	Importation, Remedies	Admitted
CX	3358	C	Hausman Deposition Exhibit #007 - Confidential Exhibit #4 to the Complaint	Hausman	RMDY	Admitted
CX	3359	C	Hasuman Deposition Exhibit #008 - QTSIH 00010507 - 515	Hausman	RMDY	Admitted
CX	3360	C	Hausman Deposition Exhibit #009 - QTSIH 00010516 - 517	Hausman	RMDY	Admitted
CX	3361		Hausman Deposition Exhibit #010 - QTSIH 00520669 - 678	Hausman	RMDY	Admitted
CX	3362		Hausman Deposition Exhibit #011 - Verizon Wireless news release	Hausman	RMDY	Admitted
CX	3363	C	Hausman Deposition Exhibit #012 - QTSI 00908315 - 324	Hausman	RMDY	Admitted
CX	3364		Hausman Deposition Exhibit #013 - Qualcomm, Inc. Form 10-Q for the Quarterly Period Ending 12/30/2007	Hausman / Stipulation	Importation, Remedies	Admitted
CX	3365					Withdrawn
CX	3366					Withdrawn
CX	3367					Withdrawn
CX	3368					Withdrawn
CX	3369					Withdrawn
CX	3370					Withdrawn
CX	3371					Withdrawn
CX	3372					Withdrawn
CX	3373					Withdrawn
CX	3374					Withdrawn
CX	3375	C	ATI's Second Supplemental Responses to Tessera's First Set of Interrogatories		Infrng/Non-infrng	Admitted
CX	3376					Withdrawn
CX	3377					Withdrawn
CX	3378					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3379					Withdrawn
CX	3380	C	Amendment Number One (1) to the Agreement for Exchange of Confidential Information between IBM and Tessera	DiStefano	OWNR	Admitted
CX	3381					Withdrawn
CX	3382					Withdrawn
CX	3383					Withdrawn
CX	3384					Withdrawn
CX	3385					Withdrawn
CX	3386					Withdrawn
CX	3387					Withdrawn
CX	3388					Withdrawn
CX	3389	C	list of ST-NV finished goods and product codes taken from the T&F documents	Qu/Hundt	Infrng/Non-infrng	Admitted
CX	3390		File History of US Patent No. 5,241,133 (Mullen)	Freyman	INFRNG/NON-INFRNG	Admitted
CX	3391	C	Declaration of Matthew D. Smith	Smith	Importation, Remedies	Admitted
CX	3392	C	Motorola's Confidential Response to Complaintant Tessera's Second Set of Requests for Admissions (#3-15)	Stipulation	Infrng/Non-infrng	Admitted
CX	3393					Withdrawn
CX	3395		Murray Ex. # 4: Freescale Semiconductor, Inc. 10-K	Murray / Stipulation	Infrng/Non-infrng, Remedies	Admitted
CX	3396					Withdrawn
CX	3397					Withdrawn
CX	3398					Withdrawn
CX	3399	C	Correspondence from J. Brown to "Bill" regardign Alan Patricoff Associates, Inc. and IST Associates, inc.	Bottoms	OWNR	Admitted
CX	3399(A)		McLellan Deposition Ex. #123 - AMD 2006 Annual Report on Form 10K	McClellan	Importation, Remedies	Admitted
CX	3400					Withdrawn
CX	3401					Withdrawn
CX	3402					Withdrawn
CX	3403	C	ST-NV'S First Amended Reponse to Tessera's Eighth Set of Interrogatories	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3404	C	Build sheet assemblies for products described in supplemental Qu witness statement: ST_TFBGA_105_2 (STITC00153023); ST_MC_TFBGA_105_3(STTITC00153005); ST_MC_TFBGA_88_2 (STITC00157396); ST_SC_TBGA_64 (STITC00152355); ST_SC_VFBGA_63 (STITC00057247); STM_SC_TFBGA_47 (STITC00152271); STM_SC_TFBGA_324 (STITC00034525); STM_SC_VFBGA_56 (STITC00153181)	Qu	INFRNG/NON-INFRNG	Admitted
CX	3405	C	Package outline diagrams for for products described in supplemental Qu witness statement: ST_TFBGA_105_2 (STITC00055882); ST_MC_TFBGA_105_3(STTITC00055882); ST_MC_TFBGA_88_2 (STITC00055433); ST_SC_TBGA_64 (STIT00053860); ST_SC_VFBGA_63 (STITC00055826); STM_SC_TFBGA_47 (STITC00054149); STM_SC_TFBGA_324 (STITC00021237); STM_SC_VFBGA_56 (STITC00054307)	Qu	INFRNG/NON-INFRNG	Admitted
CX	3406	C	Substrate technical documents for products described in supplemental Qu witness statement: ST_TFBGA_105_2 (STITC00026645); ST_MC_TFBGA_105_3(STTITC00025704); ST_MC_TFBGA_88_2 (STITC00025696); ST_SC_TBGA_64 (STITC00026074); ST_SC_VFBGA_63 (STITC00024922); STM_SC_TFBGA_47 (STITC00020177); STM_SC_TFBGA_324 (STITC00025013); STM_SC_VFBGA_56 (STITC00024740)	Qu / Sitaraman	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3407	C	Wire bonding diagrams for products described in supplemental Qu witness statement: ST_TFBGA_105_2 (STITC00153016); ST_MC_TFBGA_105_3(STTITC00152999); ST_MC_TFBGA_88_2 (STITC00074037); ST_SC_TBGA_64 (STITC00152351); ST_SC_VFBGA_63 (STITC00073889); STM_SC_TFBGA_47 (STITC00152267); STM_SC_TFBGA_324 (STITC00153469); STM_SC_VFBGA_56 (STITC00153177)	Qu	INFRNG/NON-INFRNG	Admitted
CX	3408	C	Table of Packages	Qu	INFRNG/NON-INFRNG	Admitted
CX	3409	C	Geometric Dimensions of STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CX	3410	C	Geometric Dimensions of STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CX	3411	C	Geometric Dimension of STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3412	C	Geometric Dimension of STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CX	3413	C	Geometric Dimension of STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CX	3414	C	Geometric Dimension of STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CX	3415	C	Geometric Dimension of STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	3416	C	Geometric Dimension of STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3417	C	CrossSection of STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CX	3418	C	CrossSection of STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CX	3419	C	CrossSection of STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CX	3420	C	CrossSection of STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3421	C	CrossSection of STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CX	3422	C	CrossSection of STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	3423	C	CrossSection of STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3424	C	CrossSection of STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CX	3425	C	Mesh for STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CX	3426	C	Mesh for STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CX	3427	C	Mesh for STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CX	3428	C	Mesh for STM-MC-TFBGA-103-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	3429	C	Mesh for STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3430	C	Mesh for STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CX	3431	C	Mesh for STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CX	3432	C	Mesh for STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3433	C	Material Property FEA Inputs	Qu	INFRNG/NON-INFRNG	Admitted
CX	3434	C	Column Displacement STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CX	3435	C	Column Displacement STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CX	3436	C	Column Displacement STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3437	C	Column Displacement STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3438	C	Column Displacement STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	3439	C	Column Displacement STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3440	C	Column Displacement STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CX	3441	C	Column Displacement STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CX	3442	C	AC Movement STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CX	3443	C	AC Movement STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CX	3444	C	AC Movement STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CX	3445	C	AC Movement STM-SC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3446	C	AC Movement STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CX	3447	C	AC Movement STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3448	C	AC Movement STM-SC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	3449	C	AC Movement STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CX	3450	C	Plastic Work STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CX	3451	C	Plastic Work STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CX	3452	C	Plastic Work STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CX	3453	C	Plastic Work STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3454	C	Plastic Work STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CX	3455	C	Plastic Work STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CX	3456	C	Plastic Work STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3457	C	Plastic Work STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	3458	C	Percentage Life Improvement Table Method 1	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3459	C	Symmetry Results Plot	Qu	INFRNG/NON-INFRNG	Admitted
CX	3460	C	Copper Layer Mesh	Qu	INFRNG/NON-INFRNG	Admitted
CX	3461	C	Copper Layer Comparison Table	Qu	INFRNG/NON-INFRNG	Admitted
CX	3462	C	Polar Plot STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CX	3463	C	Polar Plot STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CX	3464	C	Polar Plot STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	3465	C	Polar Plot STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3466	C	Polar Plot STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CX	3467	C	Polar Plot STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CX	3468	C	Intentionally left blank	Qu	INFRNG/NON-INFRNG	Admitted
CX	3469	C	Polar Plot STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3470	C	Polar Plot STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CX	3471	C	Plastic Work External STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CX	3472	C	Plastic Work External STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CX	3473	C	Plastic Work External STM-SC-TFBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CX	3474	C	Plastic Work External STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CX	3475	C	Plastic Work External STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3476	C	Plastic Work External STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	3477	C	Plastic Work External STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3478	C	Plastic Work External STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3479	C	Percentage Life Improvement Table Method 2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3480	C	Compression for STM-SC-VFBGA-56	Qu	INFRNG/NON-INFRNG	Admitted
CX	3481	C	Compression for STM-SC-TFBGA-47	Qu	INFRNG/NON-INFRNG	Admitted
CX	3482	C	Compression for STM-SC-TBGA-64	Qu	INFRNG/NON-INFRNG	Admitted
CX	3483	C	Compression for STM-SC-TFBGA-324	Qu	INFRNG/NON-INFRNG	Admitted
CX	3484	C	Compression for STM-MC-TFBGA-105-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3485	C	Compression for STM-MC-TFBGA-88-2	Qu	INFRNG/NON-INFRNG	Admitted
CX	3486	C	Compression for STM-SC-VFBGA-63	Qu	INFRNG/NON-INFRNG	Admitted
CX	3487	C	Compression for STM-MC-TFBGA-105-3	Qu	INFRNG/NON-INFRNG	Admitted
CX	3496					Withdrawn
CX	3497	C	Respondent Qualcomm Incorporated's Fourth Supplemental Response to Tessera, Inc.'s Interrogatory No. 1	Stipulation	Infrng/Non-infrng, Remedies	Admitted
CX	3498	C	IC Package Technology Updates, April 20, 2005	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	3499					Withdrawn
CX	3500					Withdrawn
CX	3501					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3502					Withdrawn
CX	3503					Withdrawn
CX	3504					Withdrawn
CX	3505					Withdrawn
CX	3506					Withdrawn
CX	3507					Withdrawn
CX	3508					Withdrawn
CX	3509					Withdrawn
CX	3510	C	Samsung Meeting, December 11, 2006	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	3511	C	Technology Review Package Engineering V13	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	3512					Withdrawn
CX	3513					Withdrawn
CX	3514					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3515	C	Customer Package Technology Update, January 2007, Preliminary Version V1	Hausman	RMDY	Admitted
CX	3516					Withdrawn
CX	3517	C	Package Engineering: An Eye on the Future	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	3518					Withdrawn
CX	3519	C	The Prismark Wireless Technology Report, July 2005	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	3520					Withdrawn
CX	3521					Withdrawn
CX	3522	C	The Prismark Wireless Technology Report, October 2005	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	3523					Withdrawn
CX	3524	C	ULC GSM Phones: LoCosto and Beyond, December 19, 2007	Gregorich	INFRNG/NON-INFRNG	Admitted
CX	3525					Withdrawn
CX	3526		U.S. Patent No. 5,148,265 (Khandros, et al.)	Ivey	Conception, Reduction to Practice, Patent Ownership, Tessera	Admitted
CX	3527		U.S. Patent No. 5,148,266 (Khandros, et al.)	Ivey	Conception, Reduction to Practice, Patent Ownership, Tessera	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3528					Withdrawn
CX	3529					Withdrawn
CX	3530					Withdrawn
CX	3531	C	Smith Declaration 2.21.2008	ST-NV	Importation, Remedies	Admitted
CX	3532	C	2008.02.22 STMicroelectronics First Amended and Supplemental Response to Tessera's Eighth Set of Interrogatories (108-124)	ST-NV	Infrng/Non-infrng, Importation, Remedy, Rebuttal to License Defense	Admitted
CX	3533	C	STMicroelectronics Second Amended and Supplemental Response to Tessera's Eighth Set of Interrogatories (108-124) served July 3, 2008	Malone	INFRNG/NON-INFRNG	Admitted
CX	3534	C	2008.02.22 STMicroelectronics Second Amended and Supplemental Response to Tessera's First Set of Interrogatories (1-5)	ST-NV	Infrng/Non-infrng, Importation, Remedy, Rebuttal to License Defense	Admitted
CX	3535	C	2008.02.22 STMicroelectronics Second Amended and Supplemental Response to Tessera's Fourth Set of Interrogatories (31)	ST-NV	Infrng/Non-infrng, Importation, Remedy, Rebuttal to License Defense	Admitted
CX	3536	C	2008.02.22 STMicroelectronics Second Amended and Supplemental Response to Tessera's Seventh Set of Interrogatories (71-107)	ST-NV	Infrng/Non-infrng, Importation, Remedy, Rebuttal to License Defense	Admitted
CX	3537	C	2008.07.03 STMicroelectronics Third Amended and Supplemental Response to Tessera's First Set of Interrogatories (1-5)	Malone	INFRNG/NON-INFRNG	Admitted
CX	3538	C	2008.07.03 STMicroelectronics Third Amended and Supplemental Response to Tessera's Fourth Set of Interrogatories (31)	Malone	INFRNG/NON-INFRNG	Admitted
CX	3539	C	2008.07.03 STMicroelectronics Third Amended and Supplemental Response to Tessera's Seventh Set of Interrogatories (71-107)	Malone	INFRNG/NON-INFRNG	Admitted
CX	3540	C	2008.07.03 STMicroelectronics Third Amended and Supplemental Response to Tessera's Third Set of RFAs	Malone	INFRNG/NON-INFRNG	Admitted
CX	3541	C	2008.02.22 STMicroelectronics Second Amended and Supplemental Response to Tessera's Second Set of RFAs	ST-NV	Importation, Renedy, License Defense	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3542	C	4.16.2008 Chambers Depo. Ex. 3 - STMicroelectronics First Amended and Supplemental Response to Tessera's Eighth Set of Interrogatories (108-124)	Chambers	INFRNG/NON-INFRNG, RMDY	Admitted
CX	3543		4.16.2008 Chambers Depo. Ex. 4 - One Page from Interrogatory Answers	Chambers	INFRNG/NON-INFRNG, RMDY	Admitted
CX	3544		4.16.2008 Chambers Depo. Ex. 5 - STMicroelectronics Advertisement	Chambers	INFRNG/NON-INFRNG, RMDY	Admitted
CX	3545		4.16.2008 Chambers Depo. Ex. 6 - ST Presentation	Chambers	INFRNG/NON-INFRNG, RMDY	Admitted
CX	3546	C	4.16.2008 Chambers Depo. Ex. 7 - Composite Spreadsheet	Chambers	INFRNG/NON-INFRNG, RMDY	Admitted
CX	3547		4.16.2008 Chambers Depo. Ex. 8 - Printout of Web Pages from Future Electronics	Chambers	INFRNG/NON-INFRNG, RMDY	Admitted
CX	3548		4.16.2008 Chambers Depo. Ex. 9 - Advertisement Entitled Speak With More Intelligence	Chambers	INFRNG/NON-INFRNG, RMDY	Admitted
CX	3549		4.16.2008 Chambers Depo. Ex. 10 - Form 20-F for STMicroelectronics	Chambers	INFRNG/NON-INFRNG, RMDY	Admitted
CX	3550		4.16.2008 Chambers Depo. Ex. 11 - Press Release by STMicroelectronics	Chambers	INFRNG/NON-INFRNG, RMDY	Admitted
CX	3551					Withdrawn
CX	3552					Withdrawn
CX	3553					Withdrawn
CX	3554					Withdrawn
CX	3555		4.16.2008 Chambers Depo. Ex. 16 - STMicroelectronics Advertisement Concerning Flash Memory	Chambers	Importation, Remedies	Admitted
CX	3556		4.16.2008 Chambers Depo. Ex. 17 - STMicroelectronics Advertisement Concerning LightFlash	Chambers	Importation, Remedies	Admitted
CX	3557		2.26.2008 Licciardello Depo. Ex. 1 - ST Document titled We Put More Intelligence Into Everything	Licciardello	Importation, Remedies	Admitted
CX	3558		2.26.2008 Licciardello Depo. Ex. 8 - ST Presentation dated 1.23.2008	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3559	C	2.26.2008 Licciardello Depo. Ex. 29 - ST-NV Combined Appendices A and B	Licciardello	Importation, Remedy, Infrng/Non-infrng	Admitted
CX	3560		5.27.2008 Licciardello Depo. Ex. 2 - Securities and Exchange Commission form 6-K, dated 3.31.2008	Liccardello	INFRNG/NON-INFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3561		5.27.2008 Licciardello Depo. Ex. 3 - Press release entitled STMicroelectronics, Intel, Francisco Partners Close Transaction dated 3.31.2008	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3562		5.27.2008 Licciardello Depo. Ex. 3A - Print-outs from the Future Electronics website	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3563		5.27.2008 Licciardello Depo. Ex. 4 - Press release entitled Numonyx Enters Memory Market in a Strong Position dated 3.31.2008	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3564		5.27.2008 Licciardello Depo. Ex. 4A - Print-outs from the Future Electronics website	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3565		5.27.2008 Licciardello Depo. Ex. 5 - Print-outs from the Numonyx website concerning memory products and product searches	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3566		5.27.2008 Licciardello Depo. Ex. 5A - Print-outs from the Future Electronics website	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3567		5.27.2008 Licciardello Depo. Ex. 6 - Print-outs from the STMicroelectronics website redirecting to the Numonyx website	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3568		5.27.2008 Licciardello Depo. Ex. 7 - Master Agreement by and between STMicroelectronics, Intel, Redwood, and Francisco Partners dated 5.22.2007	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3569		5.27.2008 Licciardello Depo. Ex. 7A - Document entitled We Put More Intelligence into Everything	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3570		5.27.2008 Licciardello Depo. Ex. 8A - STMicroelectronics Company Presentation dated 5.14.2008	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3571		5.27.2008 Licciardello Depo. Ex. 9 - Securities and Exchange Commission form 20-F for the period ended 12.21.2006	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3572		5.27.2008 Licciardello Depo. Ex. 12 - Avnet Marketing of ST Products	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3573		5.27.2008 Licciardello Depo. Ex. 18 - ST Lightflash advertisement	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3574		5.27.2008 Licciardello Depo. Ex. 19 - STdocument titled Speak with more intelligence	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3575		5.27.2008 Licciardello Depo. Ex. 20 - Listing of Memory Products from Arrow NAC website	Liccardello	INFRNG/NON-INFRNG	Admitted
CX	3576		5.23.2008 Perillat Depo Ex. 6 - Document entitled Hitachi Chemical Data Sheet	Perillat	INFRNG/NONINFRNG	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3577					Withdrawn
CX	3578		5.23.2008 Perillat Depo Ex. 5 - Document entitled Loctite Die Attach Materials	Perillat	Infrng/Non-infrng	Admitted
CX	3579		5.23.2008 Perillat Depo Ex. 6 - Document entitled Hitachi Chemical Data Sheet	Perillat	INFRNG/NONINFRNG	Admitted
CX	3580		5.23.2008 Perillat Depo Ex. 7 - Document entitled Die Bonding Paste	Perillat	INFRNG/NONINFRNG	Admitted
CX	3581		5.23.2008 Perillat Depo Ex. 8 - Document entitled Ablebond 2025D	Perillat	INFRNG/NONINFRNG	Admitted
CX	3582	C	5.23.2008 Perillat Depo Ex. 9 - Document entitled Glue Die Attach in Process Control	Perillat	INFRNG/NONINFRNG	Admitted
CX	3583	C	5.23.2008 Perillat Depo Ex. 10 - Product Specification for H5FN*MV86BAA	Perillat	INFRNG/NONINFRNG	Admitted
CX	3584	C	5.23.2008 Perillat Depo Ex. 11 - Document entitled Package Outline Assembly	Perillat	INFRNG/NONINFRNG	Admitted
CX	3585	C	5.23.2008 Perillat Depo Ex. 12 - Product Specification for 75FN*MV86BAA	Perillat	INFRNG/NONINFRNG	Admitted
CX	3586					Withdrawn
CX	3587					Withdrawn
CX	3588					Withdrawn
CX	3589					Withdrawn
CX	3590	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7243987	Qu, Hundt	Infrng/Non-infrng	Admitted
CX	3591	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7298388	Qu, Hundt	Infrng/Non-infrng	Admitted
CX	3592	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7363848	Qu, Hundt	Infrng/Non-infrng	Admitted
CX	3593	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7446062	Qu, Hundt	Infrng/Non-infrng	Admitted
CX	3594	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7811789	Qu, Hundt	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3595	C	Compilation of STMicroelectronics N.V. Built Sheet Assembly (BSA) documents that reference Package Outline Assembly (POA) number 7858639	Qu, Hundt	Infrng/Non-infrng	Admitted
CX	3596					Withdrawn
CX	3597					Withdrawn
CX	3598					Withdrawn
CX	3599					Withdrawn
CX	3600					Withdrawn
CX	3601					Withdrawn
CX	3602					Withdrawn
CX	3603					Withdrawn
CX	3604					Withdrawn
CX	3605					Withdrawn
CX	3606					Withdrawn
CX	3607					Withdrawn
CX	3608					Withdrawn
CX	3609					Withdrawn
CX	3610					Withdrawn
CX	3611					Withdrawn
CX	3612					Withdrawn
CX	3613					Withdrawn
CX	3614					Withdrawn
CX	3615					Withdrawn
CX	3616					Withdrawn
CX	3617					Withdrawn
CX	3618					Withdrawn
CX	3619					Withdrawn
CX	3620		Freescale Semiconductor Inc. Form 10-Q for period ended March 28, 2008	Stipulation	Remedies	Admitted
CX	3621		Freescale Semiconductor Inc. Form 10-K for period ended December 31, 2007	Stipulation	Remedies	Admitted
CX	3622		Spansion Inc. Form 10-Q for period ended March 30, 2008	Stipulation	Remedies	Admitted
CX	3623		Spansion Inc. Form 10-K for period ended December 30, 2007	Stipulation	Remedies	Admitted
CX	3624		Qualcomm Inc. Form 10-Q for period ended March 30, 2008	Stipulation	Remedies	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3625		Qualcomm Inc. Form 10-K for period ended September 30, 2007	Stipulation	Remedies	Admitted
CX	3626		Motorola Inc. Form 10-Q for period ended March 29, 2008	Stipulation	Remedies	Admitted
CX	3627		Motorola Inc. Form 10-K for period ended December 31, 2007	Stipulation	Remedies	Admitted
CX	3628	C	Motorola's First Supplemental Response to Tessera's Fourth Set of Interrogatories (#31) (served May 16, 2008)	Stipulation	Infrng/Non-infrng, Remedies	Admitted
CX	3629	C	Motorola's First Supplemental Response to Tessera's Fifth Set of Interrogatories (40, 48-51) (served May 16, 2008)	Stipulation	Infrng/Non-infrng, Remedies	Admitted
CX	3630	C	Motorola's Second Supplemental Response to Tessera's Sixth Set of Interrogatories (88) (served May 16, 2008)	Stipulation	Infrng/Non-infrng, Remedies	Admitted
CX	3631	C	Motorola's Second Supplemental Response to Tessera's Third Set of Interrogatories (25, 26) (served May 16, 2008)	Stipulation	Infrng/Non-infrng, Remedies	Admitted
CX	3632	C	Motorola's Fifth Supplemental Response to Tessera's Second Set of Interrogatories (6, 17, and 20) (served May 16, 2008)	Stipulation	Infrng/Non-infrng, Remedies	Admitted
CX	3633	C	Motorola's Fifth Supplemental Response to Tessera's First Set of Interrogatories (1-5) (served May 16, 2008)	Stipulation	Infrng/Non-infrng, Remedies	Admitted
CX	3634					Withdrawn
CX	3635					Withdrawn
CX	3636		Qualcomm Incorporated's Company Overview for 2007	Hausman	RMDY	Admitted
CX	3637					Withdrawn
CX	3638					Withdrawn
CX	3639					Withdrawn
CX	3640					Withdrawn
CX	3641					Withdrawn
CX	3642					Withdrawn
CX	3643					Withdrawn
CX	3644					Withdrawn
CX	3645					Withdrawn
CX	3646					Withdrawn
CX	3647					Withdrawn

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
CX	3648					Withdrawn
CX	3649					Withdrawn
CX	3650					Withdrawn
CX	3651					Withdrawn
CX	3652					Withdrawn
CX	3653					Withdrawn
CX	3654					Withdrawn
CX	3655					Withdrawn
CX	3656					Withdrawn
CX	3657					Withdrawn
CX	3658					Withdrawn
CX	3659					Withdrawn
CX	3660					Withdrawn
CX	3661					Withdrawn
CX	3662					Withdrawn
CX	3663					Withdrawn
CX	3664					Withdrawn
CX	3665					Withdrawn
CX	3667					Withdrawn
CX	3668					Withdrawn
CX	3669	C	Supplemental Witness Statement of Dr. Jianmin Qu	Qu/Sitaraman	INFRNG/NON-INFRNG	Admitted
CX	3670	C	Respondent STMicroelectronics N.V.'s Fourth Amended and Supplemental Response to Tessera's Second Set of Requests for Admission (served 07.11.08)	Malone	INFRNG/NON-INFRNG	Admitted
CX	3671		Rule 132 Declaration of Scot A. Griffin from In re Reexamination of US Patent No. 5,679,977	Ivey	Vldy/Invldy	Admitted
CX	3672		Response to Official Action regarding Reexamination of '977 patent	Ivey	Vldy/Invldy	Admitted
CX	3673		Amendment in Response to Official Office Action mailed 03.282008 in the Reexamination of '977 patent	Ivey	Vldy/Invldy	Admitted
CX	3674		Rule 132 Declaration of Scot A. Griffin from In re Reexamination of US Patent No. 5,852,326	Ivey	Vldy/Invldy	Admitted
CX	3675		Declaration of Dr. Ephraim Suhir in the Reexamination of '326 patent	Ivey	Vldy/Invldy	Admitted
CX	3676		Principal Declaration of Glenn Urbish in Reexamination of the '419 patent	Ivey	Vldy/Invldy	Admitted
CX	3677		Tessera Technologies, Inc. Form 10-K	Mitchell	Domestic Industry	Admitted

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS

August 4, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
JPX	1	C	Bottoms-Up database (Note: This is the physical exhibit version of JX-0075C)	Mitchell	Domestic Industry	Admitted
JPX	2	C	ST NV Chip package XTV0984N (Physical Sample)	Hundt, Qu, Tessera Corporate Designee	Remedy	Admitted
JX	1		U.S. Patent No. 5,852,326 (Copy of Certfied Copy) - Exhibit #1 to Complaint	Mitchell, Griffin Pickett, Qu, McWilliams, and/or various others	Infrng/Non-infrng	Admitted
JX	2		U.S. Patent No. 6,433,419 (Copy of Certified Copy) - Exhibit #2 to Complaint	Mitchell, Griffin Pickett, Qu, McWilliams, and/or various others	Infrng/Non-infrng	Admitted
JX	3		File History for U.S. Patent No. 5,852,326	Mitchell, Griffin Pickett, Qu, McWilliams, and/or various others	Infrng/Non-infrng	Admitted
JX	4		File History for U.S. Patent No. 6,433,419	Mitchell, Griffin Pickett, Qu, McWilliams, and/or various others	Infrng/Non-infrng	Admitted
JX	5	C	Confidential License Agreement with 3M	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	6	C	Confidential License Agreement with Advanced Semiconductor Engineering, Inc. (ASE)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	7	C	Confidential License Agreement with Akita Elpida Memory, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	8	C	Confidential License Agreement with AMD	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	9	C	Confidential License Agreement with Amkor Technology, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	10	C	Confidential License Agreement with Asahi Kasei Microsystems Co., Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	11	C	Confidential License Agreement with ChipMOS Technologies, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	12	C	Confidential License Agreement with ChipPAC, Ltc. (BV1)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	13	C	Confidential License Agreement with Cochlear Co.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	14	C	Confidential License Agreement with Compeq Manufacturing Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	15	C	Confidential License Agreement with Crane Aerospace, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
JX	16	C	Confidential License Agreement with DPAC Technologies Corp.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	17	C	Confidential License Agreement with EEMS Italia, SpA	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	18	C	Confidential License Agreement with Flexera	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	19	C	Confidential License Agreement with Flextech Holdings, Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	20	C	Confidential License Agreement with Fujitsu, Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	21	C	Confidential License Agreement with Hitachi Cable, Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	22	C	Confidential License Agreement with Hitachi, Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	23	C	Confidential License Agreement with Hynix Semiconductor, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	24	C	Confidential License Agreement with Infineon Technologies AG	Pickett	Tessera History, Domestic Industry	Admitted
JX	25	C	Confidential License Agreement with Integrated Packaging Assembly Corp. (now 12A Technologies, Inc.)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	26	C	Confidential License Agreement with Intel Co.	Pickett	Tessera History, Domestic Industry	Admitted
JX	27	C	Confidential License Agreement with LG Micron Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	28	C	Confidential License Agreement with Matsushita Electric Industrial Co., Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	29	C	Confidential License Agreement with Micron Technology, Inc.	Pickett	Tessera History, Domestic Industry	Admitted
JX	30	C	Confidential License Agreement with Miecer Semiconductor, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	31	C	Confidential License Agreement with Mitsui High-Tec Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	32	C	Confidential License Agreement with Mitsui Mining & Smelting Co., Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	33	C	Confidential License Agreement with NEC Electronics Co.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
JX	34	C	Confidential License Agreement with North Co.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	35	C	Confidential License Agreement with North Dakota State University	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	36	C	Confidential License Agreement with NXP B.V.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	37	C	Confidential License Agreement with Oki Electric Industry Co., Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	38	C	Confidential License Agreement with Orient Semiconductor Electronics Ltd (OSE)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	39	C	Confidential License Agreement with Payton Technolog Corp.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	40	C	Confidential License Agreement with Plexus Co.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	41	C	Confidential License Agreement with Powertech Technology Inc. (PTI)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	42	C	Confidential License Agreement with Quimoda, AG	Pickett	Tessera History, Domestic Industry	Admitted
JX	43	C	Confidential License Agreement with Renesas Eastern Japan Semiconductor, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	44	C	Confidential License Agreement with Renesas Kyushu Semiconductor Corp.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	45	C	Confidential License Agreement with Renesas Northern Japan Semiconductor, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	46	C	Confidential License Agreement with Renesas Technology Co.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	47	C	Confidential License Agreement with ROHM Co., Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	48	C	Confidential License Agreement with Samsung Electro-Mechanics Co., Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	49	C	Confidential License Agreement with Samsung Electronics Co., Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	50	C	Confidential License Agreement with Samsung Techwin Co., Ltd (formerly Samsung Aerospace)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	51	C	Confidential License Agreement with Sanyo Electric Co., Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	52	C	Confidential License Agreement with Seiko Epson Co.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
JX	53	C	Confidential License Agreement with SGS Thompson	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	54	C	Confidential License Agreement with Sharp Co.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	55	C	Confidential License Agreement with Shinko Electric Industries Co., Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	56	C	Confidential License Agreement with Siemens AG	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	57	C	Confidential License Agreement with Siliconware Precision Industries Co., Ltd. (SPIL)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	58	C	Confidential License Agreement with Sony Co.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	59	C	Confidential License Agreement with Sunright Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	60	C	Confidential License Agreement with Texas Instruments, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	61	C	Confidential License Agreement with Toshiba Co.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	62	C	Confidential License Agreement with United Test and Assembly Center Ltd. (UTAC)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	63	C	Confidential License Agreement with United Test Center Inc. (UTC)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	64	C	Confidential License Agreement with University of Alaska	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	65	C	Confidential License Agreement with UTStarcom, Inc.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	66	C	Confidential License Agreement with Walton Advanced Electronics, Ltd.	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	67	C	TCC Patent License Agreement (Tessera & Seiko Espon Corp.)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	68	C	TCC Master License Agreement (Tessera & Shinko Electronic Industries, Co.)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	69	C	DiStefano Deposition Exhibit #148, Confidentail Invoices	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	70	C	DiStefano Deposition Exhibit #150, Declaration of Thomas H. Di Stephano in Support of Tessera's Opposition to TI's Summary Judgment Motion on Standing and Contract Issues and Countermotion	DiStefano	Background / Infrng/Non-infrng / Domestic Industry	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
JX	71	C	License Agreement in conjunction with settlement of pending litigation (Tessera & Texas Instruments, Inc.)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	72	C	Photos of Historical Tessera Parts	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	73	C	Settlement Agreement (Tessera & Micron Technology, Inc.)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	74	C	Settlement Agreement (Tessera & Infineon Technologies AG, et al.)	Mitchell, Pickett, and/or Flatow	Domestic Industry	Admitted
JX	75	C	Bottoms-Up database (Note: Corresponds to physical exhibit JPX-001C)	Mitchell	Domestic Industry	Admitted
JX	76	C	ATI Wire Bond Diagram for Customer Device W2240G(B12)	Qu and/or McLellan	Infrng/Non-infrng	Admitted
JX	77	C	ATI Bonding Diagram for Customer Device No. W2240G(B11)	Qu and/or McLellan	Infrng/Non-infrng	Admitted
JX	78	C	AT Bonding Diagram for Customer Device W2240A	Qu and/or McLellan	Infrng/Non-infrng	Admitted
JX	79	C	Bond Diagram for Customer Device Name W2240A	Qu and/or McLellan	Infrng/Non-infrng	Admitted
JX	80	C	STATSChipPAC Wire Bond Diagram for Customer Device W2240A	Qu and/or McLellan	Infrng/Non-infrng	Admitted
JX	81	C	Bonding Diagram for Customer Device W2240A	Qu and/or McLellan	Infrng/Non-infrng	Admitted
JX	82	C	Bond Diagram for Customer Device Name W2240A	Qu and/or McLellan	Infrng/Non-infrng	Admitted
JX	83	C	Mawer Deposition Exhibit #022, Freescale Bill of Materials	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	84	C	Chopin Deposition Exhibit #003, Freescale Bill of Materials	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	85	C	Mawer Deposition Exhibit #024, Freescale Bill of Materials	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	86	C	84ARS10504D001	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
JX	87	C	84ASA10578D001	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	88					Withdrawn
JX	89					Withdrawn
JX	90	C	84ASA10579D003	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	91					Withdrawn
JX	92	C	84ASA10683D001	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	93	C	67ARE10702D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	94	C	67ARE10744D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	95	C	67ARE11008D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	96	C	67ARE11080D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	97	C	67ASA11298D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
JX	98	C	67ARE11534D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	99	C	84ARE11574D001	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	100	C	84ARE11593D002	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	101	C	84ARE11725D001	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	102	C	Darveaux_and_Mawer_-_Thermal_and_Power_Cycling_Limits_of_PBG.pdf	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	103	C	Mawer _Darveaux_and_Petrucci_-_Calculation_of_Thermal_Cyclin.pdf	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	104	C	98ARE10502D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	105	C	98ARE10525D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	106	C	98ASA10510D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
JX	107	C	98ARE10527D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	108	C	98ASA10598D	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	109	C	Mawer Deposition Exhibit #007, Meeting Notification e-mail for the meeting to Review TEPBGA/-II model and experimental results presentation	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	110	C	Chopin Deposition Exhibit #009, E-mail from R. Matthew to I. Ruzaini et al regarding Low K TEPBGA/-II development TSO	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	111	C	1997 CDF-AEC Rel Symp Foils	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	112	C	1997 IRPS Foils, Part I.ppt	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	113	C	1997 IRPS Foils, Part II.ppt	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	114	C	1999 CTEA Foils.pdf	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	115	C	225 & 361 PBGA Build Rprt.doc	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted

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JX	116	C	BGA Trend Paper-A. Mawer.doc	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	117					Withdrawn
JX	118					Withdrawn
JX	119					Withdrawn
JX	120	C	Darveauz and Mawer - Thermal and Power Cycling Limits of PBGA Assem.pdf	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	121	C	SUNY-Binghamton Foils-6-98	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	122	C	McShane Deposition Exhibit #003, Freescale presentation titled, "Introduction to the Plastic Ball Grid Array (PBGA)	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	123	C	46 uBGA Brd_Lvl Cycling-6-98.ppt	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	124	C	Montgomery Deposition Exhibit #013, Freescale list regarding Invoices	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	125	C	McShane Deposition Exhibit #012, Motorola Presentation titled,"Tessera-Style µBGA Board Level Thermal Cycling Data"	Qu, Chopin, Mawer, Leoni, Kellar, McShane, Montgomery, O'Leary and/or Roossien	Infrng/Non-infrng	Admitted
JX	126					Withdrawn

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JX	127	C	Balog Deposition Exhibit #016, Mobile Devices List, , Jan - Nov 2007, All Products	Qu, Bradley, Gallagher, Banjeri, Beradoni, Gilmore, Karpinia, Reiff, Zollo, Luciano, Richards, Yang, Shurboff, Hyink, Hoffman, Johnson, Balog, Alberth, Olis, Bockol, Collins, Lehrer, Mullen, Brda, Brown, Greb, and/or Hertz	Infrng/Non-infrng	Admitted
JX	128	C	Holmes Deposition Exhibit #007, Qualcomm 409 CSP Package Specification 80-V2970-1 Revision F	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	129	C	Qualcomm Package Outline Drawing, Drawing NO. NT90-VA911-2	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	130	C	Gregorich Deposition Exhibit #004, Peet Test: A Novel Method for Evaluating Pb-Free CSP Solder Joint Reliability	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	131	C	Preecha Deposition Exhibit #004, Qualcomm Document Titled,"Engineering Marking Diagram, QSC6030, 351MSP	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted

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JX	132	C	Holmes Deposition Exhibit #016-B, Qualcomm Process Flow Chart Specification for 2-DIE Stacked CSP, MH80-VB600-C1 Rev. B	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	133	C	Holmes Deposition Exhibit #016-C, Qualcomm Process Flow Chart, Specification for 2-DIE Stacked CSP, MH80-VB600-E1 Rev. B	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	134	C	Preecha Deposition Exhibit #003, Qualcomm Report titled,"IC Package Environmental Roadmap"	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	135	C	Holmes Deposition Exhibit #016-D, Qualcomm Process Flow Chart Specification for Single DIE DSP/BGA	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	136	C	Holmes Deposition Exhibit #016-E, Qualcomm Process Flow Chart Specification for 3-DIE Side by Side CSP	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted

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JX	137	C	Holmes Deposition Exhibit #016-F, Qualcomm Process Flow Chart Specification for Single Die CSP/BGA	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	138	C	Holmes Deposition Exhibit #016-A, Qualcomm Process Flow Chart Specification for Single DIE DSP/BGA, MH80-VB600-H2 Rev. B	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	139	C	Holmes Deposition Exhibit #016-G, Qualcomm Process Flow Chart Specification for 3-DIE Side by Side CSP	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	140	C	Holmes Deposition Exhibit #016-H, Qualcomm Process Flow Chart Specification for Wire-Bond Stacked Module Package CSP	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	141	C	Gregorich Deposition Exhibit #016, Email from T. Gregorich to M. Velez et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted

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JX	142	C	Gregorich Deposition Exhibit #017, Email from T. Gregorich to E. Egan et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	143	C	Gregorich Deposition Exhibit #005, Email from R. Horvath to Tom Gregorich	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	144	C	Holmes II Deposition Exhibit #013, Email chain beginning 1/16/2003	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	145	C	Gregorich Deposition Exhibit #11, Email from R. Rice to P. Holmes	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	146	C	Gregorich Deposition Exhibit #21, Email from T. Gregorich to M. Velez et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted

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JX	147	C	Holmes II Deposition Exhibit #014, Email chain beginning 8/4/2006 (MSM6550-409CSP)	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	148	C	Preecha Deposition Exhibit #007, 2002 APEX Exhibition Conference Report	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	149	C	Gregorich Deposition Exhibit #008, Email from M. Savoy to E. Reyes et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	150	C	Gregorich Deposition Exhibit #14, Email from R. Palys to N. Anamosa	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	151	C	Gregorich Deposition Exhibit #007, Email from E. Reyes to Tom Gregorich	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted

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JX	152	C	Veatch Deposition Exhibit #013, Finite Element Analysis	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	153	C	Gregorich Deposition Exhibit #20, Email from T. Gregorich to M. Velez et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	154	C	Gregorich Deposition Exhibit #009, Email from T. Gregorich to P. Moise et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	155	C	BGA/CSP Package User Guide, July 26, 2002	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	156	C	BGA/CSP Package User Guide	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted

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JX	157	C	Gregorich Deposition Exhibit #24, Email from T. Gregorich to J. Gabriel et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	158	C	Gregorich Deposition Exhibit #10, Email from T. Gregorich R. Horvath et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	159	C	Gregorich Deposition Exhibit #22, "Impact of Ball Via Configurations on Solder Joint Reliability in Tape Based Chip-Scale Packages"	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	160	C	Holmes II Deposition Exhibit #016, Email from Sarah Weldon	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	161	C	Gregorich Deposition Exhibit #15, Email from T. Gregorich to J. Clifford et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted

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JX	162	C	Gregorich Deposition Exhibit #006, Email from R. Lane to L. Zhao et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	163	C	Gregorich Deposition Exhibit #26, 320 Chip-Scale-Package (CSP)	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	164	C	Gregorich Deposition Exhibit #25, 320 CSP Mechanical Modeling	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	165	C	Holmes II Deposition Exhibit #017, Email from Rick Horvath	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	166	C	Gregorich Deposition Exhibit #19, Email from T. Gregorich to M. Velez et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted

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JX	167	C	Gregorich Deposition Exhibit #27, Email from M. Veatch to S. Weldon et al.	Qu, Burrell, Chun, Dang, Friedman, Gerfin, Gregorich, Holmes, Lane, Hodoyan, Marburger, Preecha, Reyes, Selby-Thomas, Veatch, Velez, and/or Witten	Infrng/Non-infrng	Admitted
JX	168	C	Foong Deposition Exhibit #003, Document entitled "Concode for FBGA & MCP Package Family (Per F09-000)	Qu, Suresh, Russell, Foong, and/or Pitruzella	Infrng/Non-infrng	Admitted
JX	169	C	Spansion Binding Diagram for Device 98M73A	Qu, Suresh, Russell, Foong, and/or Pitruzella	Infrng/Non-infrng	Admitted
JX	170	C	Technical Drawings re LAA080	Qu, Suresh, Russell, Foong, and/or Pitruzella	Infrng/Non-infrng	Admitted
JX	171	C	Technical Drawings re VDE044, Package 28158	Qu, Suresh, Russell, Foong, and/or Pitruzella	Infrng/Non-infrng	Admitted
JX	172	C	Spansion Billings Reports through Q4 2006	Russell	Importation / Remedies	Admitted
JX	173	C	Spansion Billings Reports through 2006	Russell	Importation / Remedies	Admitted
JX	174	C	Malone Deposition - December 12, 2007 - Exhibit 16 - Product List	Malone	Infrng/Non-infrng / Remedy	Admitted
JX	175	C	Built Sheet Assembly for M36W0R7040U0ZC5U	Malone	Infrng/Non-infrng, Remedy	Admitted
JX	176	C	Package Outline Assembly for TO24C78T$GZ3/LFA	Qu	Infrng/Non-infrng	Admitted
JX	177	C	Substrate Technical Specs. for TO24C78T$GZ3/LFA	Qu	Infrng/Non-infrng	Admitted
JX	178	C	How to Solder a BGA On a Printed Circuit Board	Qu	Infrng/Non-infrng	Admitted
JX	179	C	Substrate Technical Specs. for M36W0R7040U0ZC5U	Qu	Infrng/Non-infrng	Admitted
JX	180	C	Substrate Technical Specs. for XCOZ*W4QN5KO (XCOZW4QN5KOT706U)	Qu	Infrng/Non-infrng	Admitted
JX	181	C	Substrate Technical Specs. for H5FN*MV86BAA (MV86BFNT$PB3/LFA)	Qu	Infrng/Non-infrng	Admitted
JX	182	C	Substrate Technical Specs. for M5R8*TU04DGP (TU04DR8T$GB/LFA)	Qu	Infrng/Non-infrng	Admitted
JX	183	C	Substrate Technical Specs. for XCAIP5JF5KOB706F	Qu	Infrng/Non-infrng	Admitted
JX	184	C	Substrate Technical Specs. for A5HX*TO21AGP (TO21AHXT$GB1/LFA)	Qu	Infrng/Non-infrng	Admitted
JX	185	C	Package Outline Assembly for XCAIP5JF5KOB706F	Qu	Infrng/Non-infrng	Admitted

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JX	186	C	Package Outline Assembly for XCOZ*W4QN5KO (XCOZW4QN5KOT706U)	Qu	Infrng/Non-infrng	Admitted
JX	187	C	Package Outline Assembly for M36W0R7040U0ZC5U	Qu	Infrng/Non-infrng	Admitted
JX	188	C	Mount & Bond Diagram for M36W0R7040U0ZC5U	Qu	Infrng/Non-infrng	Admitted
JX	189	C	Company Presentation, January 24, 2007	Qu	Infrng/Non-infrng, Remedy	Admitted
JX	190	C	Malone Deposition - Exhibit 2 - Document Entitled, "Company Presentation - January 24, 2007"	Malone	Infrng/Non-infrng, Remedy	Admitted
JX	191	C	Malone Deposition - Exhibit 15 - Document Entitled, "Subcontractors Quotations for 2000 Q1 - Rev. A"	Malone	Infrng/Non-infrng, Remedy	Admitted
JX	192	C	Built Sheet Assembly for XCAIP5JF5KOB706F	Hundt, Qu, Tessera Corporate Designee	Infrng/Non-infrng, Remedy	Admitted
JX	193	C	ST Microelectronics Inc. Invoices (multiple dates)	Qu	Infrng/Non-infrng	Admitted
JX	194	C	ST-Inc Invoice to Nokia	Hundt	Infrng/Non-infrng, Remedy, Vldy/Invldy	Admitted
JX	195	C	STMicroelectronics-N.V. Invoices (multiple dates)	Hundt, Qu, Tessera Corporate Designee	Remedy	Admitted
JX	196	C	ST-NV Invoice to Nokia	Hundt, Qu, Tessera Corporate Designee	Remedy	Admitted
JX	197					Withdrawn
JX	198	C	Transcript of the Rule 30(b)(6) deposition of Michael J. Hundt in the Tessera, Inc. v. Advanced Micro Devices, Inc. litigation in the United States District Court for the Northern District of California.	Hundt, Qu, Tessera Corporate Designee	Remedy	Admitted
JX	199	C	Mount & Bond Diagram for H5FN*MV86BAA (MV86BFNT$PB3/LFA)	Hundt, Qu, Tessera Corporate Designee	Remedy	Admitted
JX	200	C	Built Sheet Assembly for H5FN*MV86BAA (MV86BFNT$PB3/LFA)	Hundt		Admitted
JX	201	C	Malone Deposition - December 12, 2007 - Exhibit 11 - STMicroelectronics Americas Invoice Summary	Qu	Infrng/Non-infrng	Admitted
JX	202	C	Malone Deposition - December 12, 2007 - Exhibit 10 - STMicroelectronics Americas Invoice Summary	Qu	Infrng/Non-infrng	Admitted
JX	203					Withdrawn
JX	204					Withdrawn
JX	205	C	Hundt Deposition - March 28, 2007 - Exhibit 214 - Document entitled "Glue Die Attach in Process Control"	Hundt	Infrng/Non-infrng	Admitted
JX	206					Withdrawn

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JX	207					Withdrawn
JX	208					Withdrawn
JX	209	C	Hundt Deposition - March 28, 2007 - Exhibit 210 - Procurement Specification for a BGA Substrate	Hundt	Infrng/Non-infrng	Admitted
JX	210	C	Hundt Deposition - March 28, 2007 - Exhibit 217 - Package Outline for TFBGA *x10x1.20 88 F8x10+8 Pitch 0.8	Hundt	Infrng/Non-infrng	Admitted
JX	211	C	Hundt Deposition - March 28, 2007 - Exhibit 226 - Schematic of TFBGA Package	Hundt	Infrng/Non-infrng	Admitted
JX	212					Withdrawn
JX	213	C	Hundt Deposition - March 28, 2007 - Exhibit 209 - Package Outline - BASE TFBGA 47L 6.39X6.37-2L-DP 5.4X4.77MM Pitch 0.75MM	Hundt	Infrng/Non-infrng	Admitted
JX	214					Withdrawn
JX	215					Withdrawn
JX	216					Withdrawn
JX	217	C	Hundt Deposition - March 28, 2007 - Exhibit 234 - Document entitled "Deisgn for Package Board Level Reliability with CAE	Hundt	Infrng/Non-infrng	Admitted
JX	218	C	Hundt Deposition - March 29, 2007 - Exhibit 237 - Document Entitled "CSP at ST Microelectronics"	Hundt	Infrng/Non-infrng	Admitted
JX	219					Withdrawn
JX	220	C	Hundt Deposition - March 28, 2007 - Exhibit 216 - Build Sheet Assembly for MCOL*5M39598	Hundt	Infrng/Non-infrng	Admitted
JX	221	C	Hundt Deposition - March 28, 2007 - Exhibit 211 - Product Specification for Assembly of a Product	Hundt	Infrng/Non-infrng	Admitted
JX	222	C	Hundt Deposition - March 28, 2007 - Exhibit 212 - Bonding Diagram for KX*A5C0	Hundt	Infrng/Non-infrng	Admitted
JX	223					Withdrawn
JX	224					Withdrawn
JX	225					Withdrawn
JX	226					Withdrawn
JX	227					Withdrawn
JX	228					Withdrawn
JX	229					Withdrawn
JX	230					Withdrawn
JX	231					Withdrawn
JX	232					Withdrawn

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JX	233					Withdrawn
JX	234					Withdrawn
JX	235	C	Combined Deposition Designations for Balog			Admitted
JX	236	C	Combined Deposition Designations for Bradley			Admitted
JX	237	C	Combined Deposition Designations for Brda			Admitted
JX	238	C	Combined Deposition Designations for M. Brown			Admitted
JX	239	C	Combined Deposition Designations for Sheila Chopin			Admitted
JX	240					Withdrawn
JX	241					Withdrawn
JX	242	C	Combined Deposition Designations for Frankel			Admitted
JX	243	C	Combined Deposition Designations for Gerfin			Admitted
JX	244	C	Combined Deposition Designations for Greb			Admitted
JX	245	C	Combined Deposition Designations for Thomas Gregorich			Admitted
JX	246					Withdrawn
JX	247					Withdrawn
JX	248	C	Combined Deposition Designations for Holmes			Admitted
JX	249	C	Combined Deposition Designations for Michael Hundt			Admitted
JX	250					Withdrawn
JX	251					Withdrawn
JX	252	C	Combined Deposition Designations for Kellar			Admitted
JX	253					Withdrawn
JX	254	C	Combined Deposition Designations for Leoni			Admitted
JX	255	C	Combined Deposition Designations for Malone			Admitted
JX	256	C	Combined Deposition Designations for Mawer			Admitted
JX	257	C	Combined Deposition Designations for McLellan			Admitted
JX	258	C	Combined Deposition Designations for McShane			Admitted
JX	259	C	Combined Deposition Designations for Montgomery			Admitted
JX	260					Withdrawn
JX	261	C	Combined Deposition Designations for Murray			Admitted
JX	262	C	Combined Deposition Designations for O'Leary			Admitted
JX	263					Withdrawn
JX	264	C	Combined Deposition Designations for Romankiw			Admitted
JX	265	C	Combined Deposition Designations for Roossien			Admitted
JX	266	C	Combined Deposition Designations for Russell			Admitted
JX	267	C	Combined Deposition Designations for Shah			Admitted
JX	268	C	Combined Deposition Designations for Suresh			Admitted
JX	269					Withdrawn

COMPLAINANT, TESSERA, INC.'S FINAL LIST OF COMPLAINANT AND JOINT EXHIBITS

August 4, 2008

Prefix:	Exhibit Number:	Conf or Pub:	Description:	Sponsoring Witness:	Stmt of Purpose:	Receipt Into Evidence:
JX	270	C	Combined Deposition Designations for Veatch			Admitted
JX	271	C	Combined Deposition Designations for Witten			Admitted
JX	272					Withdrawn
JX	273					Withdrawn
JX	274					Withdrawn
JX	275					Withdrawn
JX	276	C	Combined Deposition Designations for Khandros			Admitted
JX	277	C	Combined Deposition Designations for Kim			Admitted
JX	278	C	Combined Deposition Designations for Craig Mitchell			Admitted
JX	279	C	Combined Deposition Designations for Pickett			Admitted
JX	280	C	Combined Deposition Designations for Shimada			Admitted
JX	281					Withdrawn
JX	282	C	Combined Deposition Designations for Licciardello			Admitted
JX	283	C	Combined Deposition Designations for Perillat			Admitted
JX	284					Withdrawn
JX	285	C	Combined Deposition Designations for Chambers			Admitted

Certain Semiconductor Chips with Minimized Chip Package Size and Products Containing Same

Inv. No. 337-TA-605

CERTIFICATE OF SERVICE

I, Heather Scholz, hereby certify that on August 4, 2008, copies of the **COMPLAINANT AND JOINT EXHIBITS – ALL EXHIBITS** was served upon the following parties as indicated:

The Honorable Marilyn R. Abbott, Secretary U.S. International Trade Commission 500 E Street, S.W., Room 112-A Washington, DC 20436	☐ Via First Class Mail ☐ Via Hand Delivery ☐ Via Overnight Courier ☐ Via Facsimile ☒ Via Electronic Submission
The Honorable Theodore R. Essex Administrative Law Judge U.S. International Trade Commission 500 E Street, S.W., Room 317-H Washington, DC 20436 **(2 Copies)**	☐ Via First Class Mail ☐ Via Hand Delivery ☒ Via Overnight Courier ☐ Via Facsimile ☐ Via Electronic mail
Gregory Moldafsky, Attorney Advisor gregory.moldafsky@usitc.gov	☒ Via Electronic mail
Kecia Reynolds, Esq. Office of Unfair Import Investigations U.S. International Trade Commission 500 E Street, S.W., Room 401-A Washington DC 20436 **(1 Copy)** kecia.reynolds@usitc.gov	☐ Via First Class Mail ☐ Via Hand Delivery ☒ Via Overnight Courier ☐ Via Facsimile ☒ Via Electronic mail
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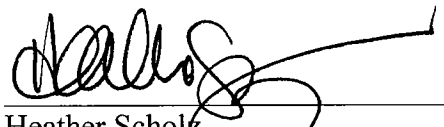

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